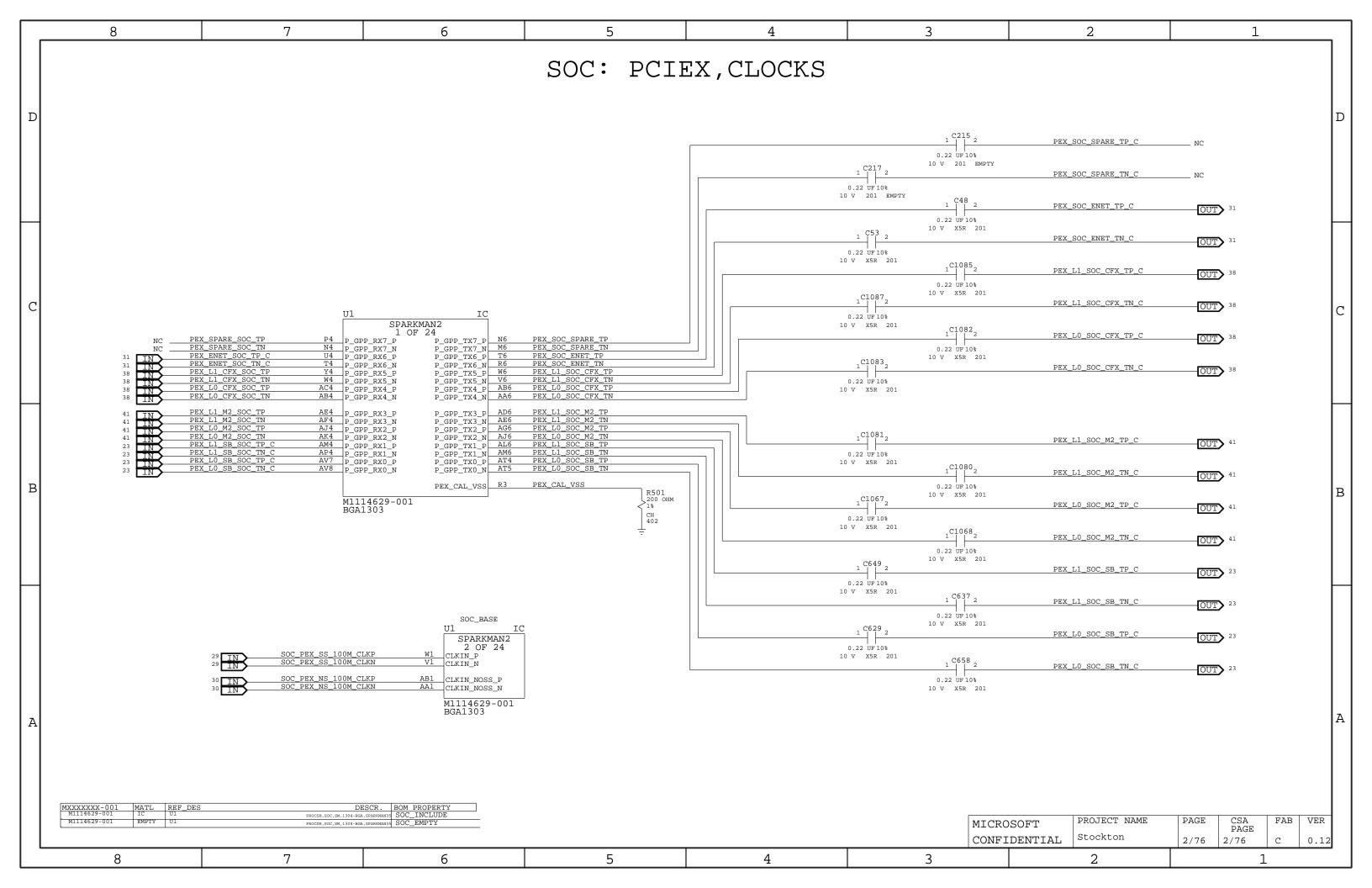
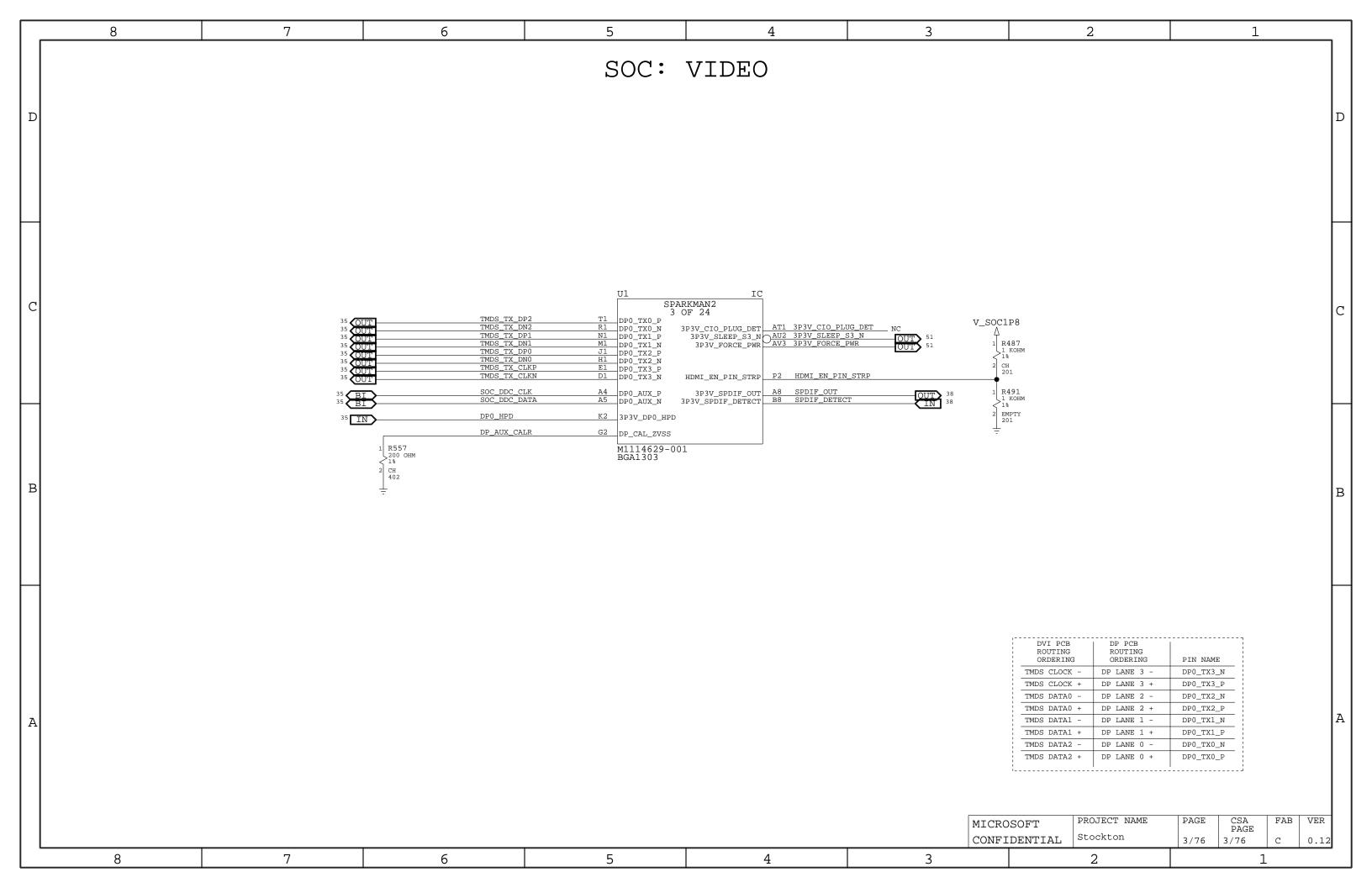
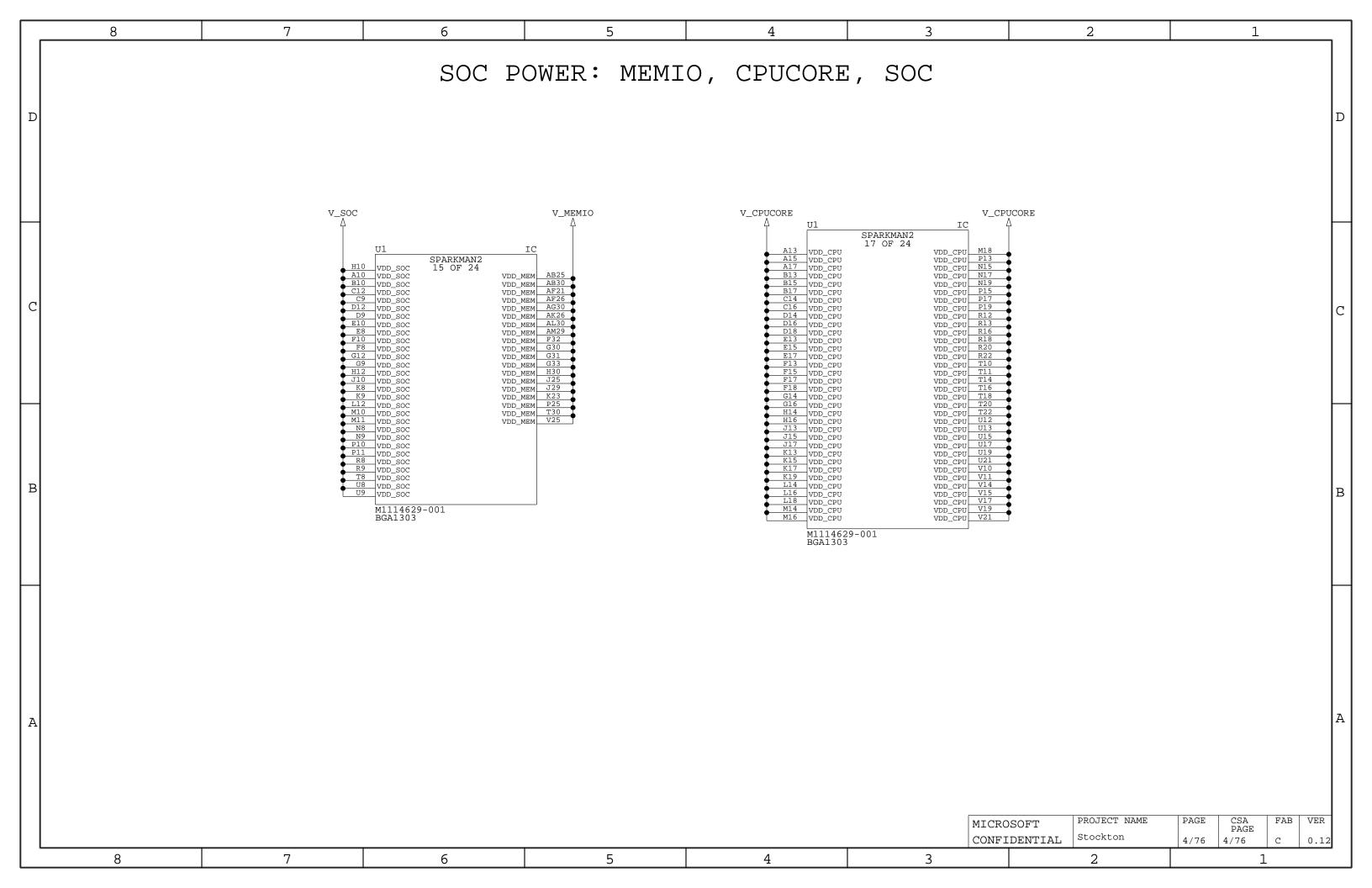
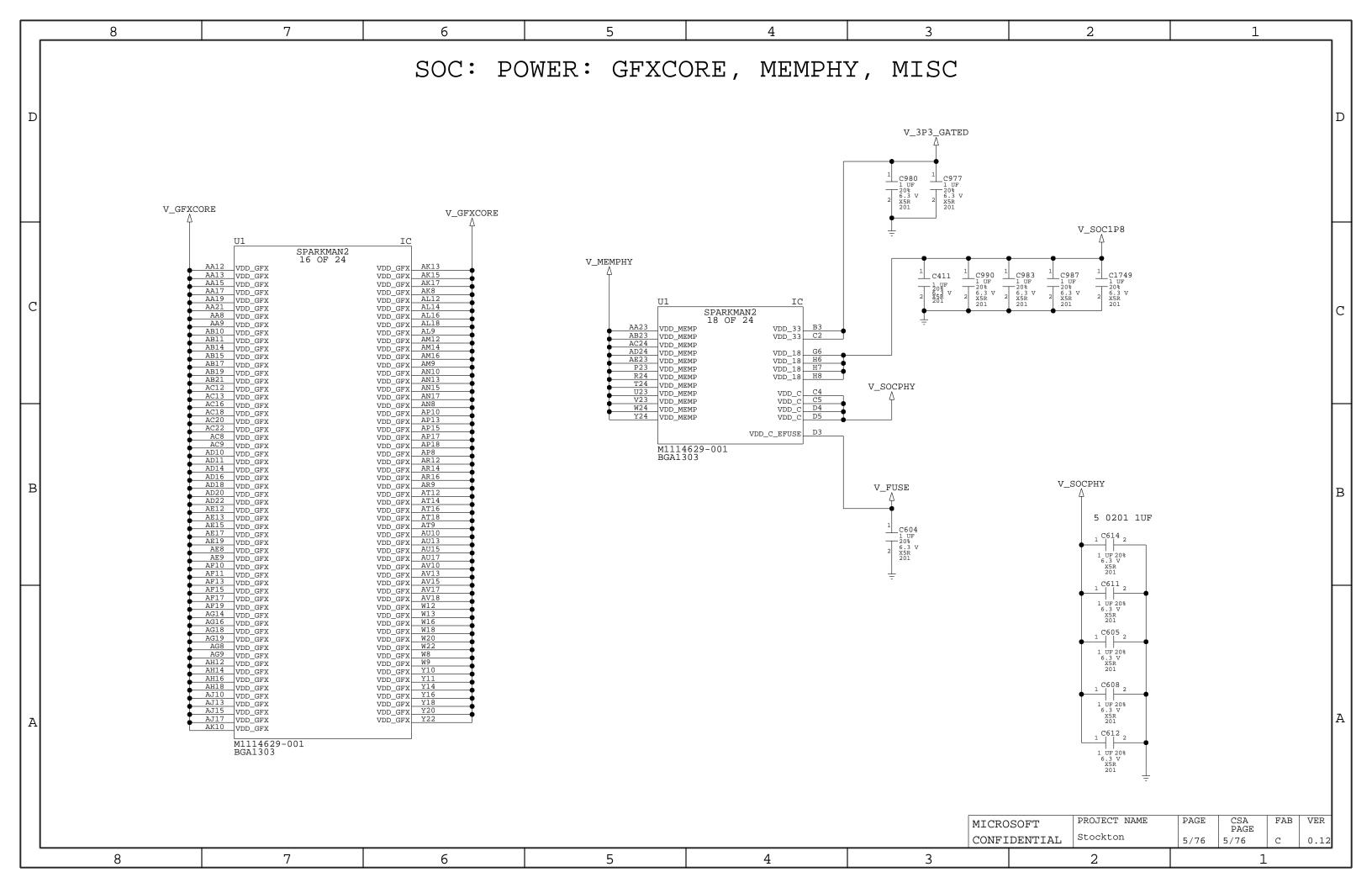
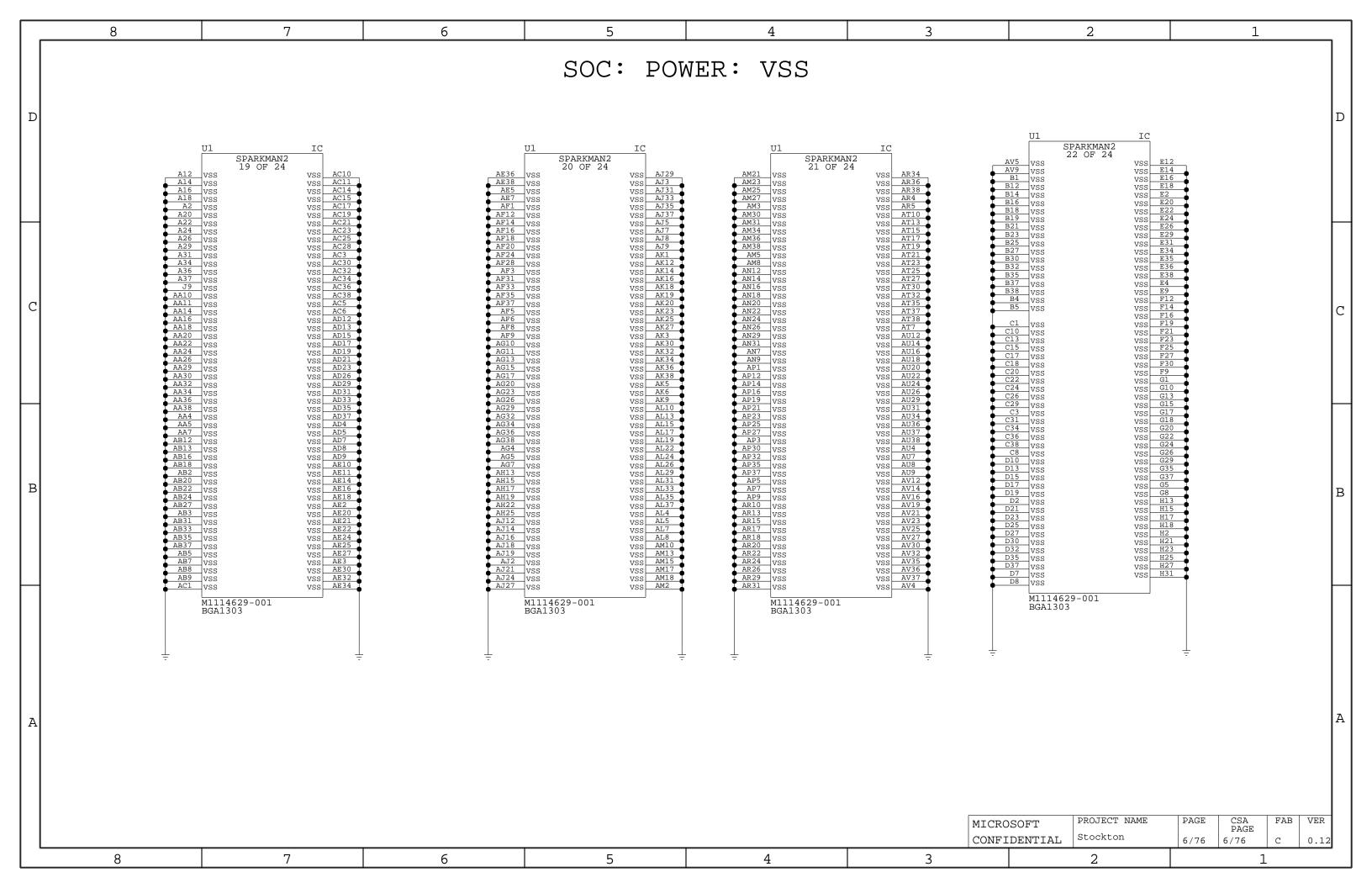
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	SHEET	SHEET NAME		SHEET	SHEET N	IAME	ST	OCKTO	N FA	B C			
	1	NONE			41	CONN: M.2							
D	2	SOC: PCIEX, CLOCKS		42	CONN: ODD				RHV	0.13	7 .	D	
	3	SOC: VIDEO		43	CONN: FRONT PANEL, FAN,	NEXUS			v	• -			
	4	SOC POWER: MEMIO, CPUCORE, SOC SOC: POWER: GFXCORE, MEMPHY, MISC SOC: POWER: VSS SOC: POWER: VSS		44	CONN: POWER								
	5			45	VREGS: V_12P0_GATED								
	6			46	VREGS: INPUT DECOUPLING								
	7			47	VREGS: V_CPUCORE, V_GFXC								
	8	SOC: DEBUG, S	B SIGNALS, V_BAT, VO	OLTAGE SENSE	48	VREGS: V_GFXCORE OUTPUT	PHASE 1 & 2						
	9	SOC: V_GFXCORE DECOUPLING SOC: V_SOC DECOUPLING		49	VREGS: V_GFXCORE OUTPUT	PHASE 3 & 4							
	10			50	VREGS: V_CPUCORE OUTPUT								
	11	SOC: V_MEMIO/	V_MEMPHY DECOUPLING		51	VREGS: V_MEMIO, V_MEMPHY	, V_SOC CONTROLLER						
	12	SOC: V_CPUCORE DECOUPLING SOC & Memory: CHA/PHY0		52	VREGS: V_MEMIO, V_MEMPHY	, V_SOC SENSE							
	13			53	VREGS: V_MEMIO AND V_MEM	PHY OUTPUT							
	14	MEMORY: PWR/VSS & DECAP, A		54	VREGS: V_SOC OUTPUT								
	15	SOC & Memory: CHB/PHY1		55	VREGS: V_5P0								
	16	MEMORY: PWR/VSS & DECAP, B SOC & Memory: CHC/PHY2		56	VREGS: V_SOC1P8, V_DRAM1	P8							
	17			57	VREGS: V_SOCPHY, V_FUSE								
	18	MEMORY: PWR/V	SS & DECAP, C		58	VREGS: V_SB1P8, V_SB1P1							
	19	SOC & Memory:	CHD/PHY3		59	VREGS: V_3P3STBY							
П	20	MEMORY: PWR/V	SS & DECAP, D		60	VREGS: V_3P3_GATED, V_3P	3_CFX						
	21	SB: SMC			61	VREGS: V_1P1STBY, V_1P8S	TBY						
	22	SB: USB			62	I2C							
	23	SB: PCIEX, SA	TA, VIDEO		63	DEBUG: MARGIN V_SOCPHY, V	_SOC1P8, V_DRAM1P8						
	24	SB: SMM UART,	SPI, JTAG, GPIO		64	DEBUG: MONITOR V_SOC1P8,	V_SOCPHY, V_12P0, V_DR	AM1P8					
B	25	SB: POWER (VS	SS)		65	DEBUG: MONITOR M.2. CFEX	PRESS						Ι
	26	SB: POWER			66	DEBUG: FACET HEADER							
	27	SB: DECOUPLIN	IG .		67	DEBUG: FTDI BRIDGE							
	28	SB: CLOCKS, S	TRAPPING, POR		68	DEBUG: FTDI BUFF, USB, P	WR						
	29	CLOCK: PCIE 1	.00MHZ SS		69	DEBUG: SWITCHES, LEDS							
	30	CLOCK: PCIE 1	00MHZ NS		70	DEBUG: HDT							
П	31	ETHERNET CONT			71	DEBUG: VR HEADERS, TEST	POINTS, CONNECTORS						┢
	32	SB: EMMC (LEG			72	LABELS AND MOUNTING							
	33	MEMORY: SPI F			73	BOM DEFINITIONS							
	34	MEMORY: SPI F			74	STOCKTON_NEXUS							
	35	HDMI: VIDEO C			75	B2B CONN AND LABELS	ar.						
	36	HDMI: LOAD SW			76	NEXUS LED AND POWER SWIT	СН						
	37	AUDIO: PREMIU											
	38	·	SPDIF, CFEXPRESS										
A	39	CONN: USB (FR	ONT & REAR)										Z
						9. UNNAMED NETS ARE N 10.SUFFIX N FOR ACTI	AMED WITH /2 TEXT SIZE VE LOW OR N JUNCTION					DDAMING	
	RULES: (APPLIED WHEN POSSIBLE) 1. MSB TO LSB IS TOP TO BOTTOM 2. WHEN POSSIBLE: INPUTS ON LEFT, OUTPUTS ON RIGHT 3. ORDER OF PAGES=CHIP INTERFACES, TERMINATION, POWER, DECOUPLING 4. AVOID USING OFF PAGE CONNECTORS FOR ON PAGE CONNECTIONS 5. LANED SIGNALS ARE GROUPED ON SYMBOLS 6. TRANSIMITTER NAME USED AS PREFIX WITH RX AND TX CONNECTIONS 7. SUFFIX V IS USED FOR VOLTAGE RAIL SIGNAL NAMES 8. SUFFIX _DP AND _DN ARE USED FOR DIFFERIENTAL PAIRS			ING	9. UNNAMED NETS ARE NAMED WITH /2 TEXT SIZE 10.SUFFIX _N FOR ACTIVE LOW OR N JUNCTION 12.SUFFIX _P FOR P JUNCTION 13.SUFFIX _EN FOR ENABLE 14.'CLK' FOR CLOCKS, 'RST' FOR RESETS 15.PWRGD FOR POWER GOOD 16.REV AND FAB ARE SET USING CUSTOM VARIABLES TOOLS>OPTIONS>VARIABLES			MICROSOFT CONFIDENTIAL	PROJECT NAME	Jun 25 13:3 PAGE CSA PAGE 1/76 1/76	FAB VE		
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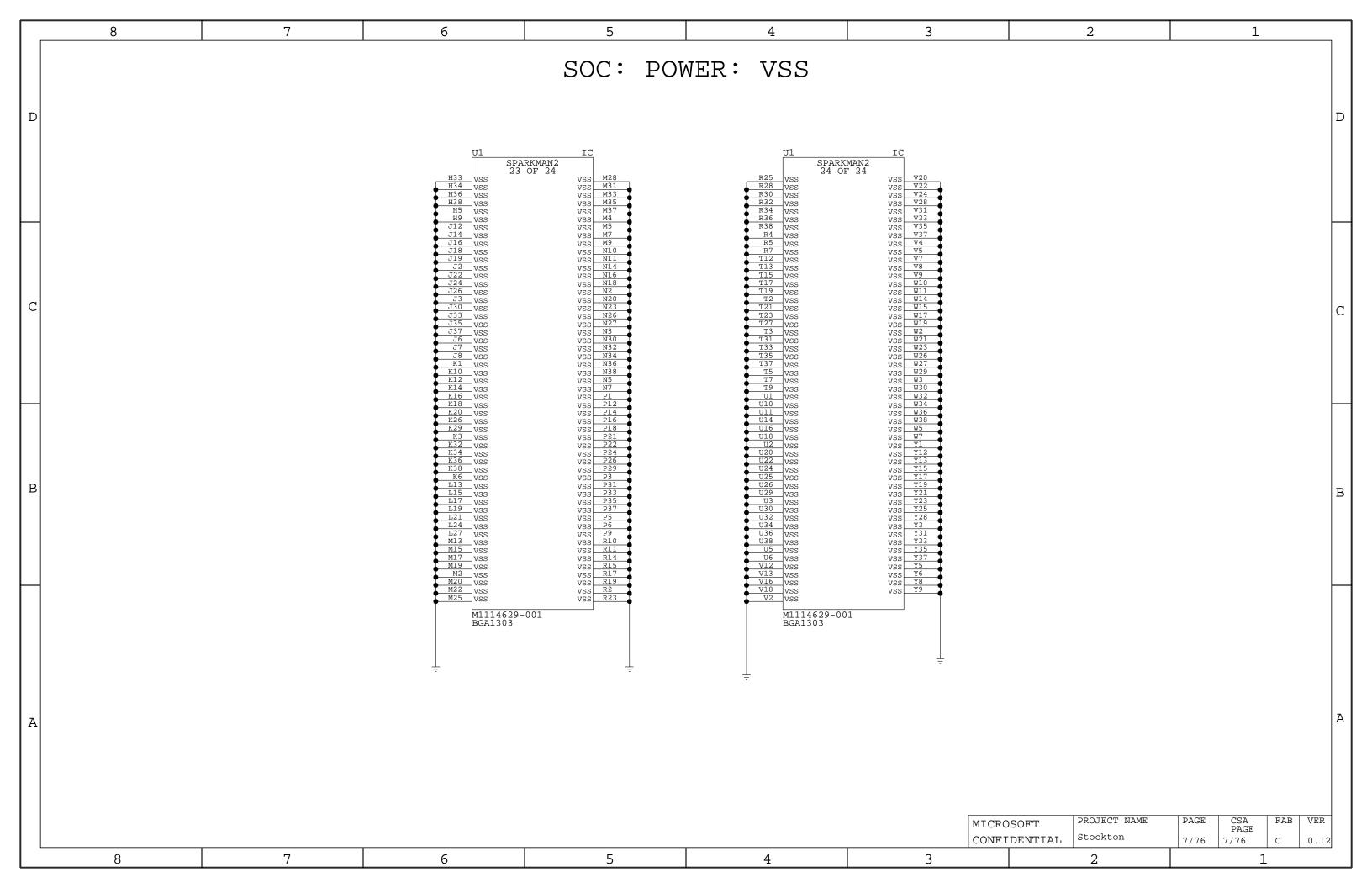


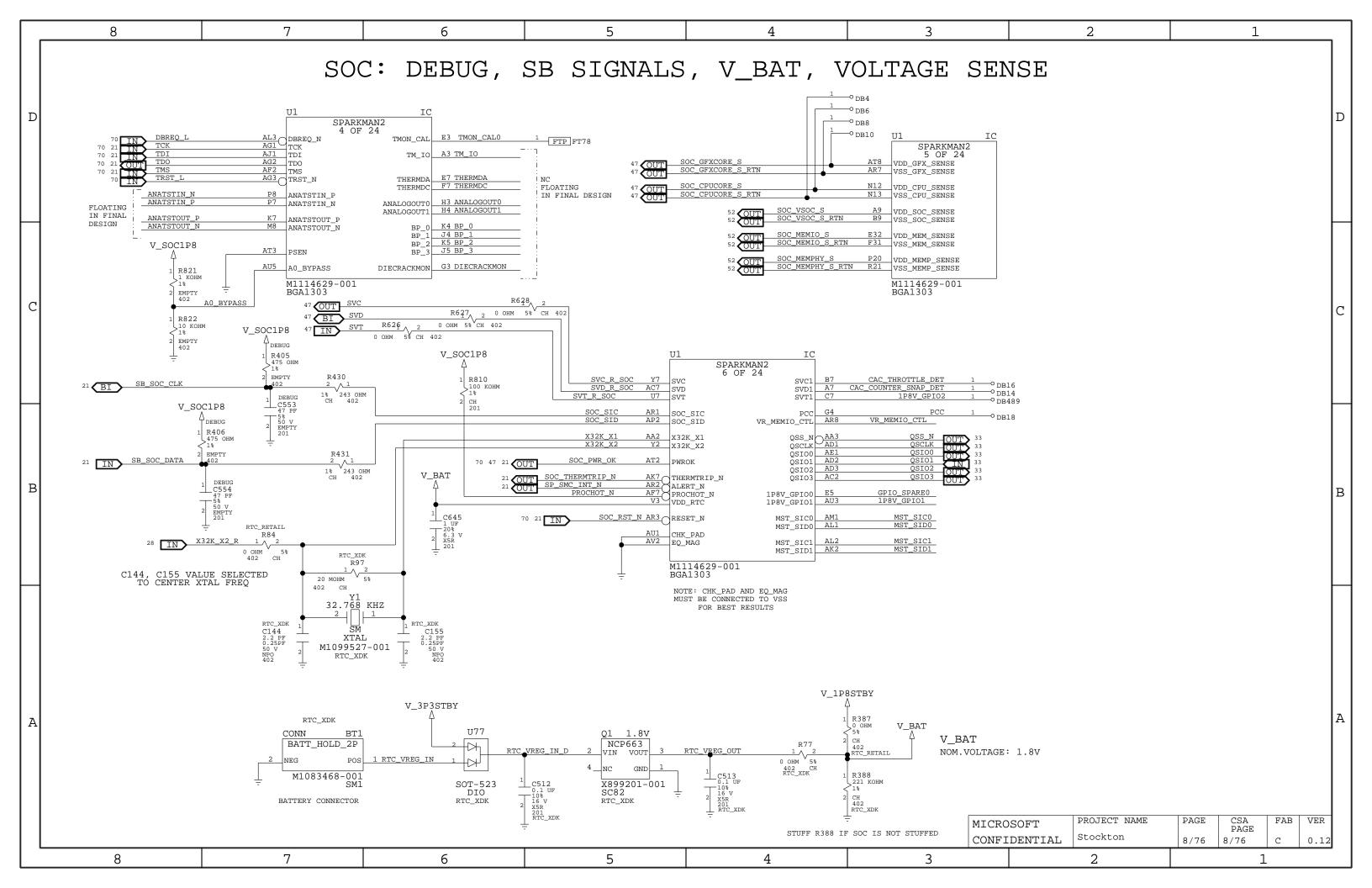


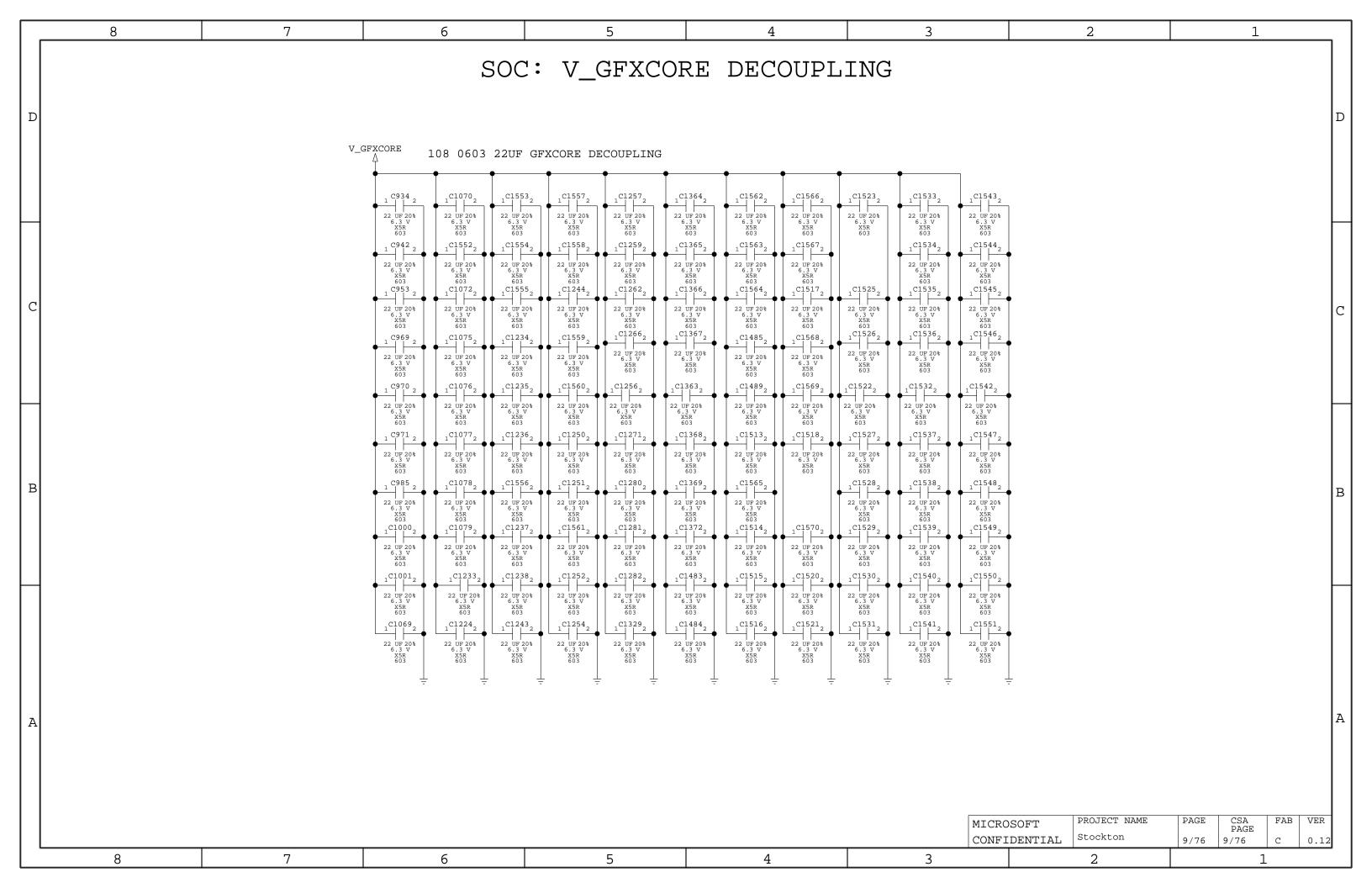


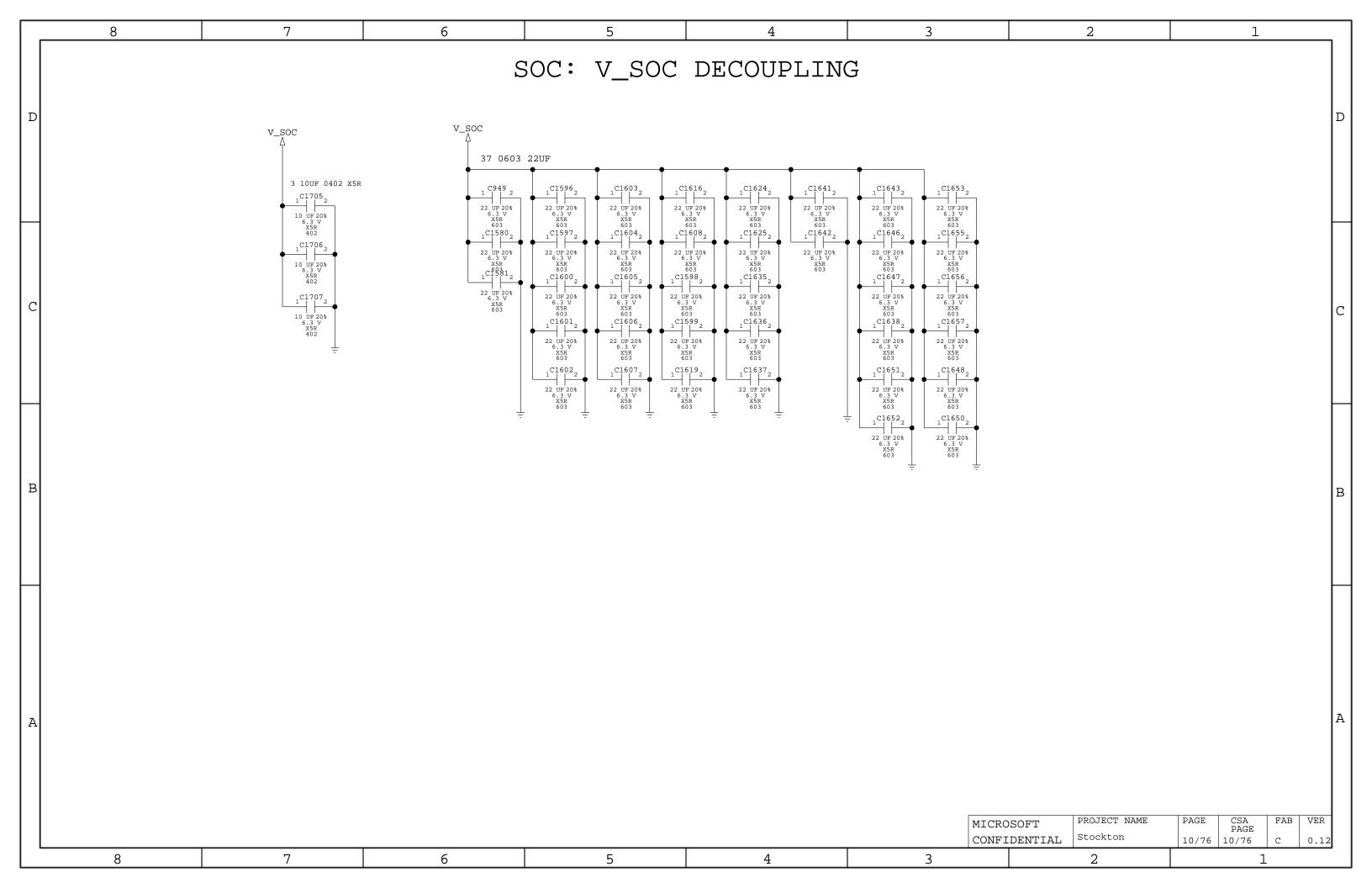


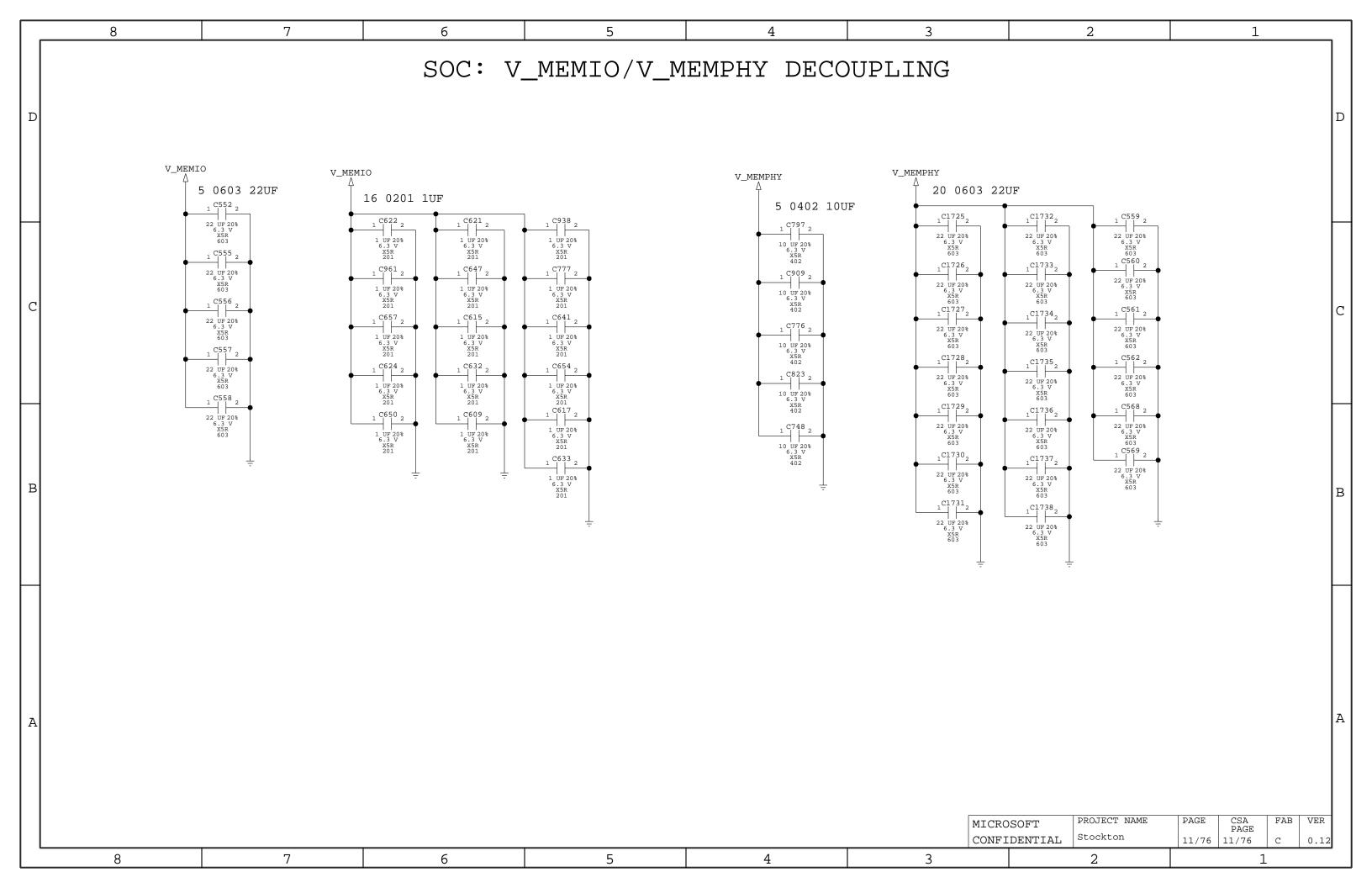


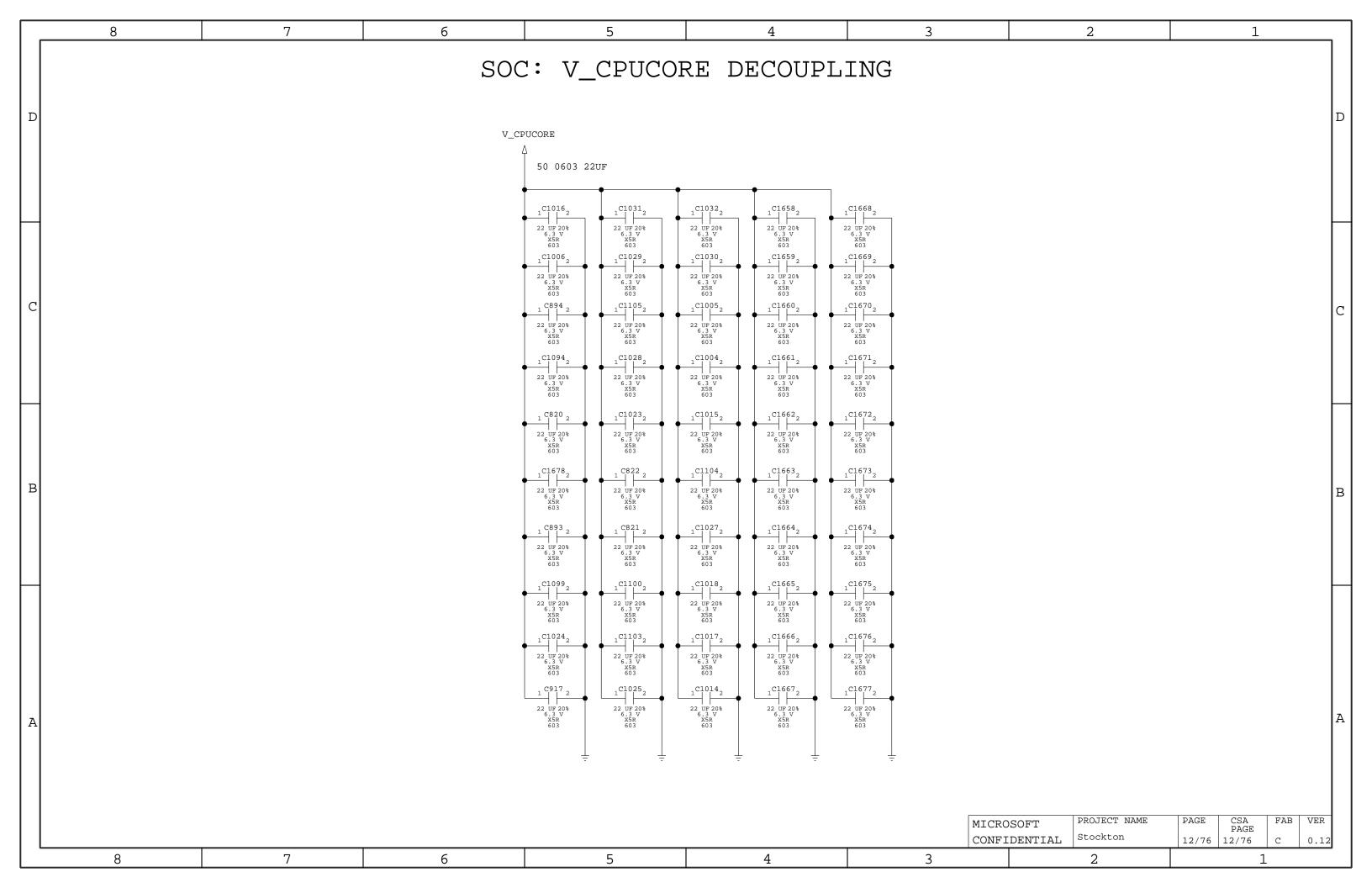


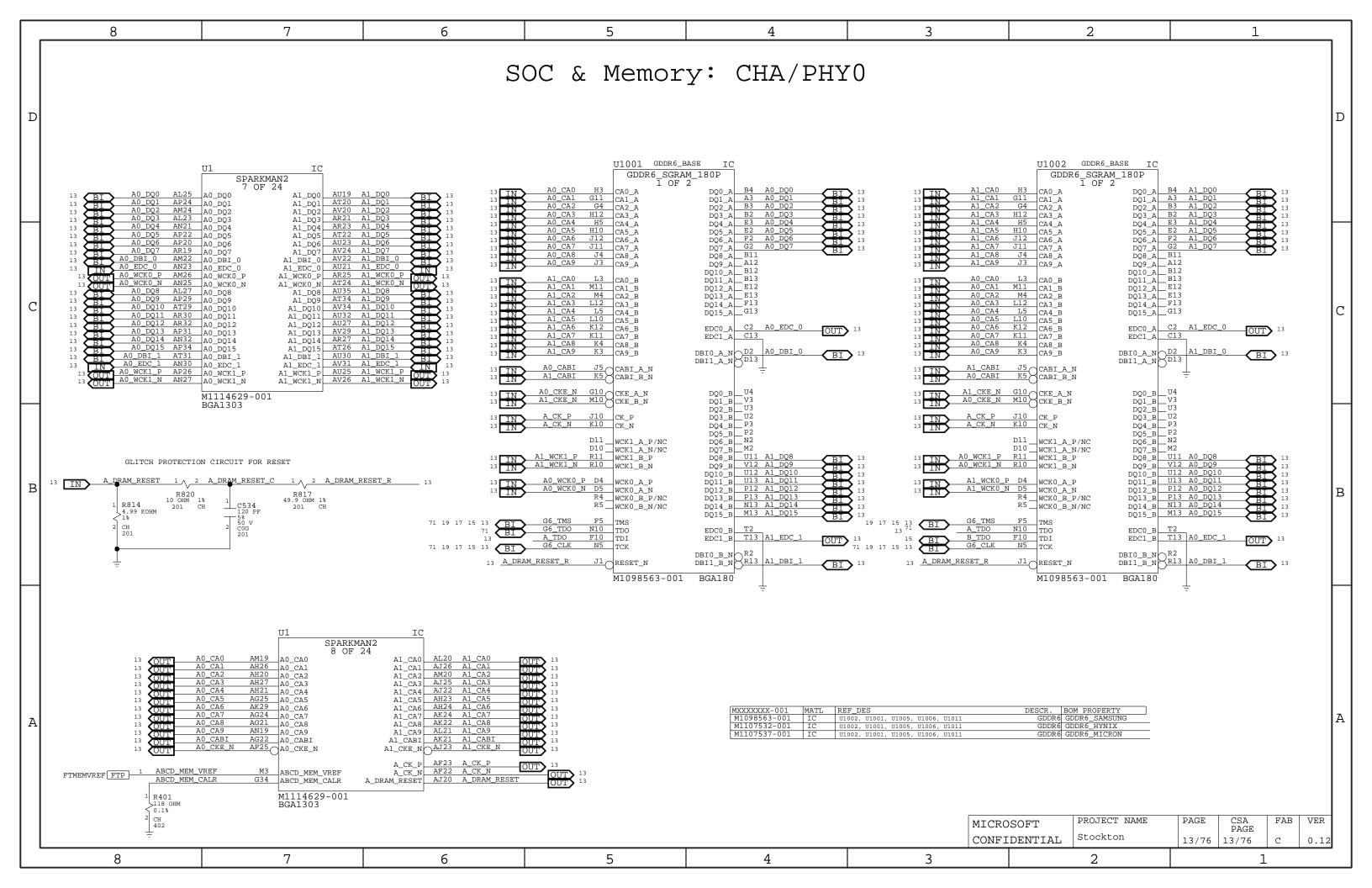


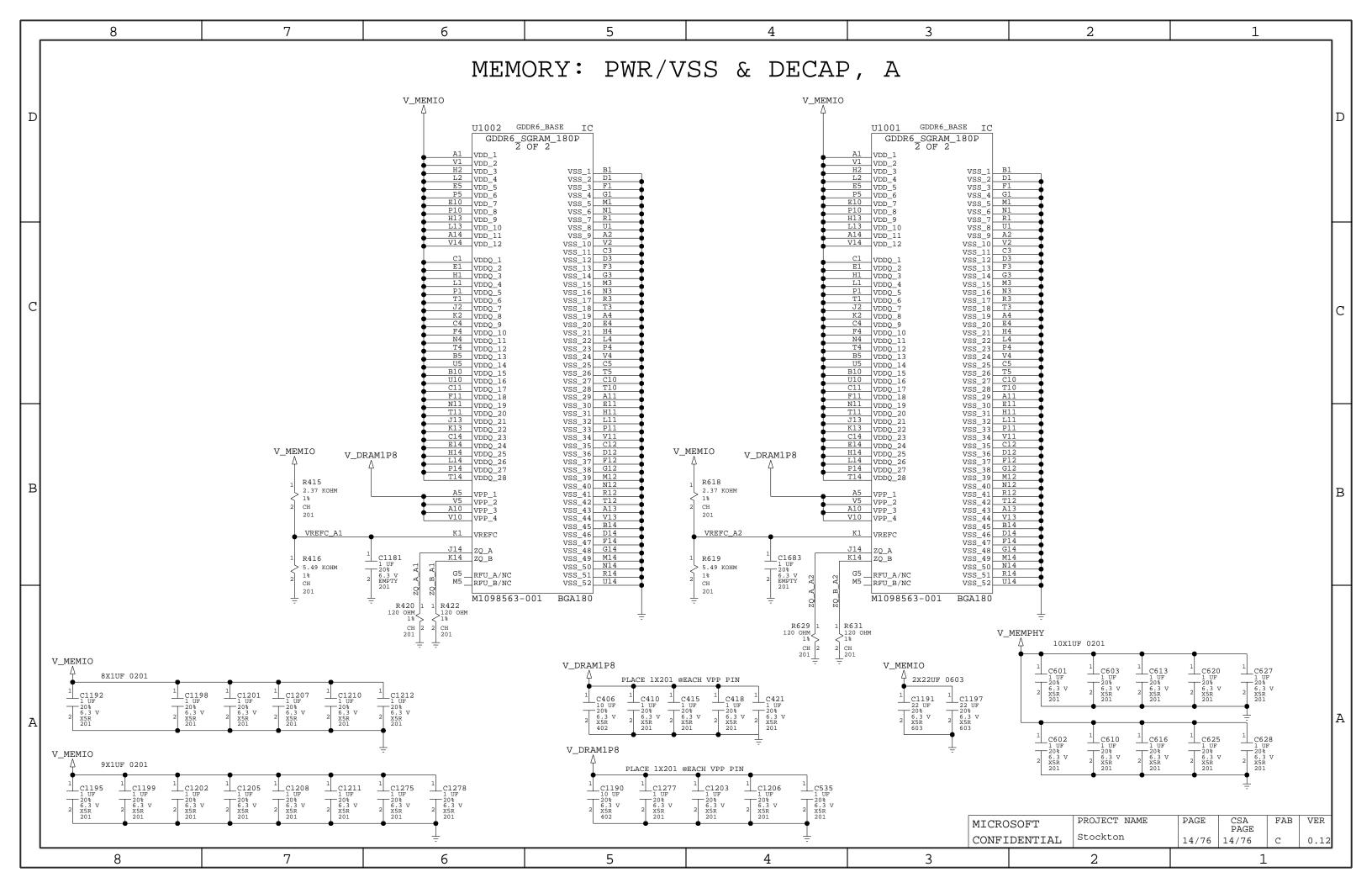


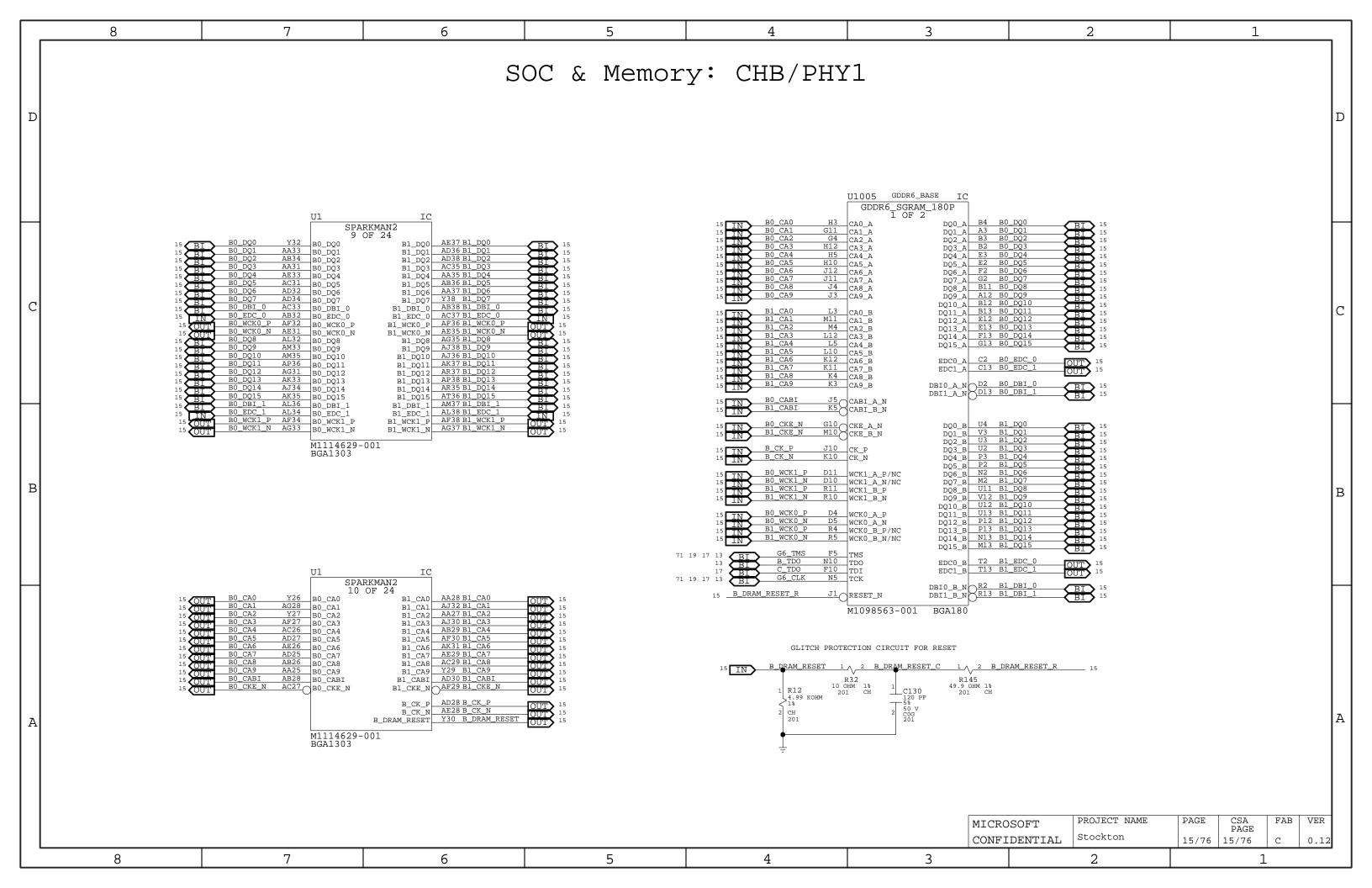


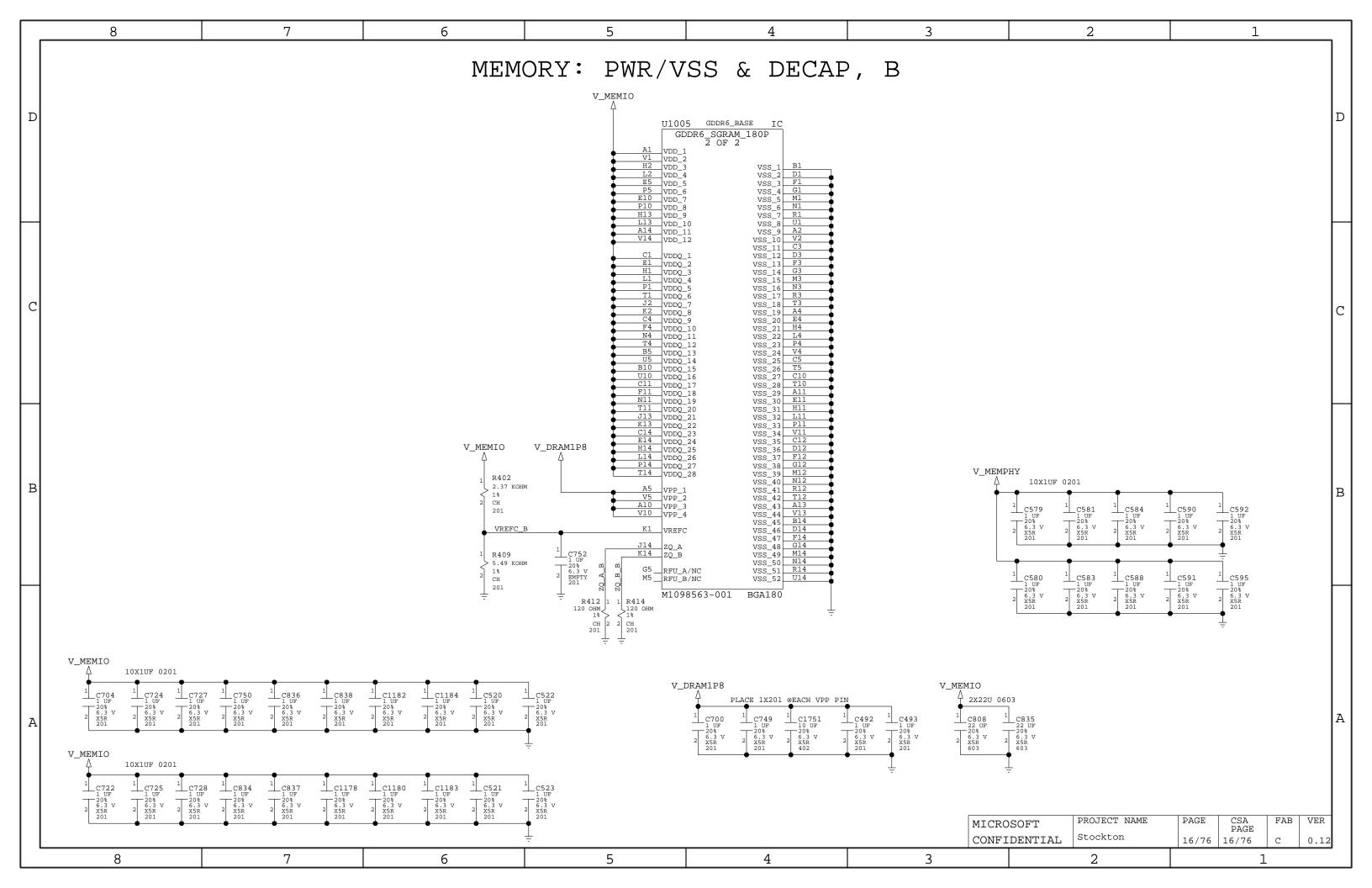


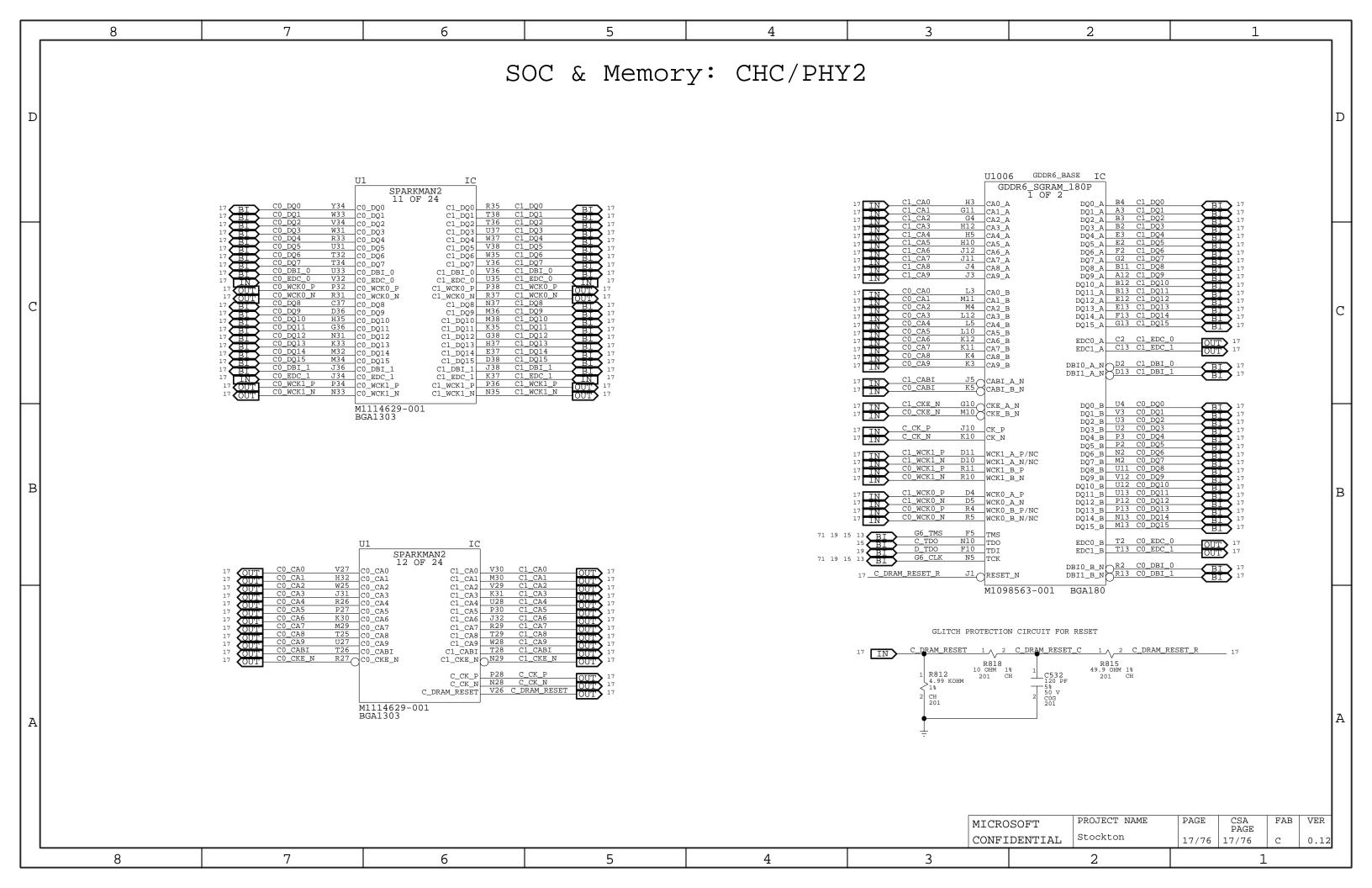


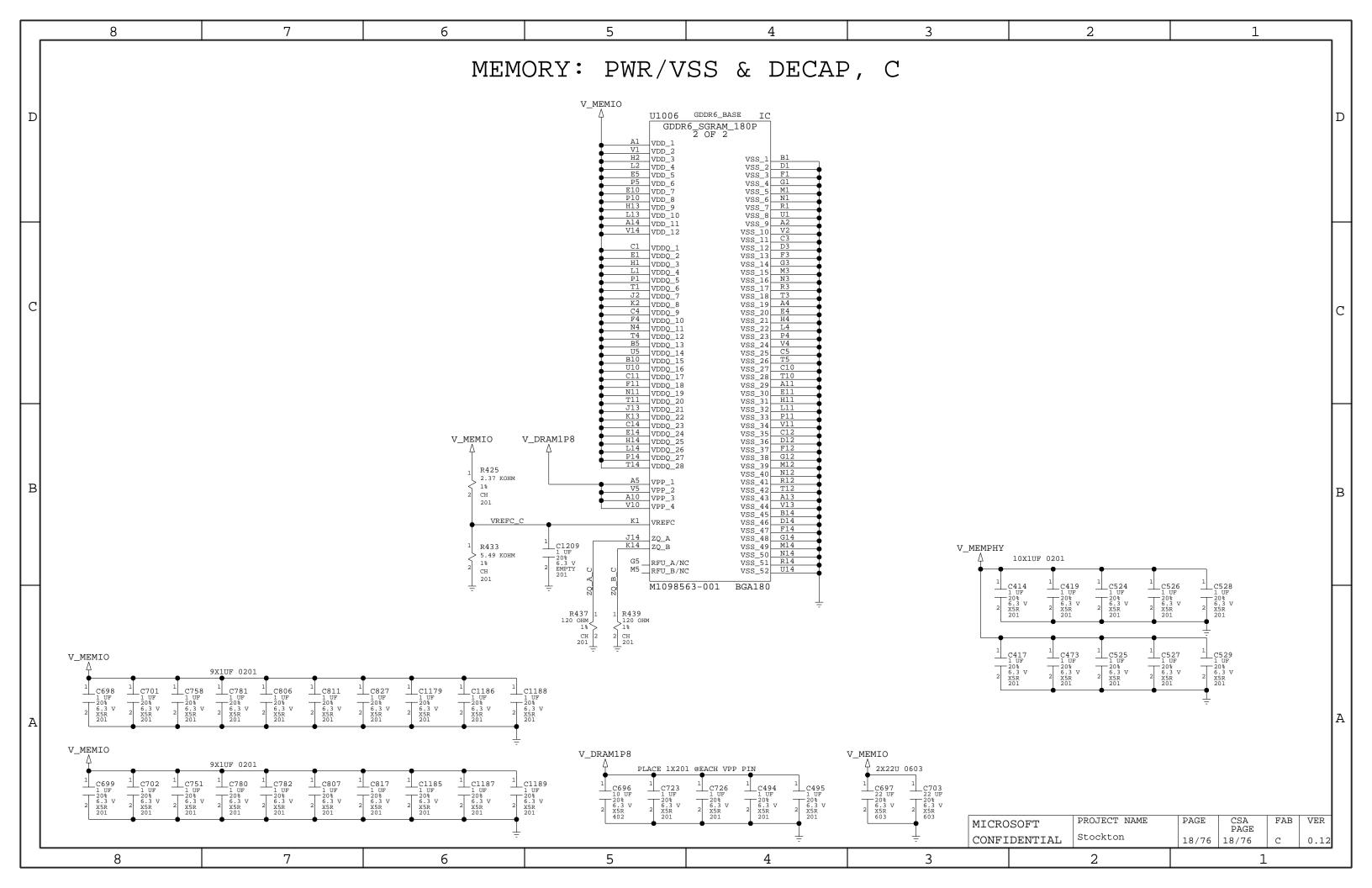


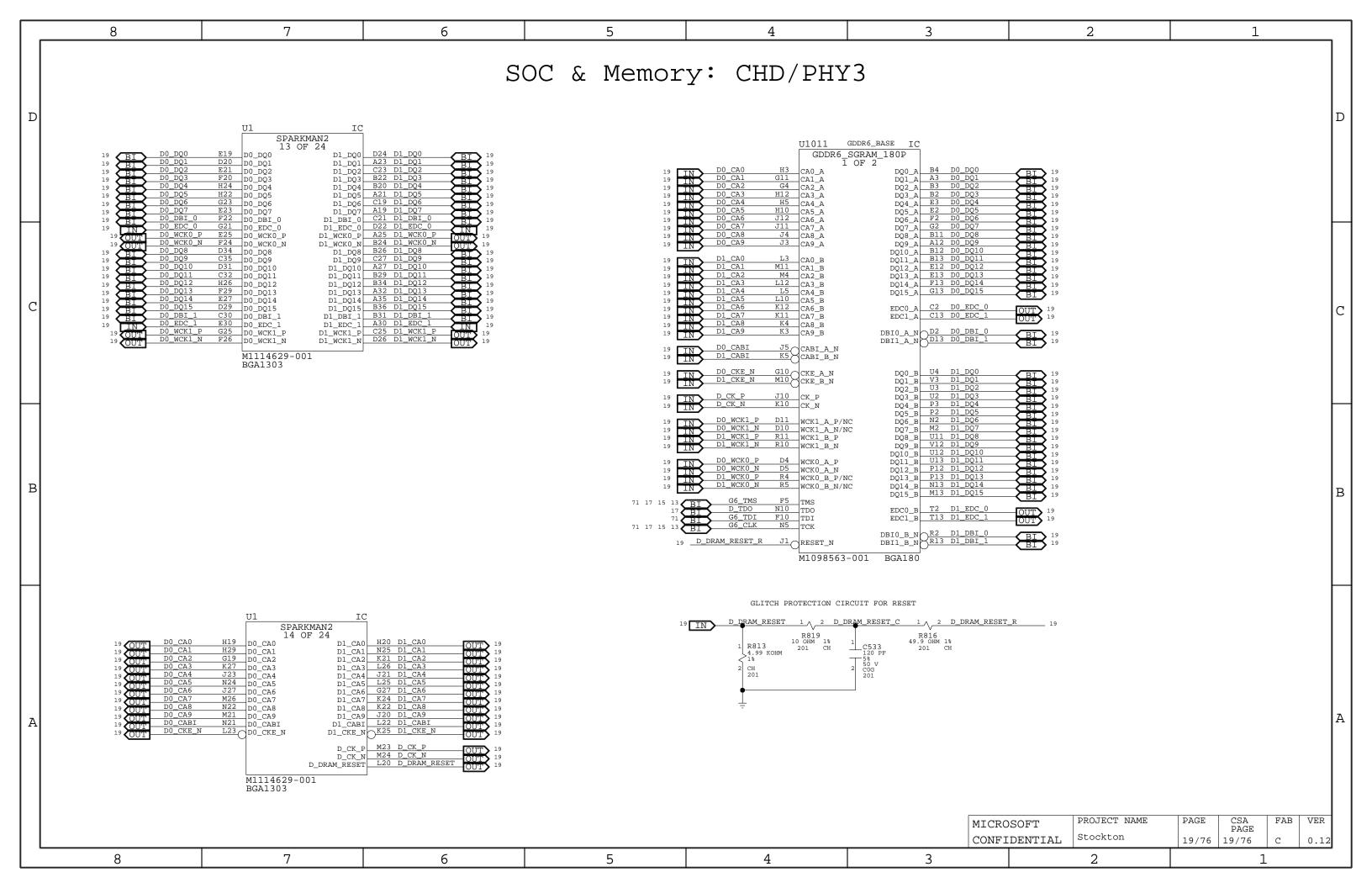


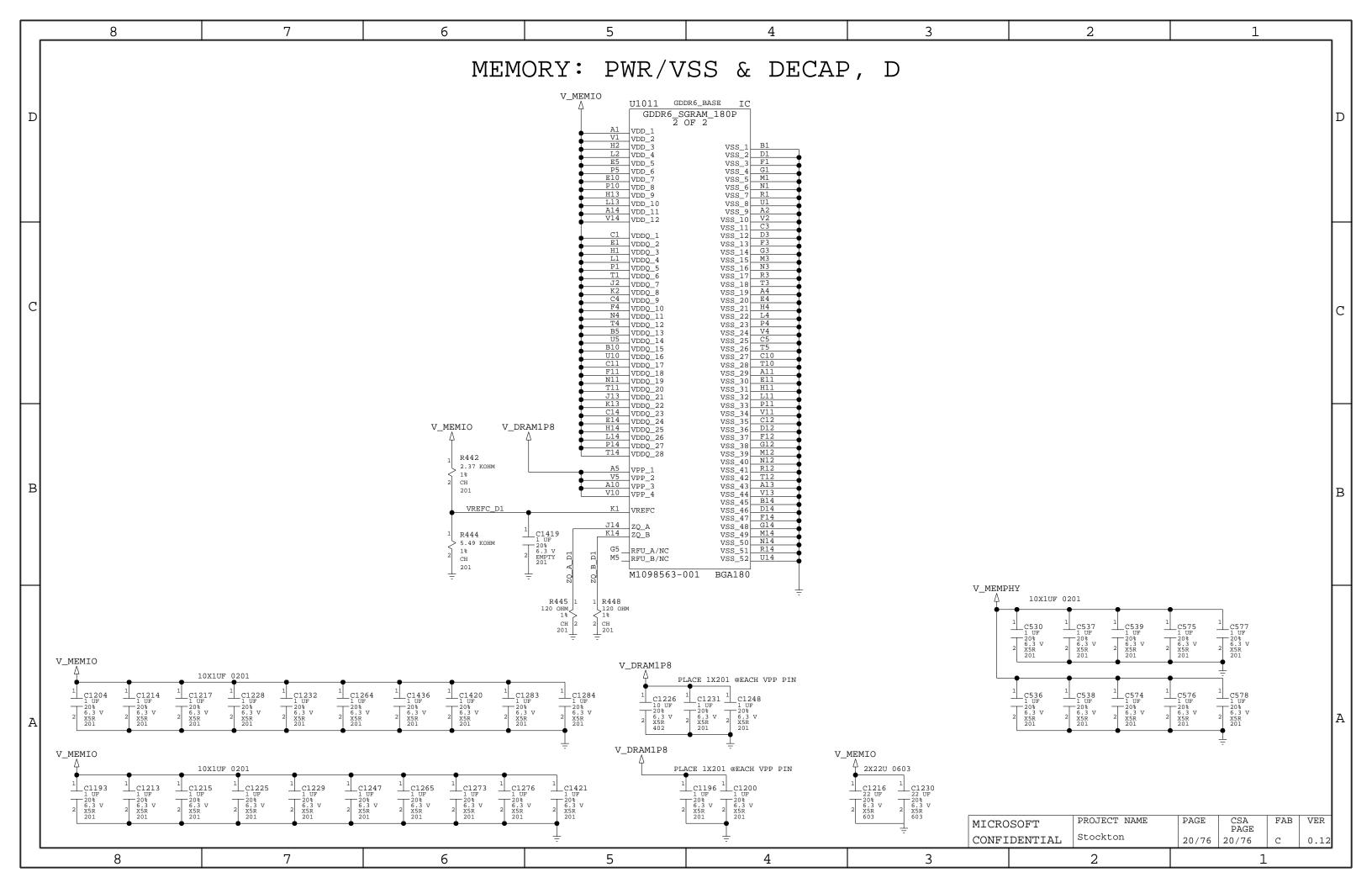


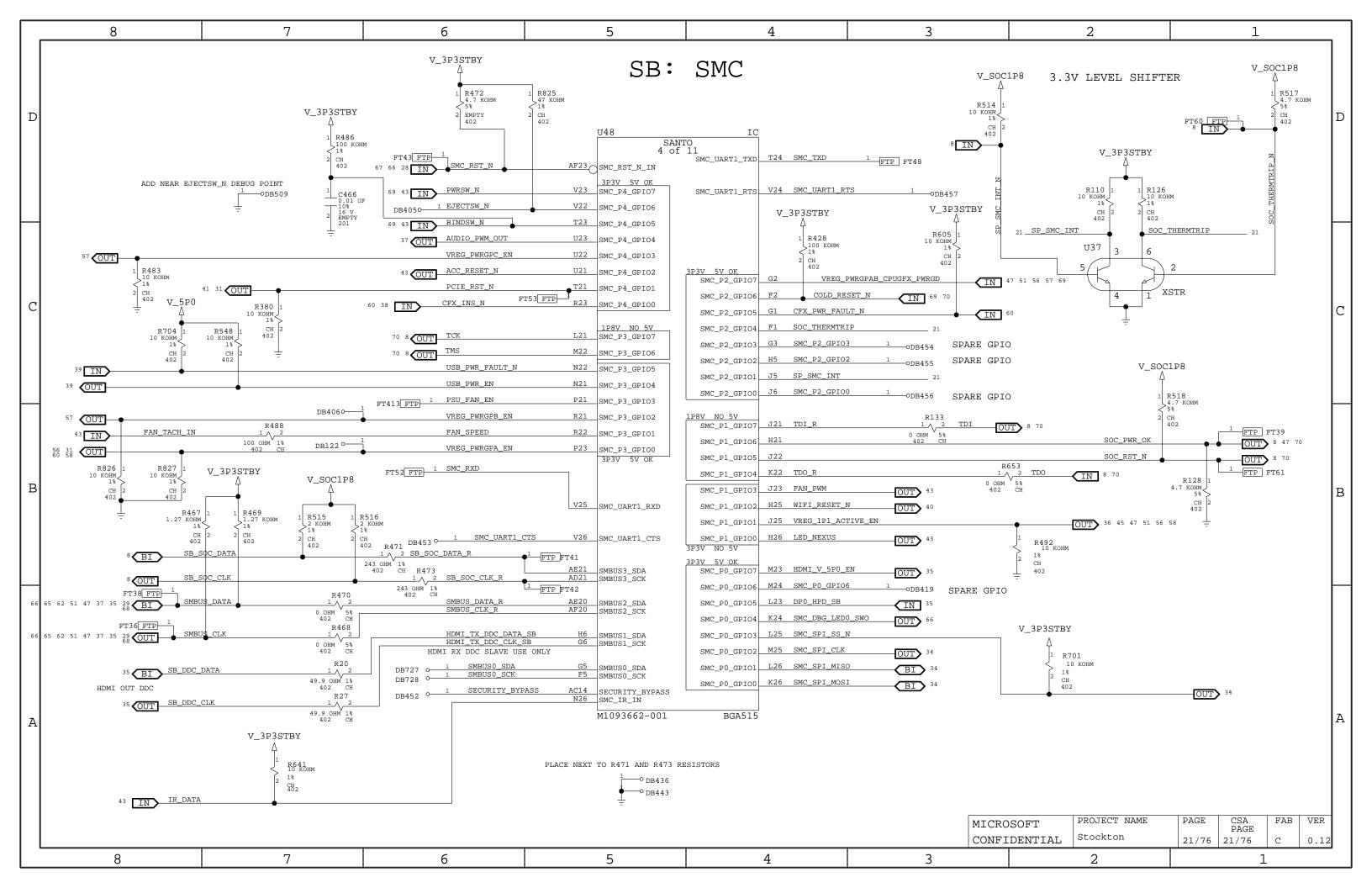


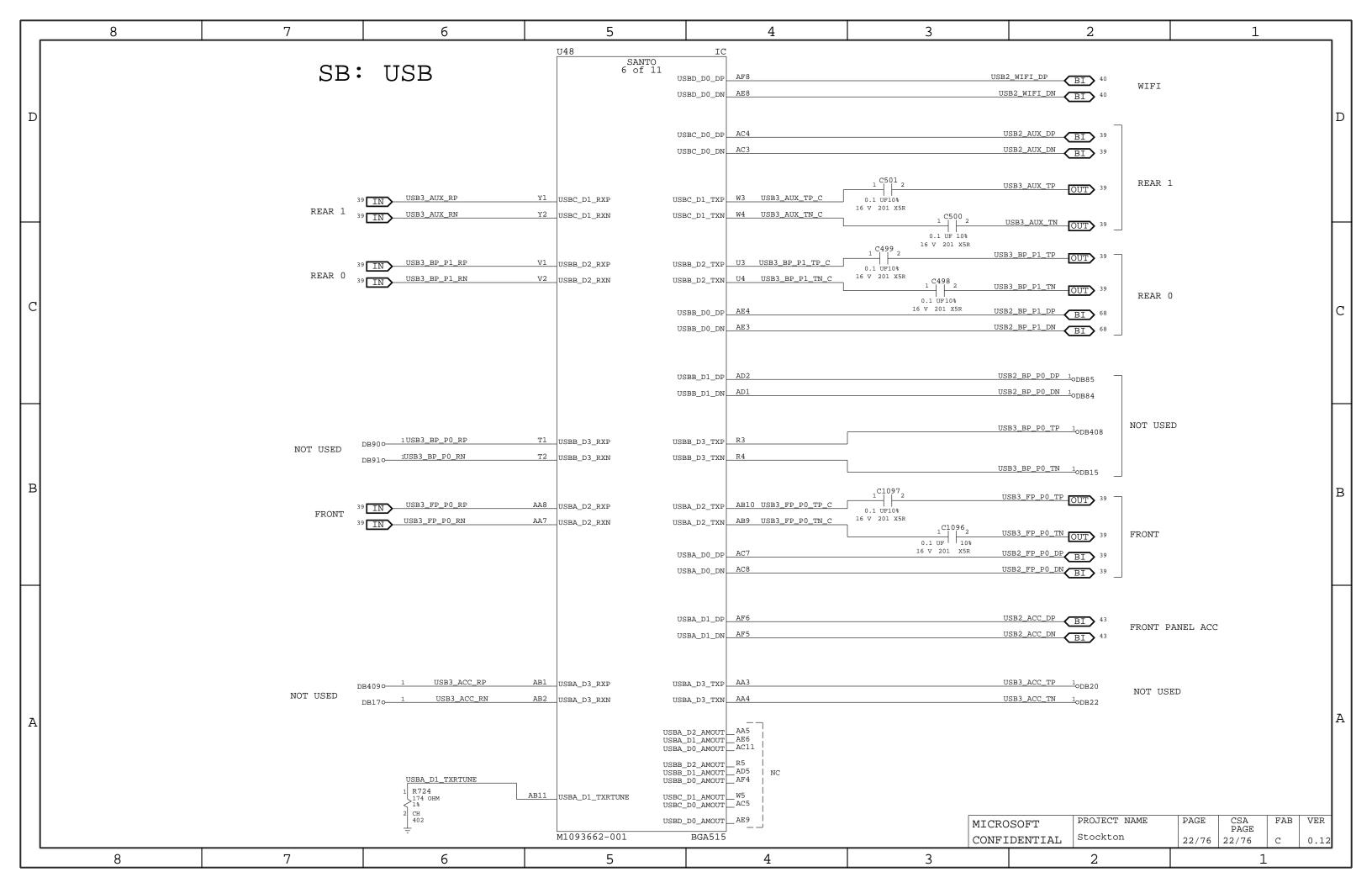


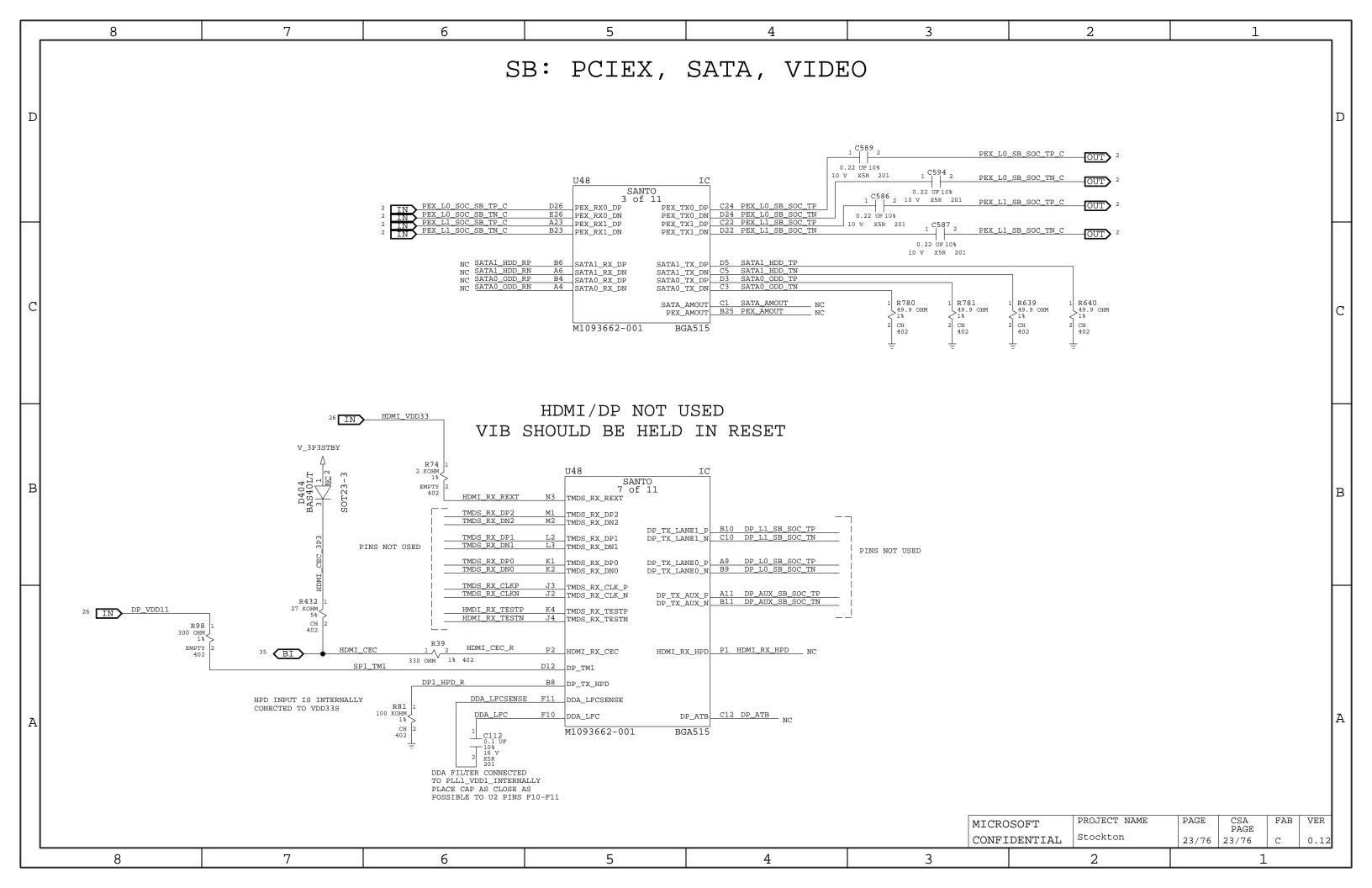


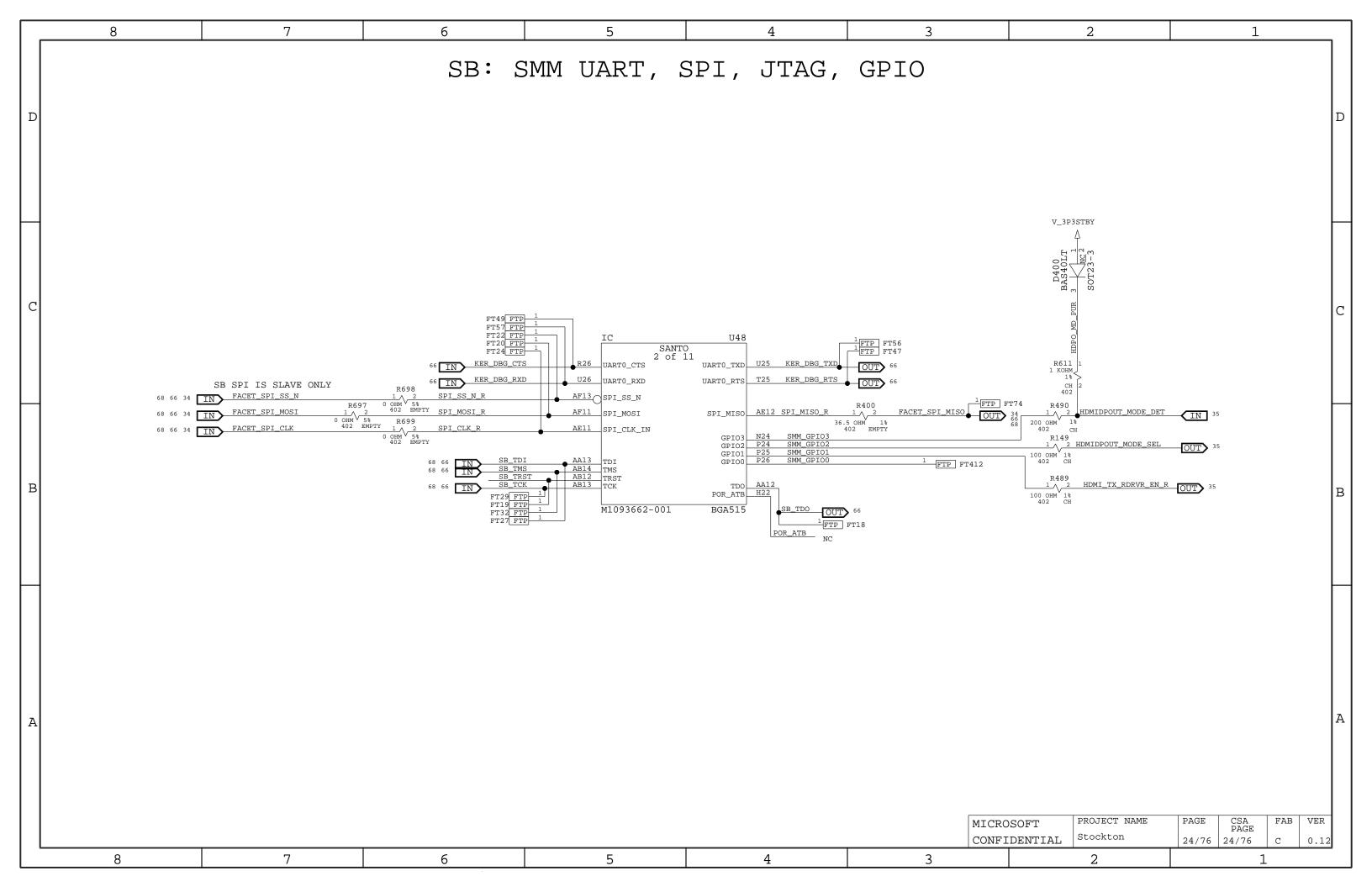


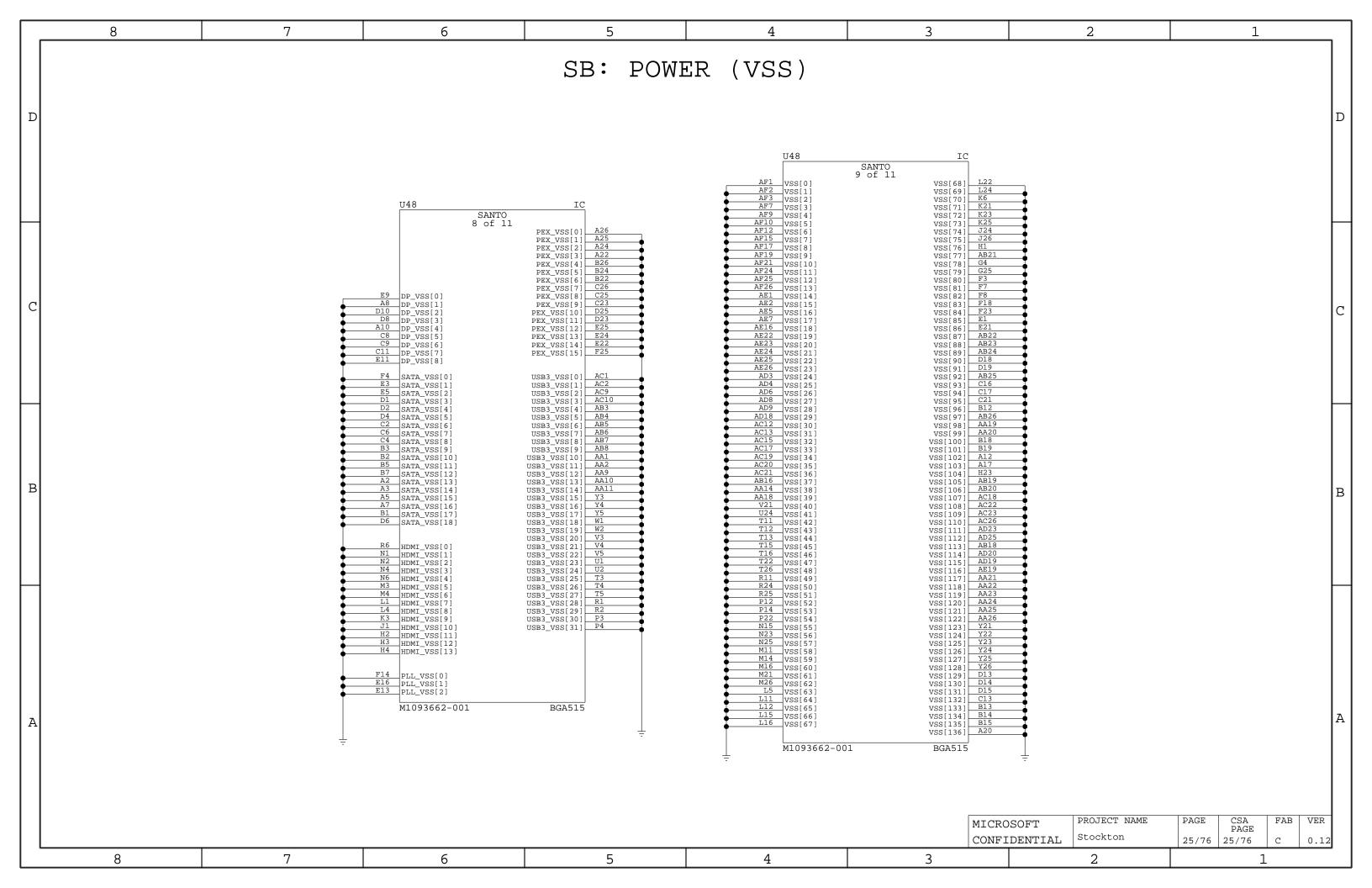


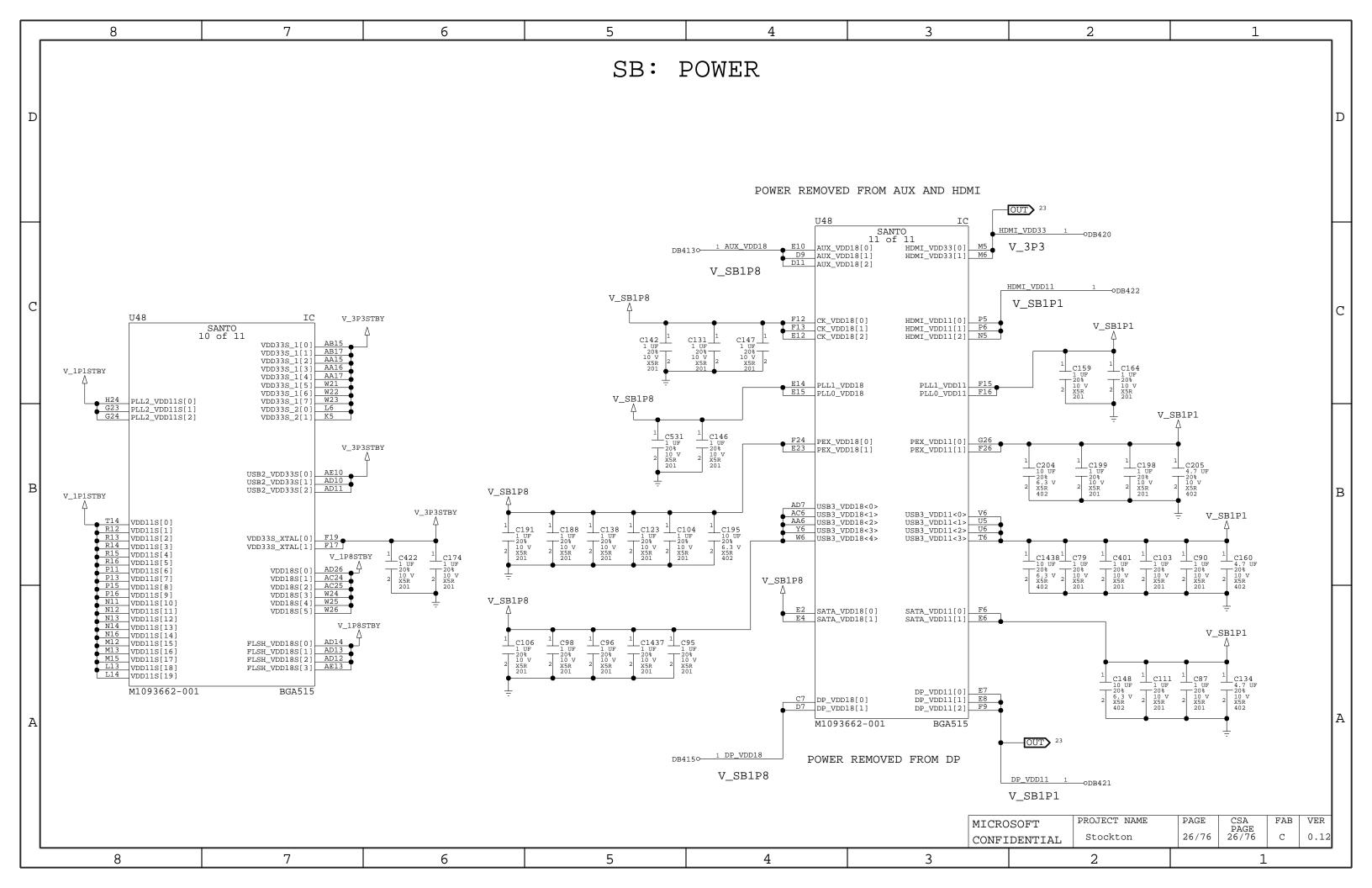


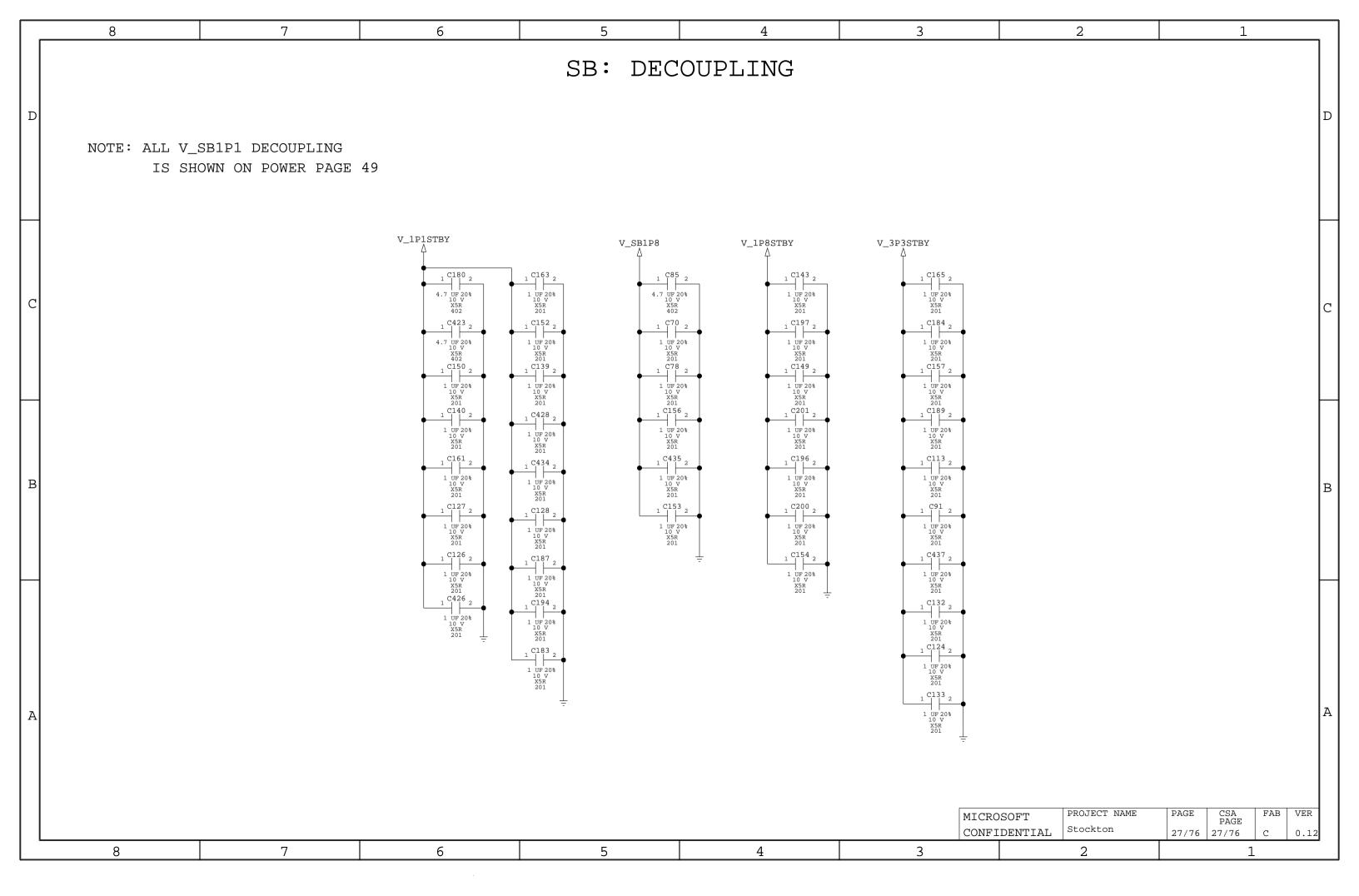


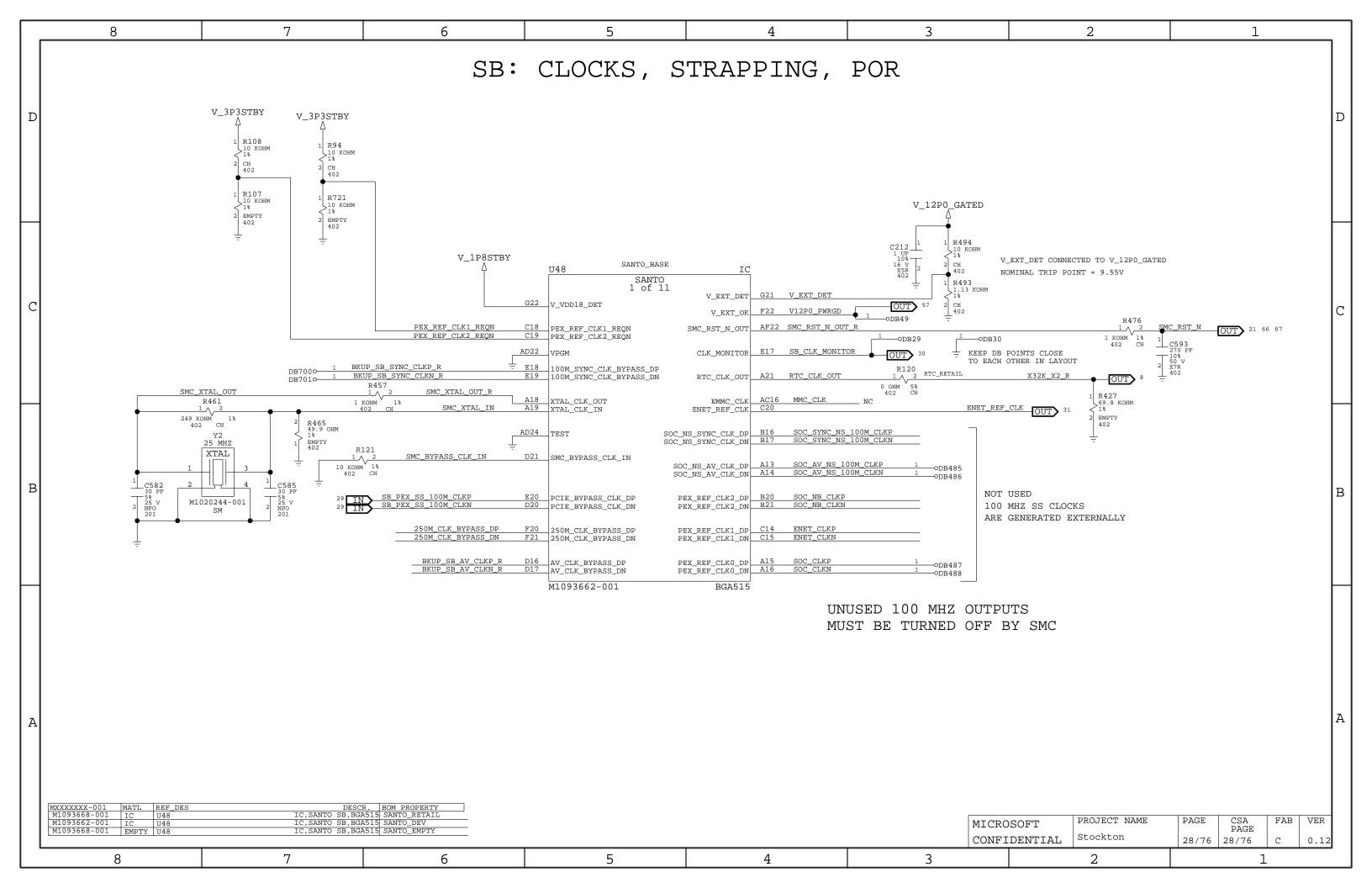


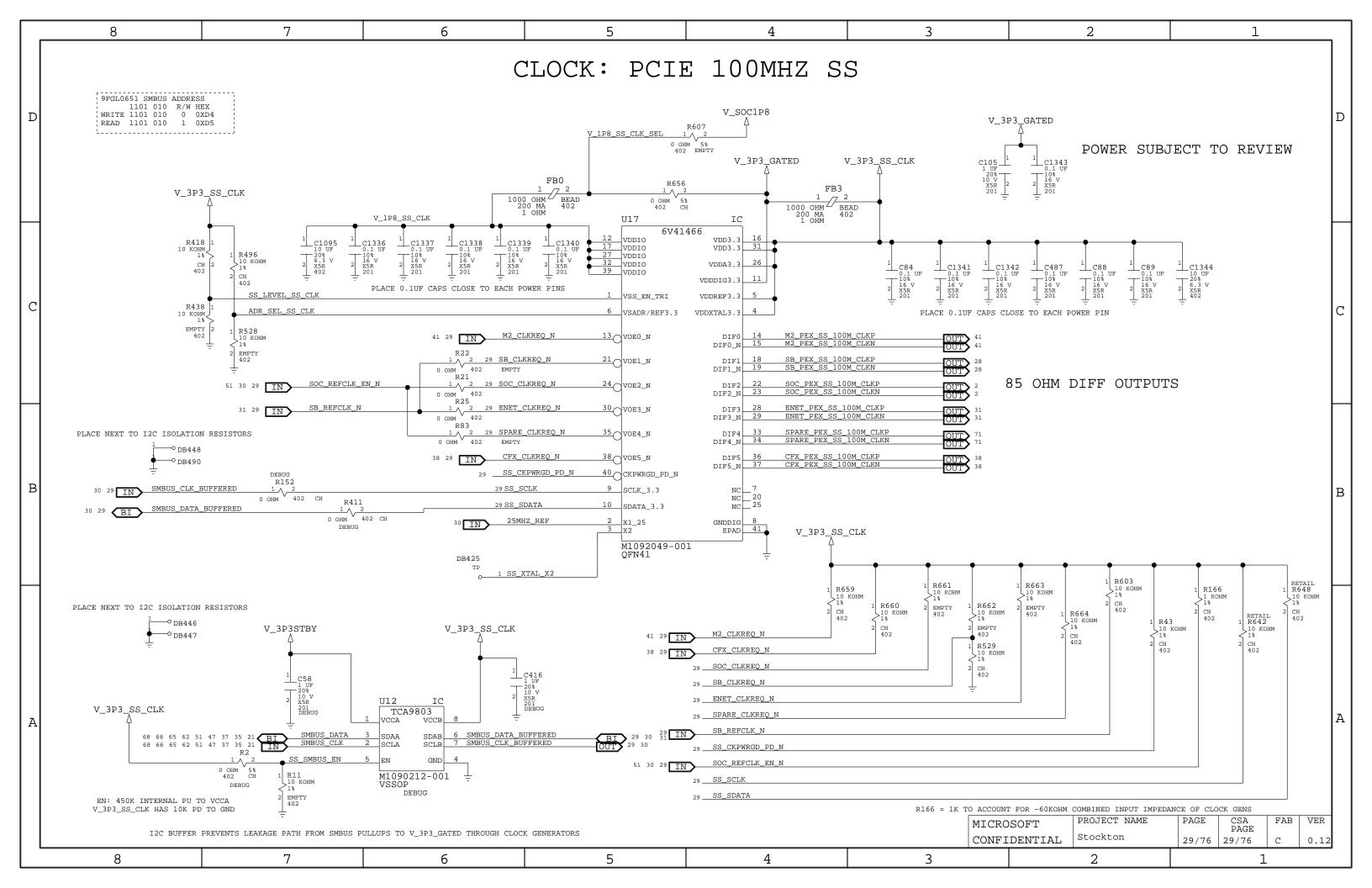


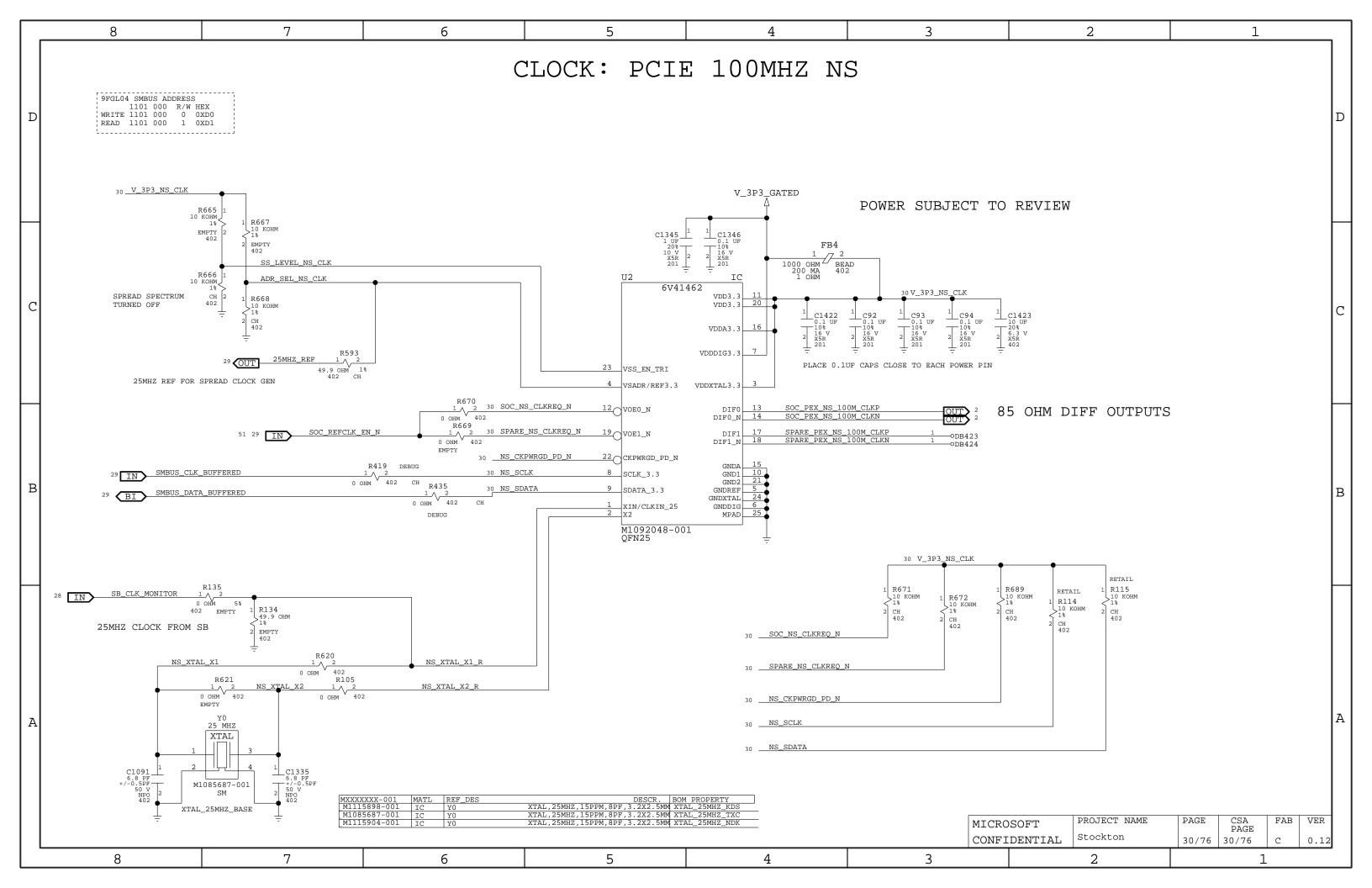


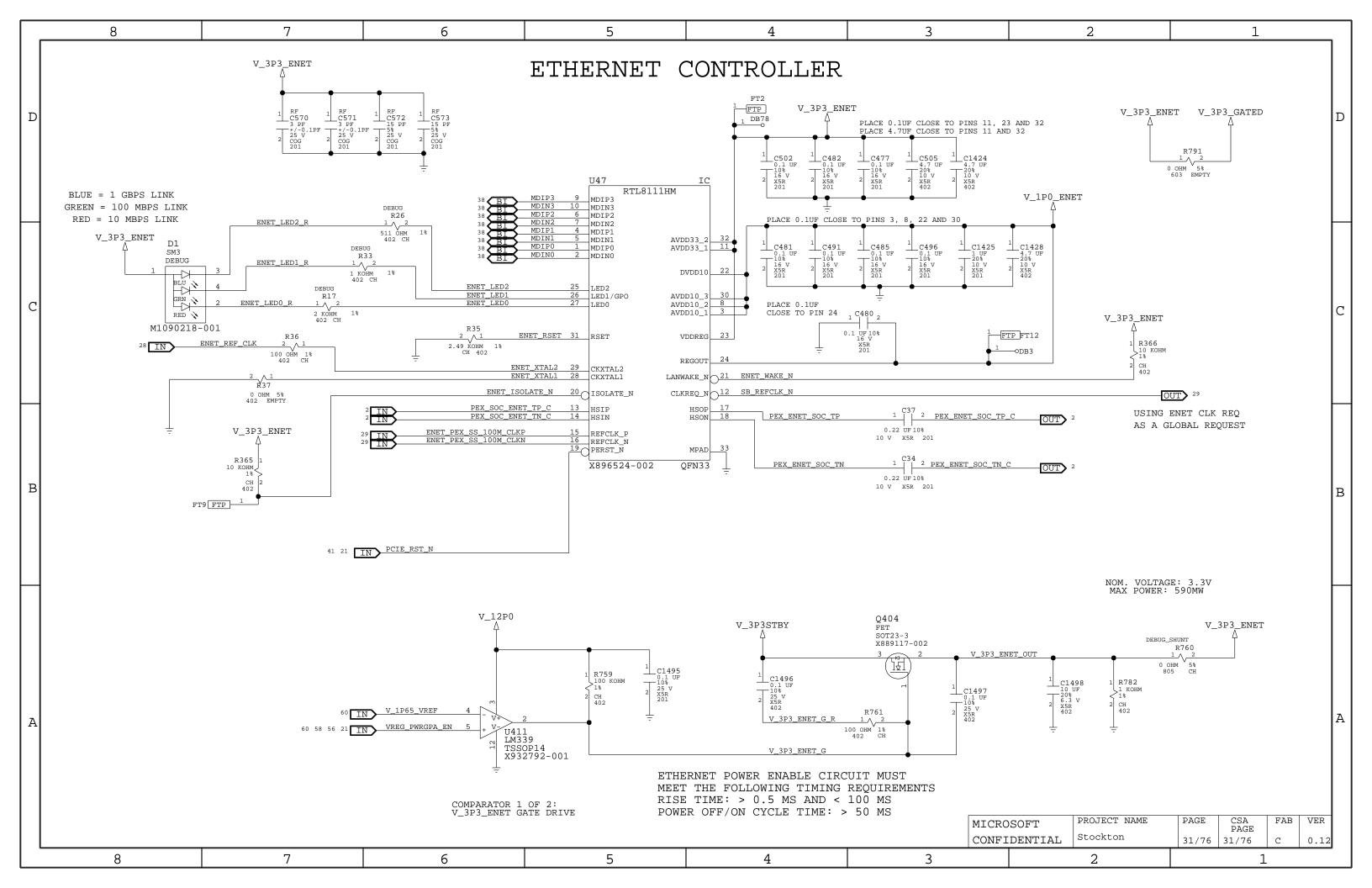


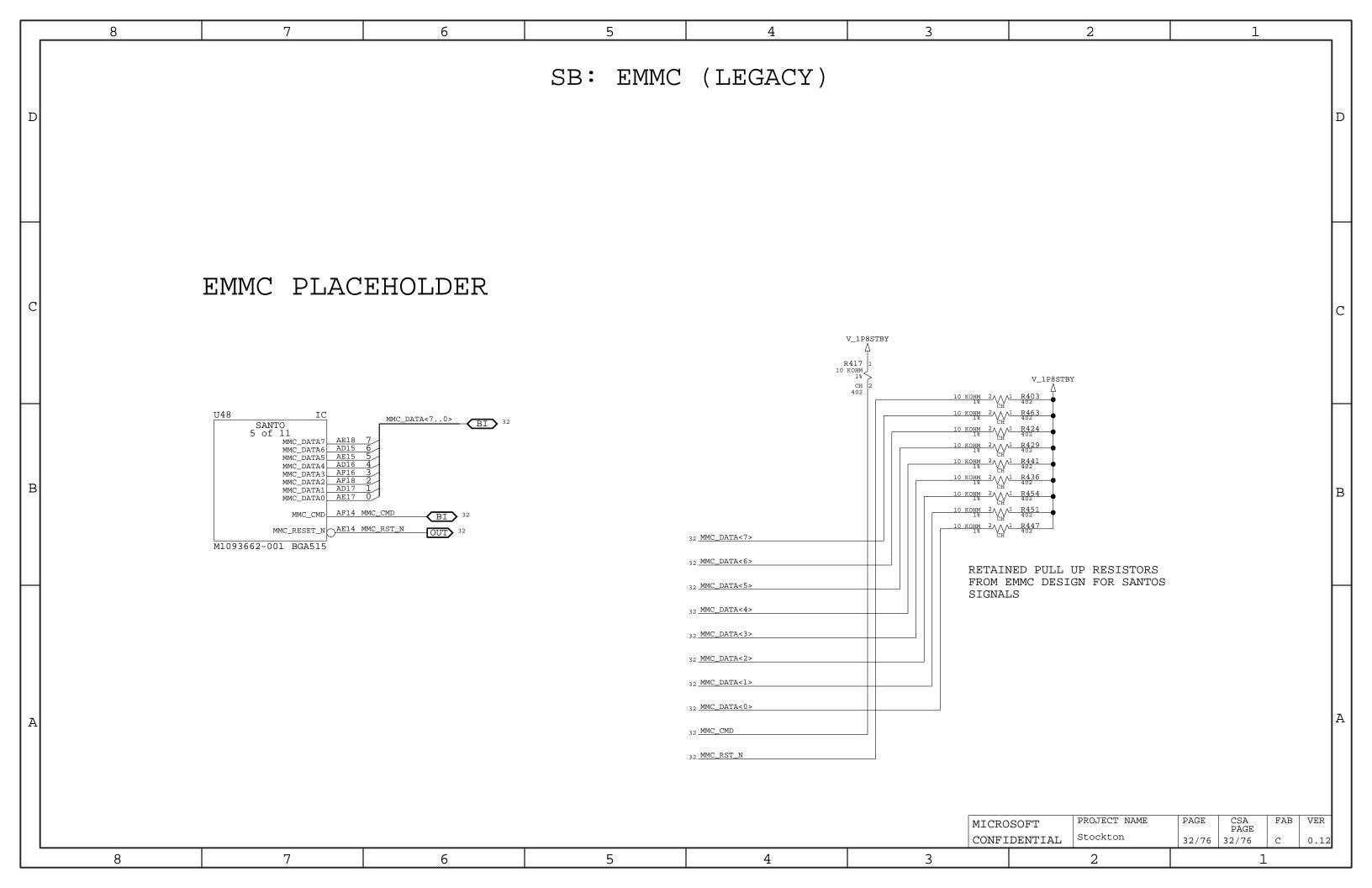


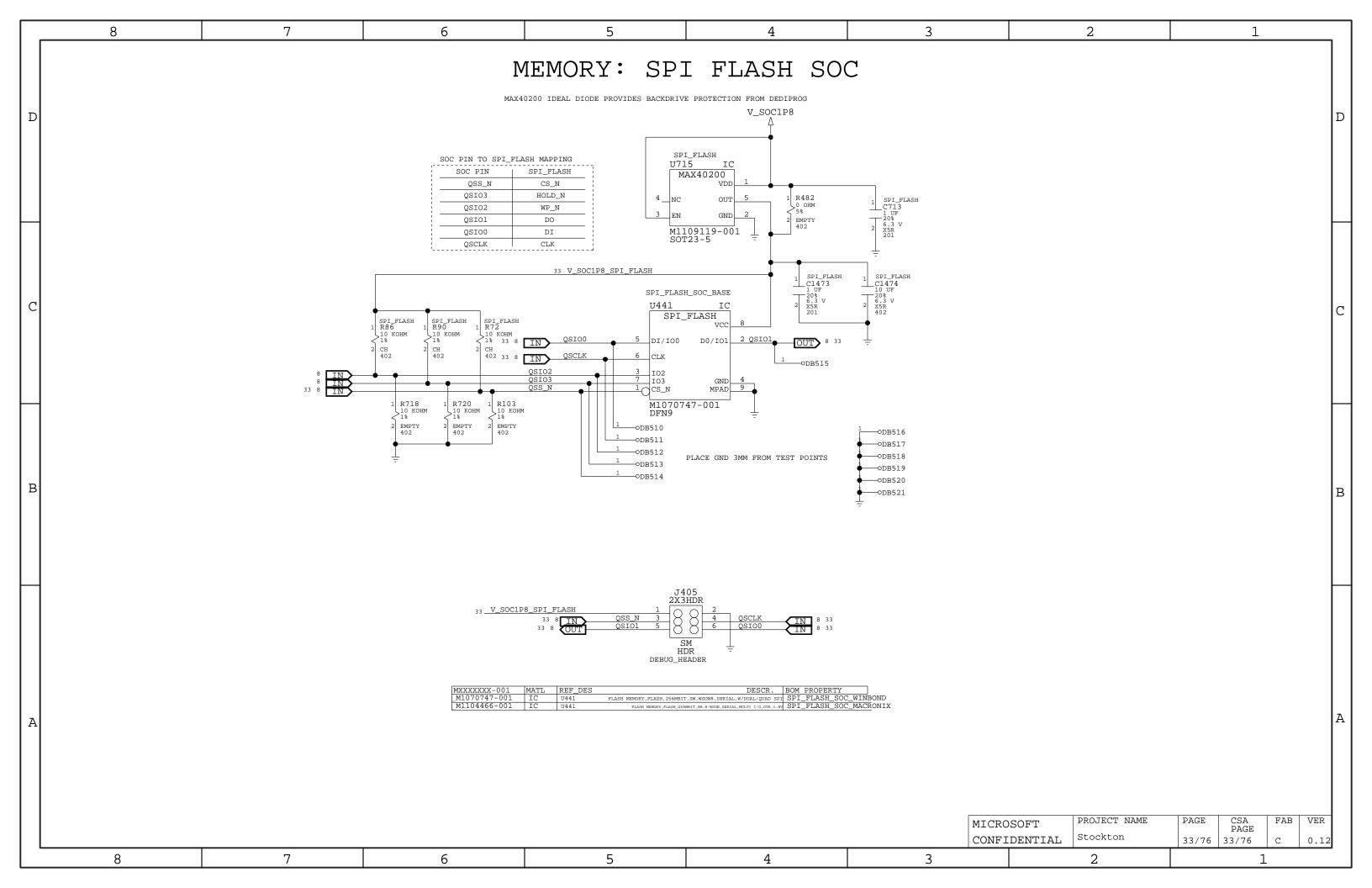


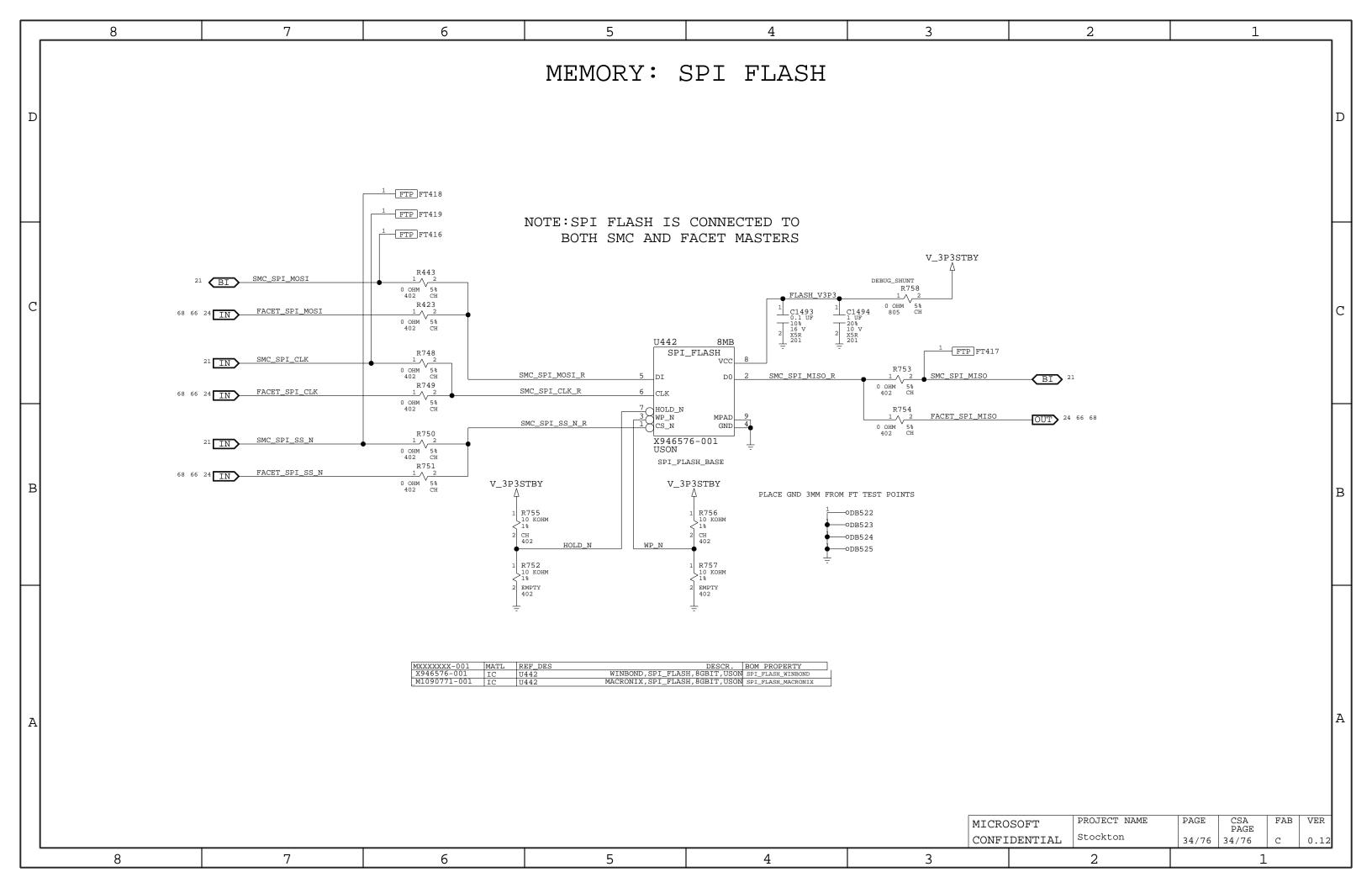


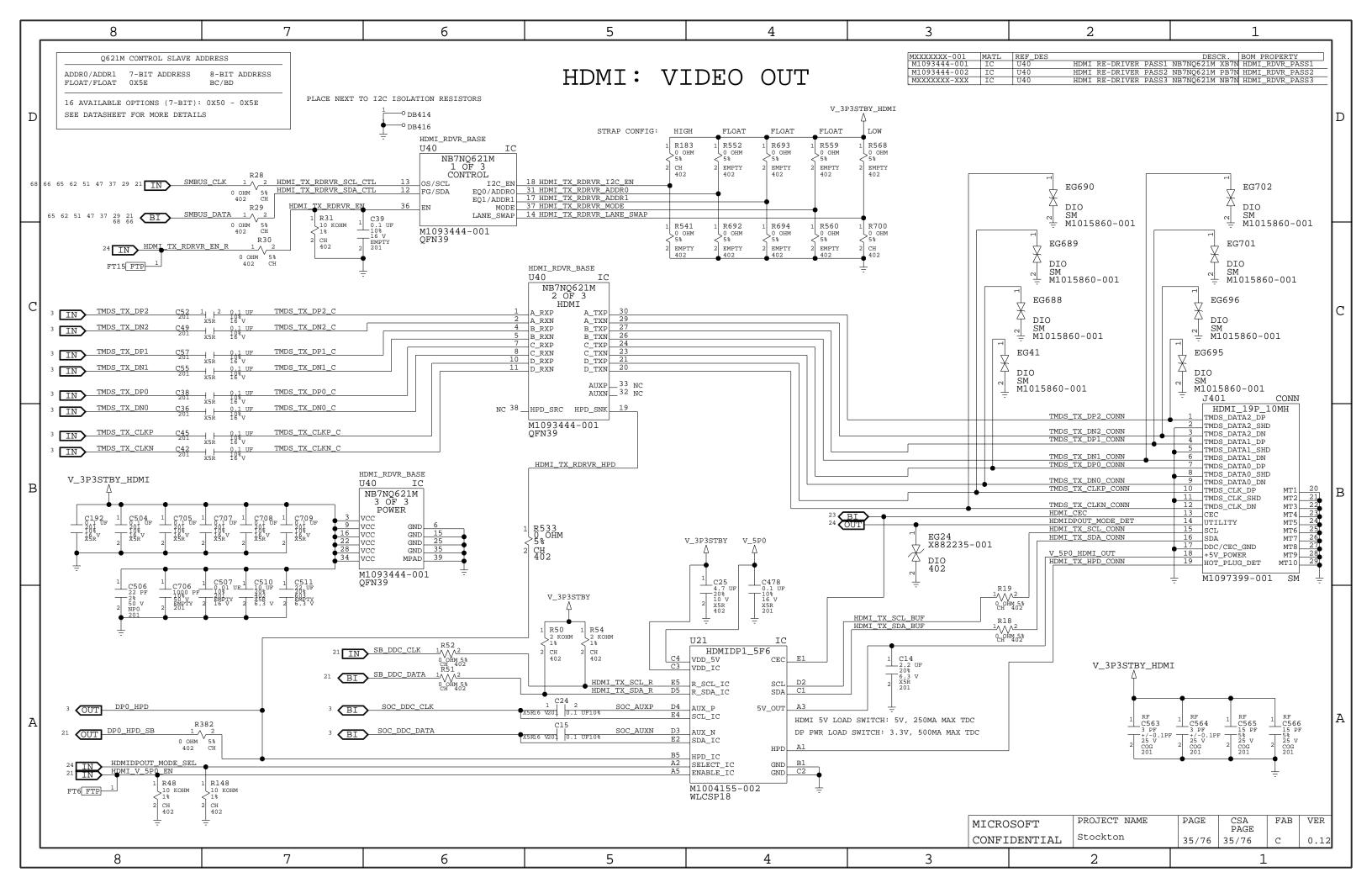


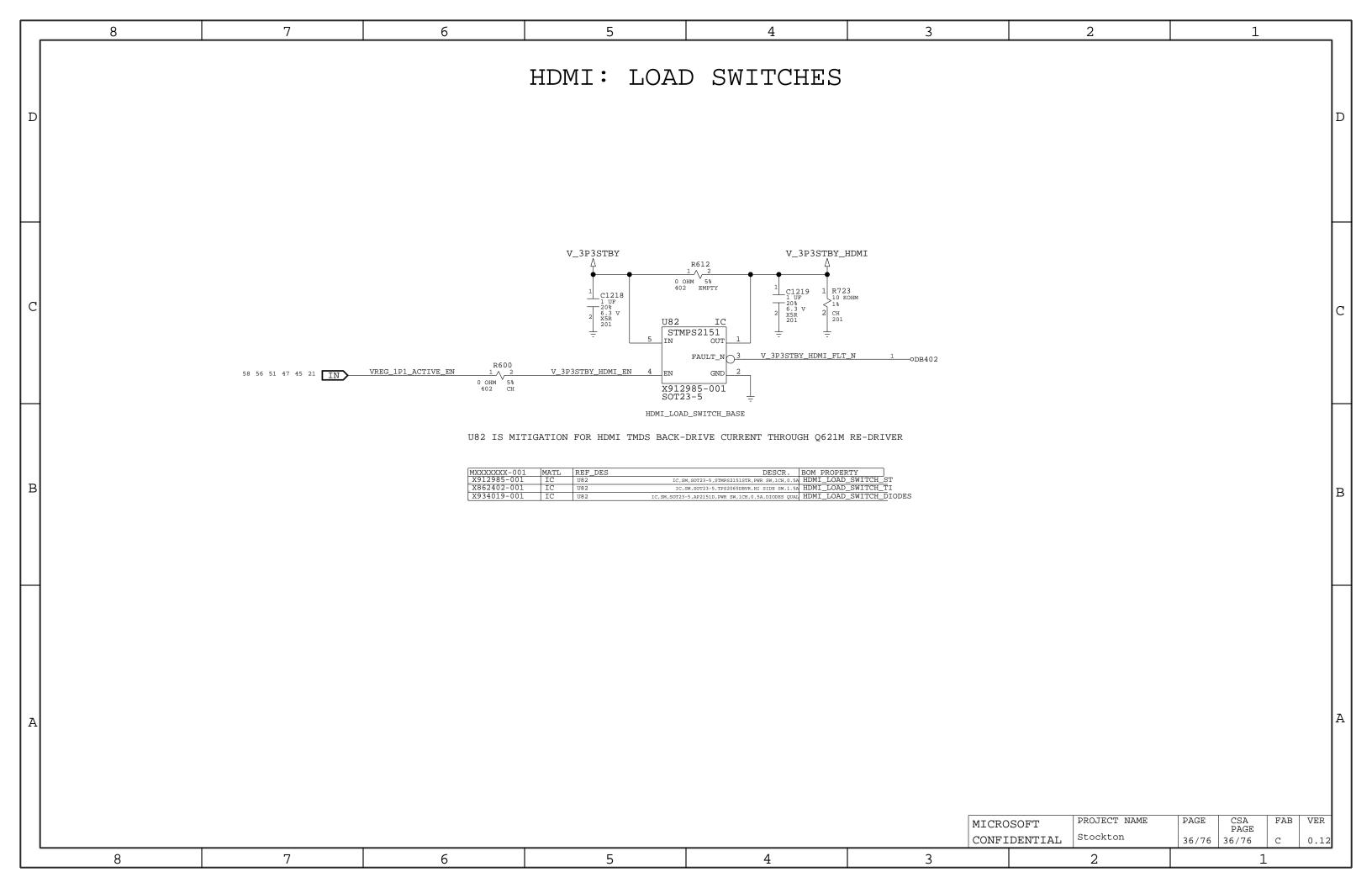


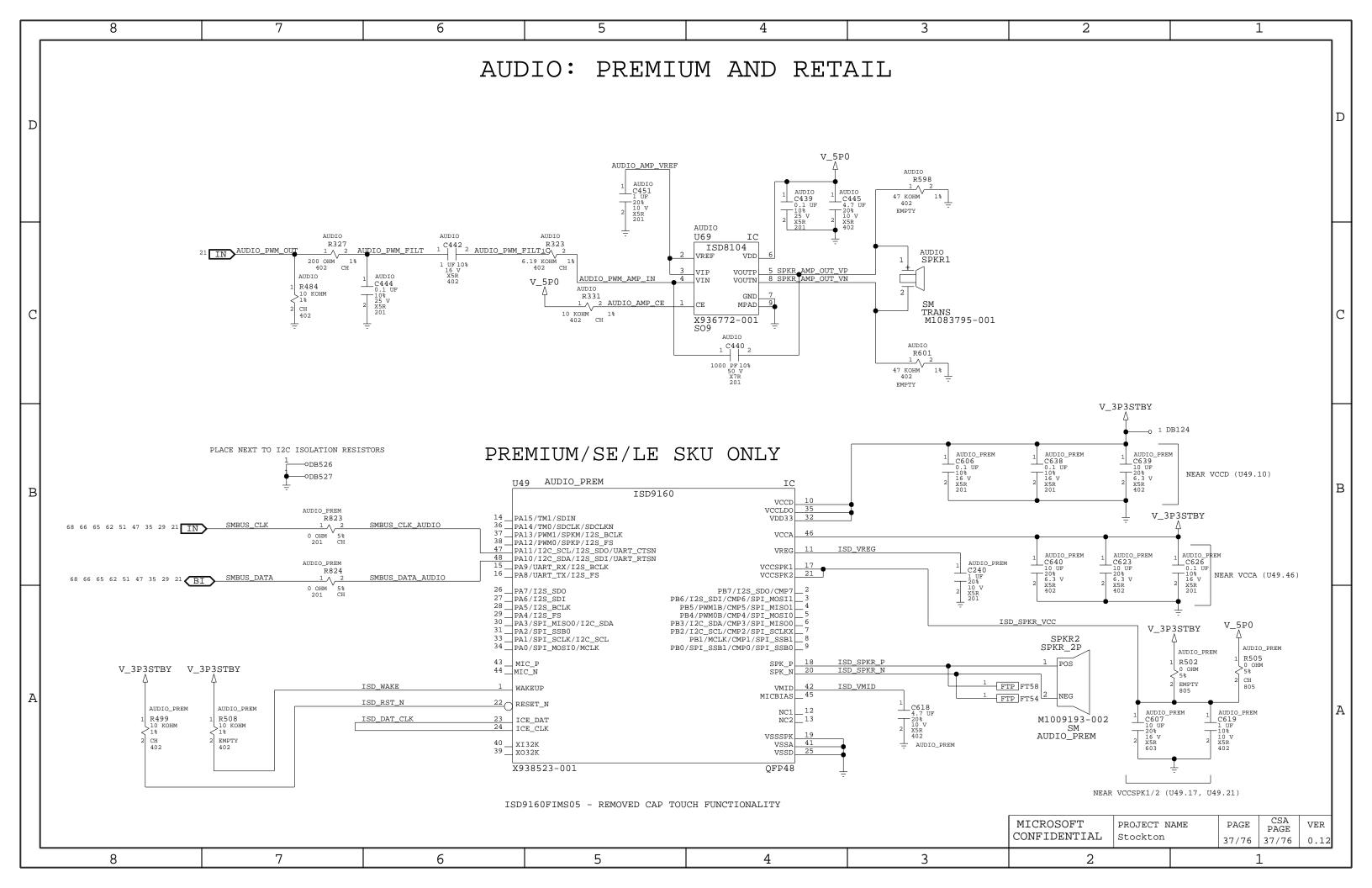


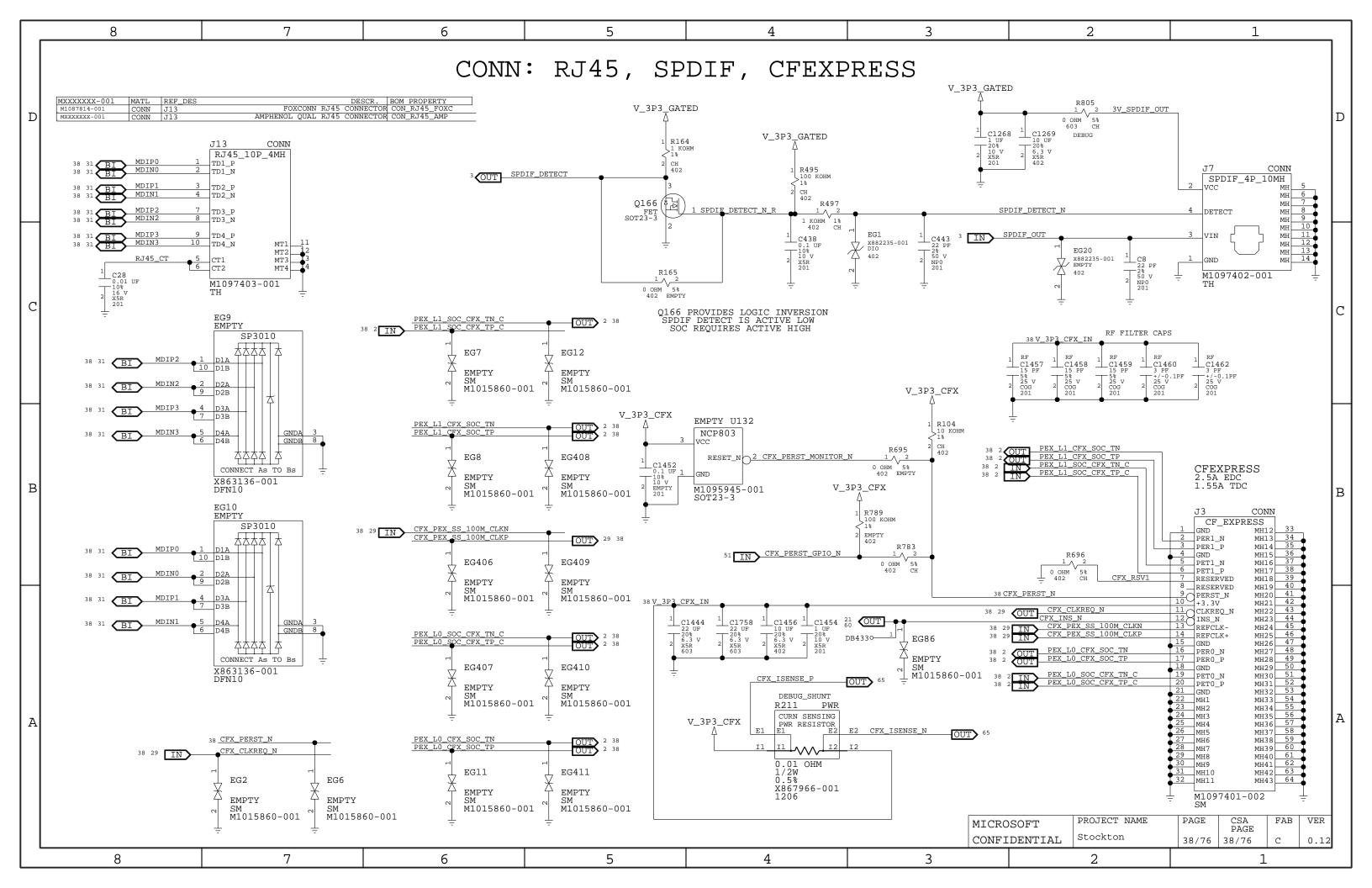


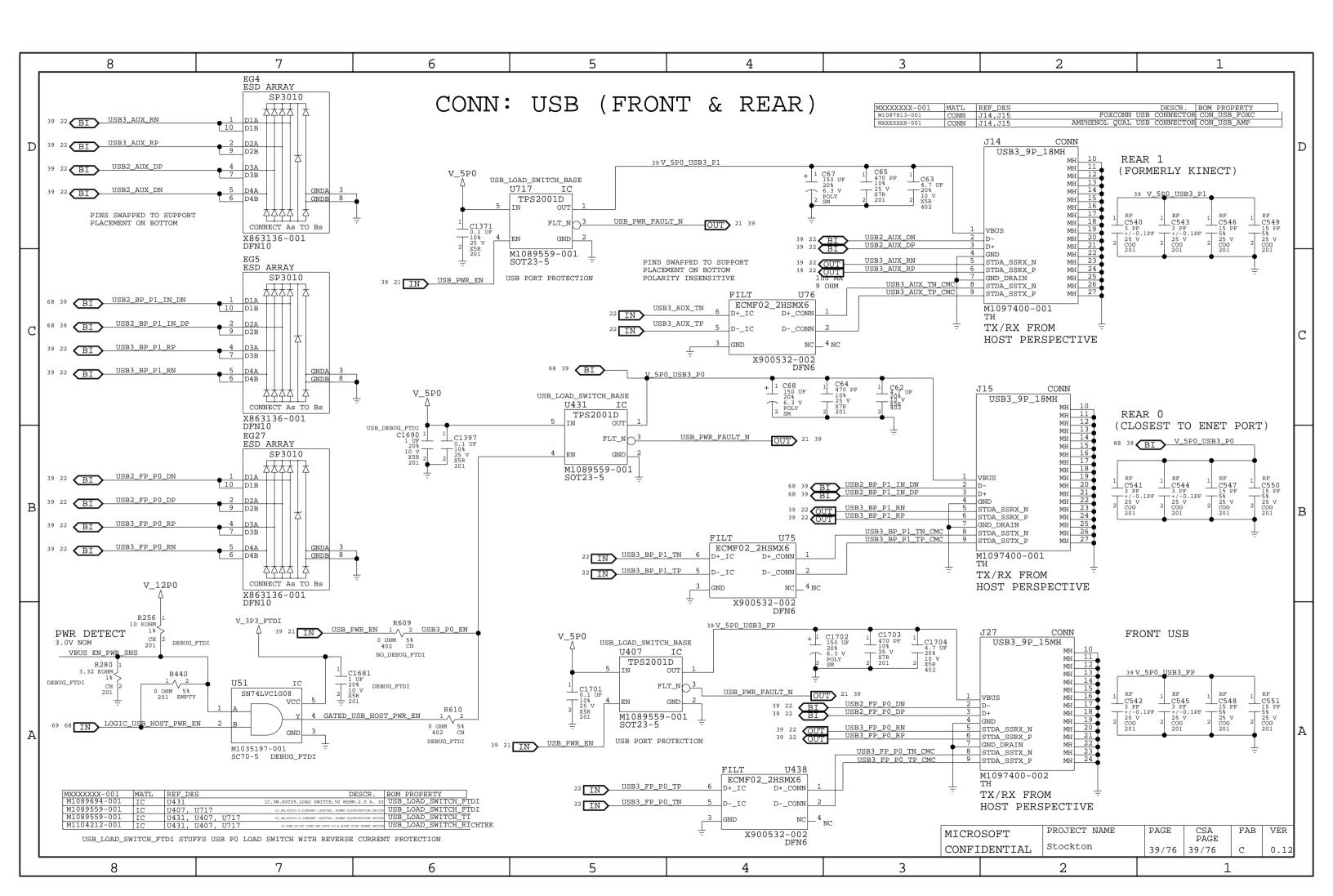


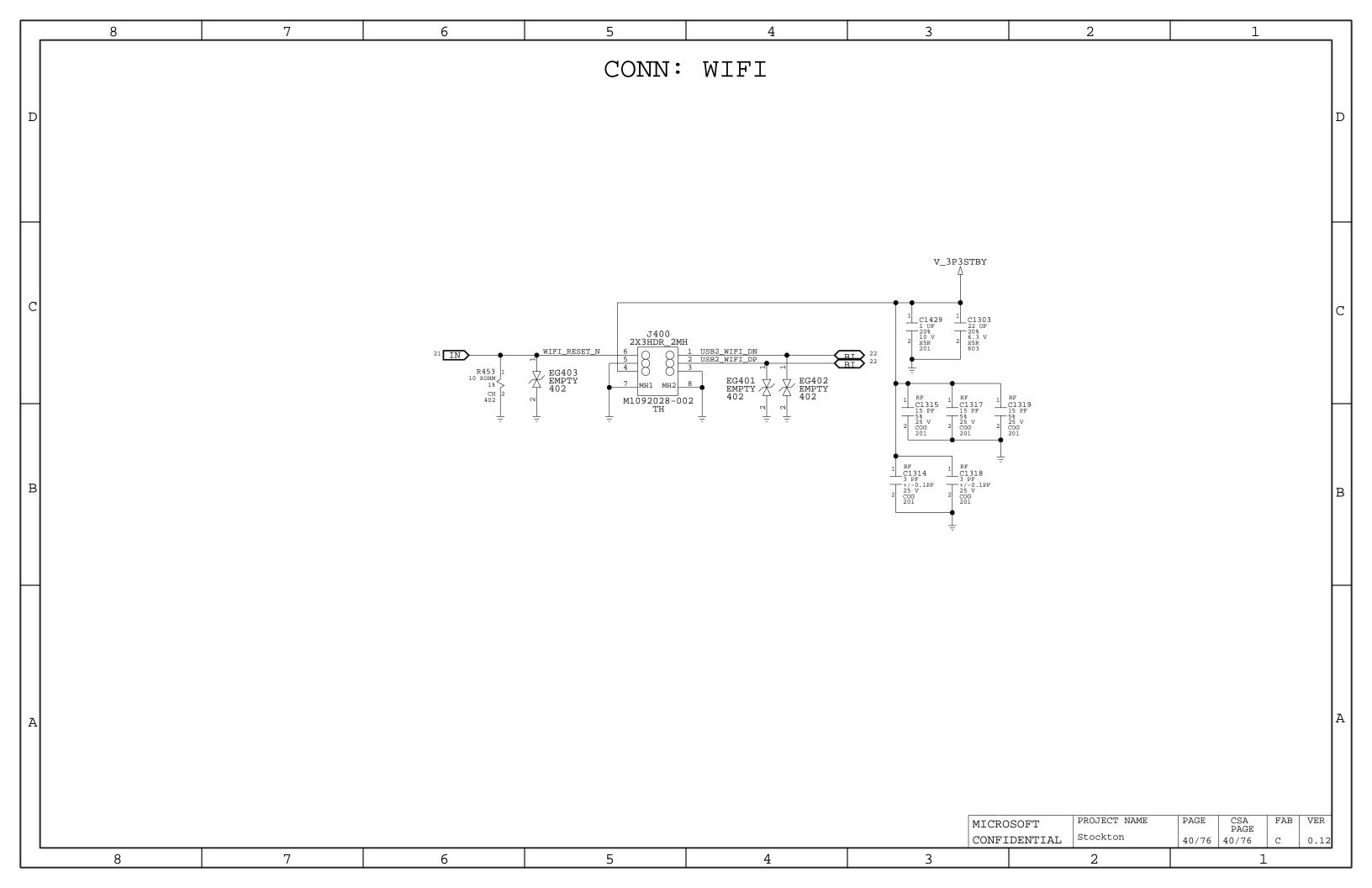


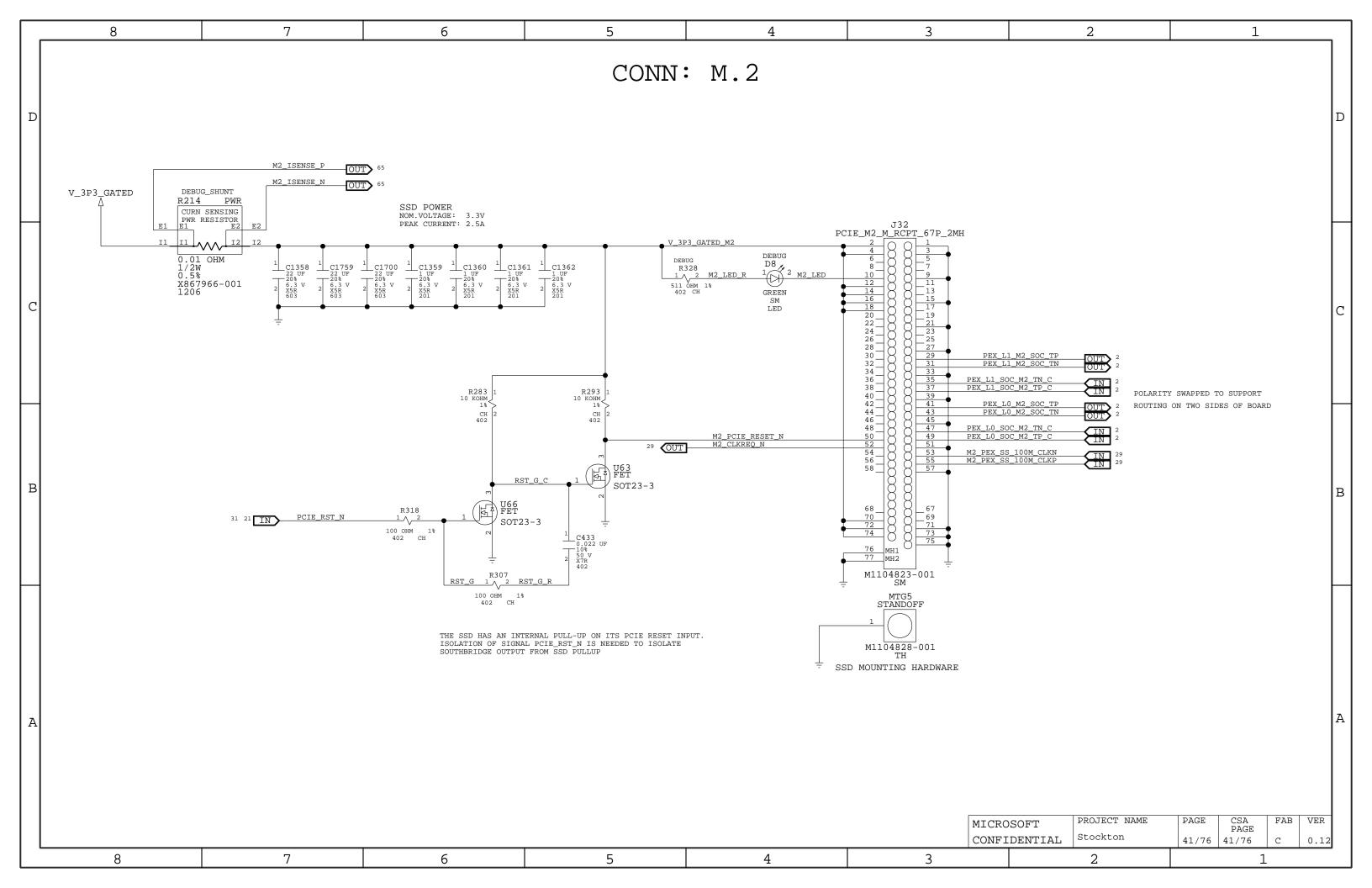


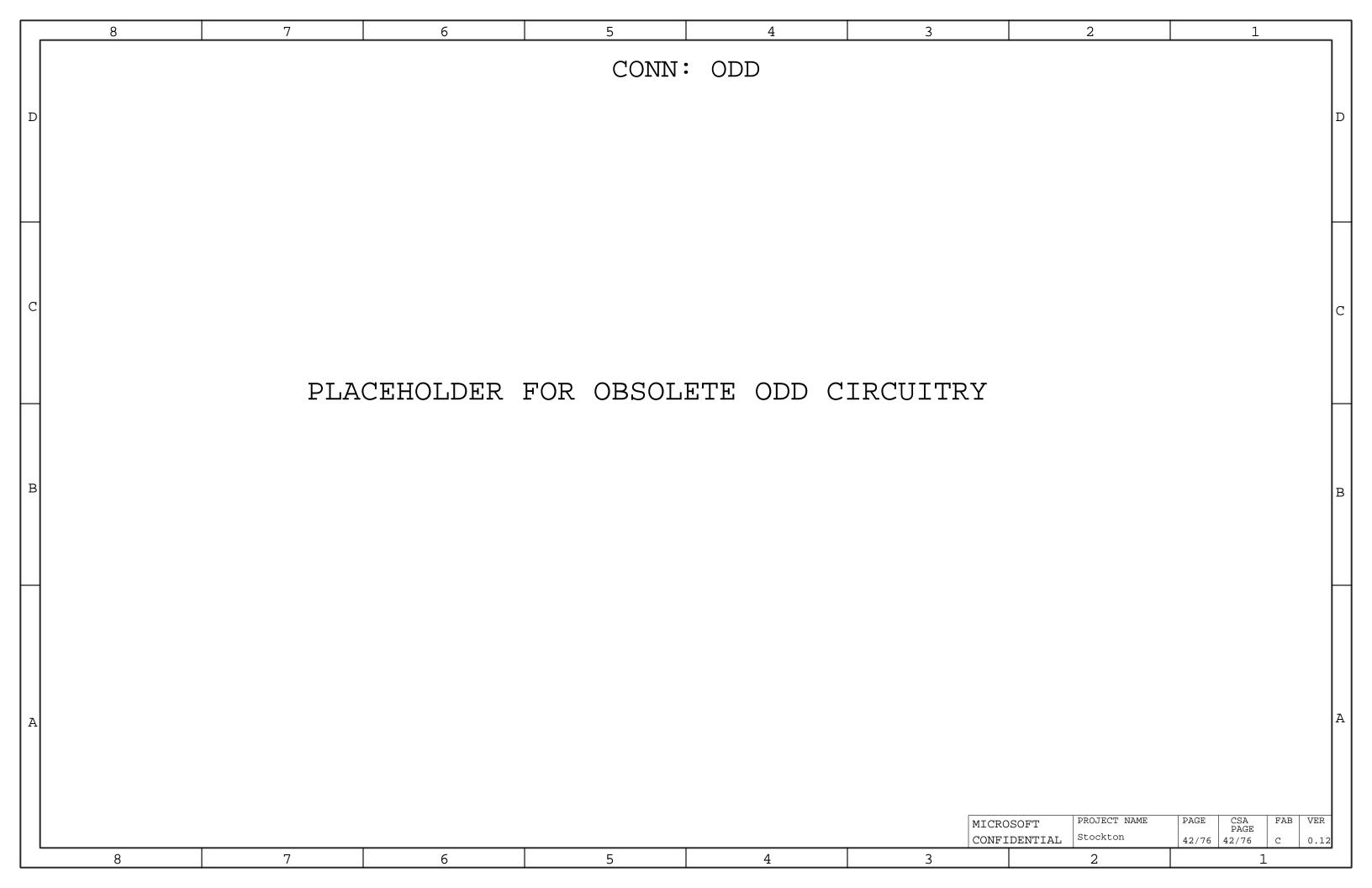


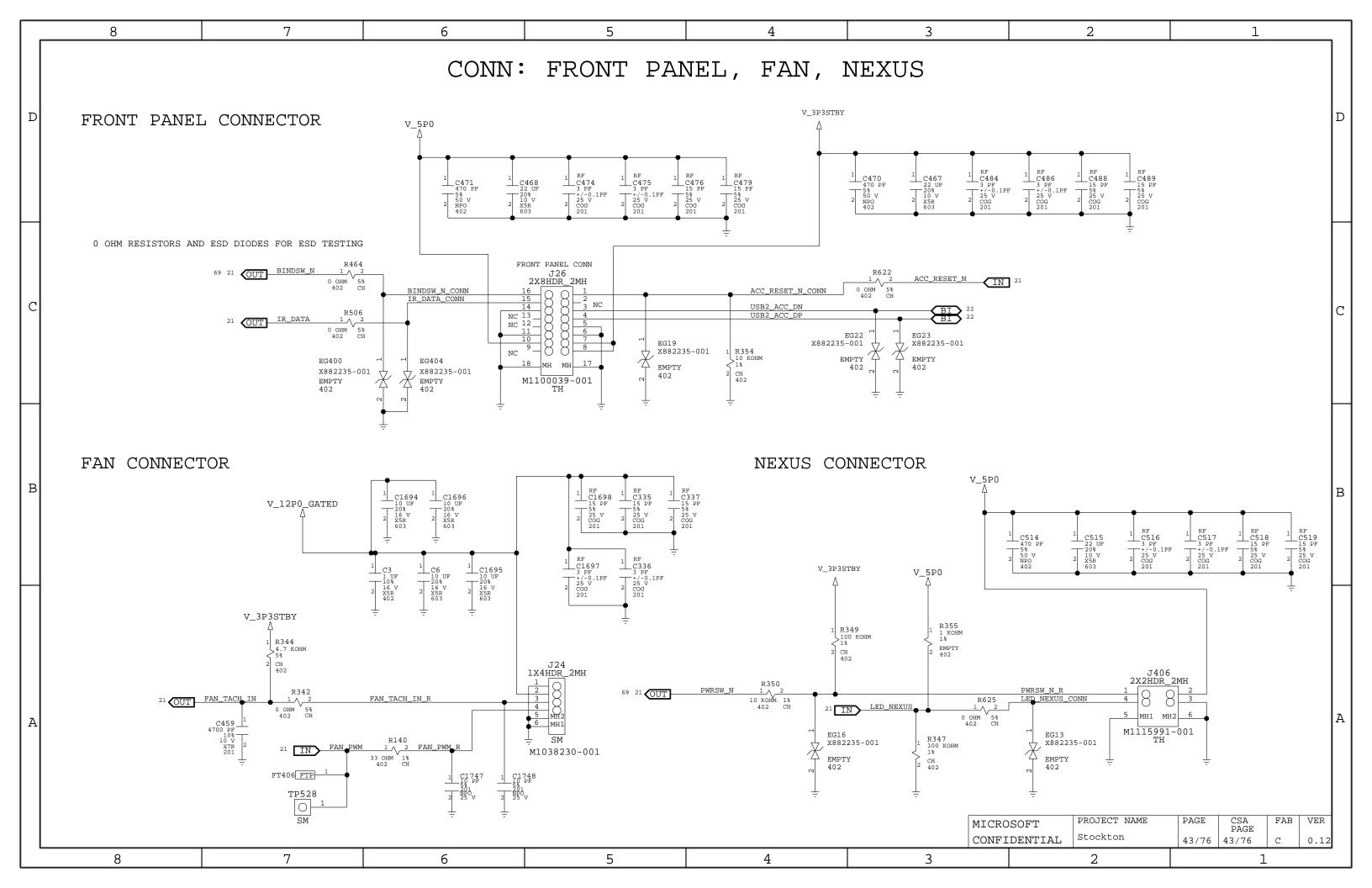


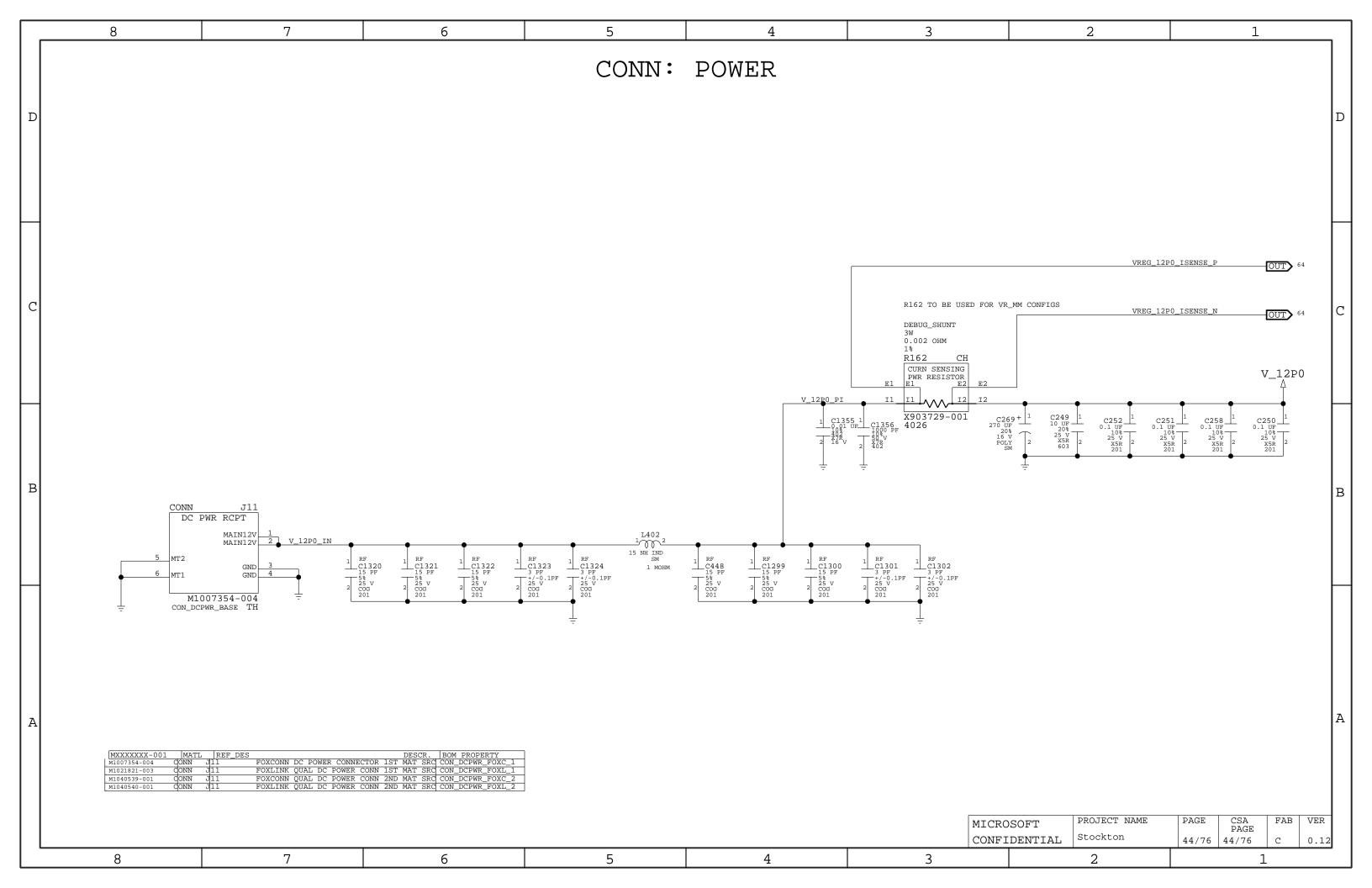


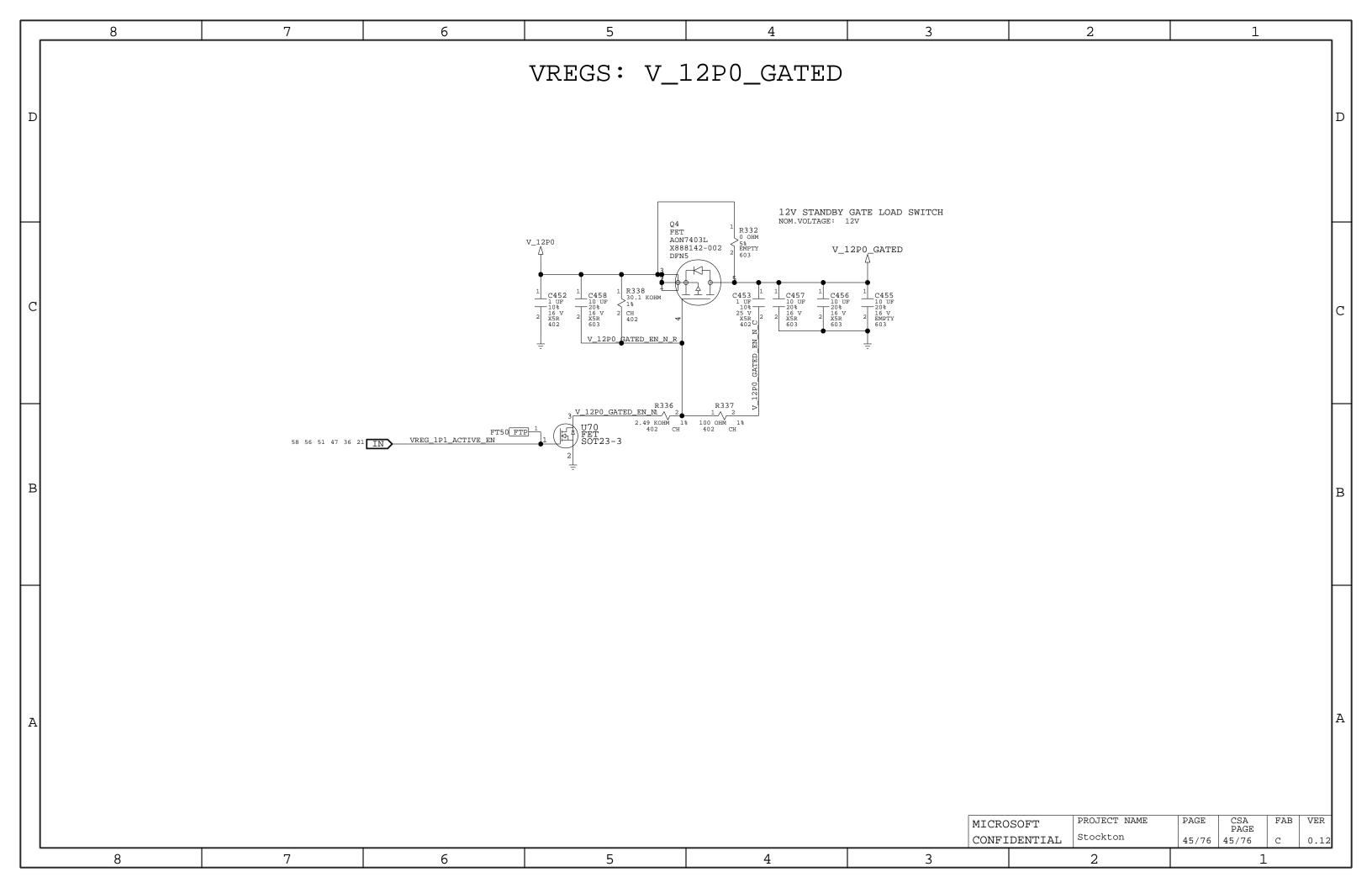


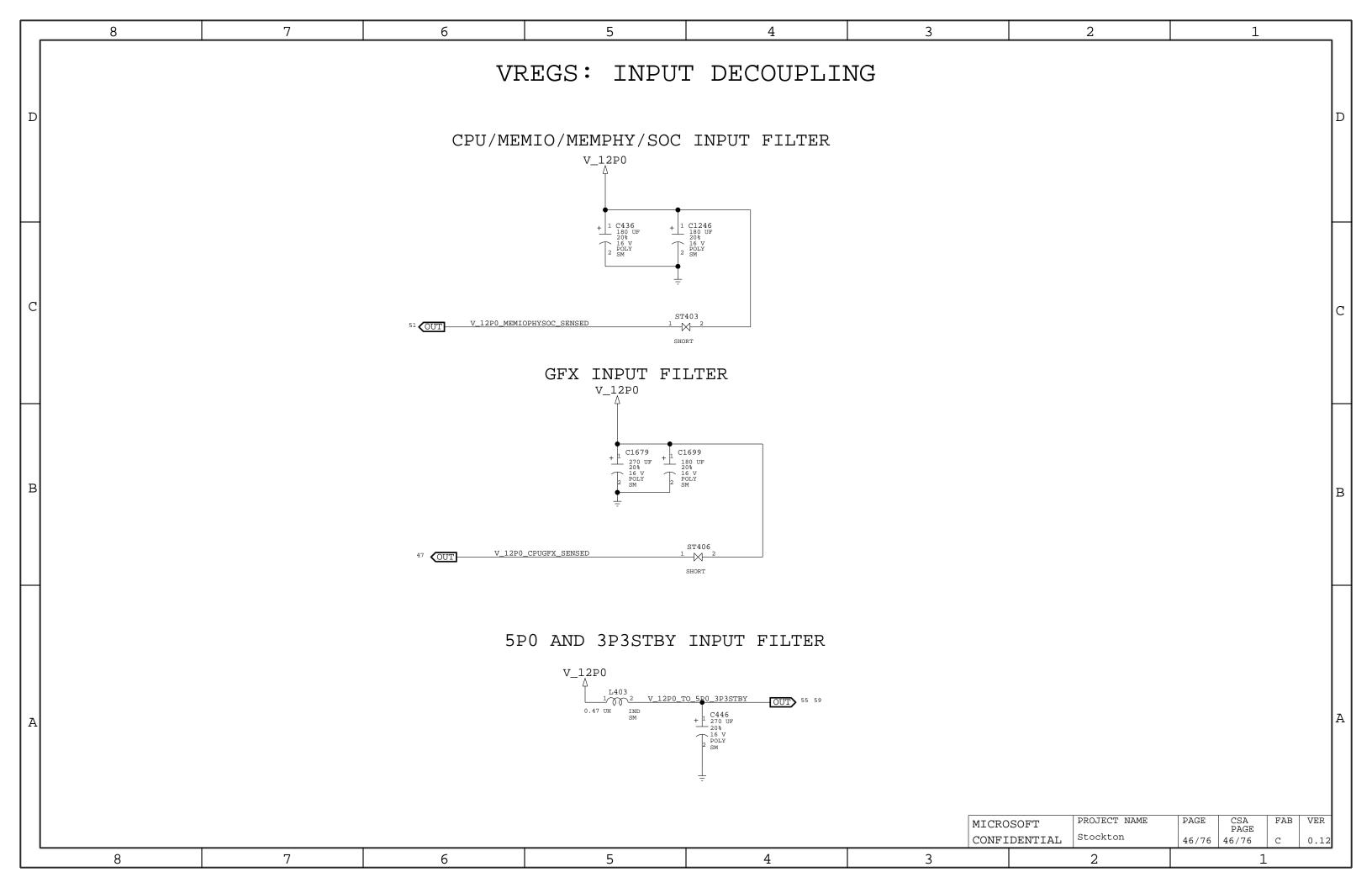


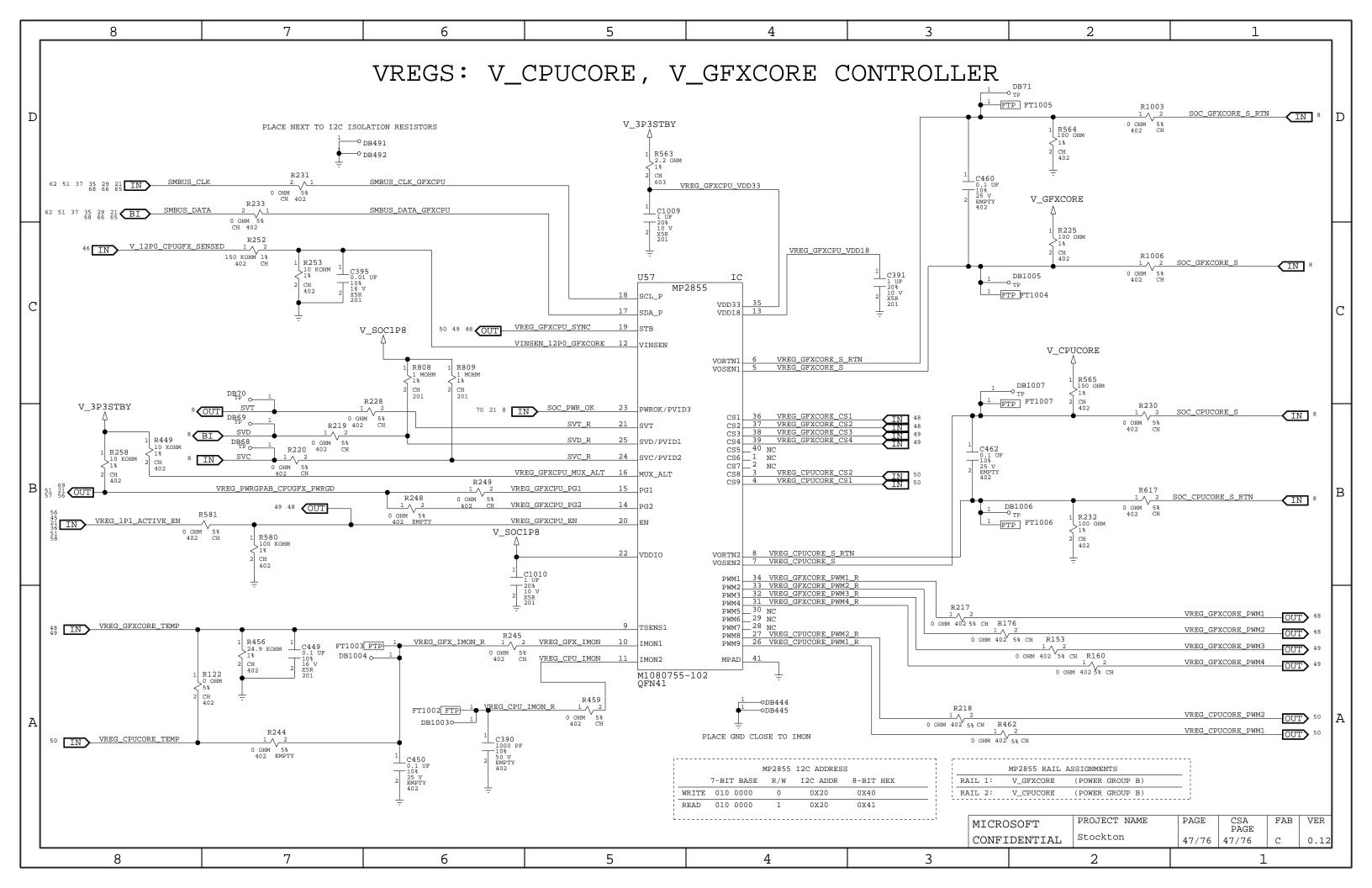


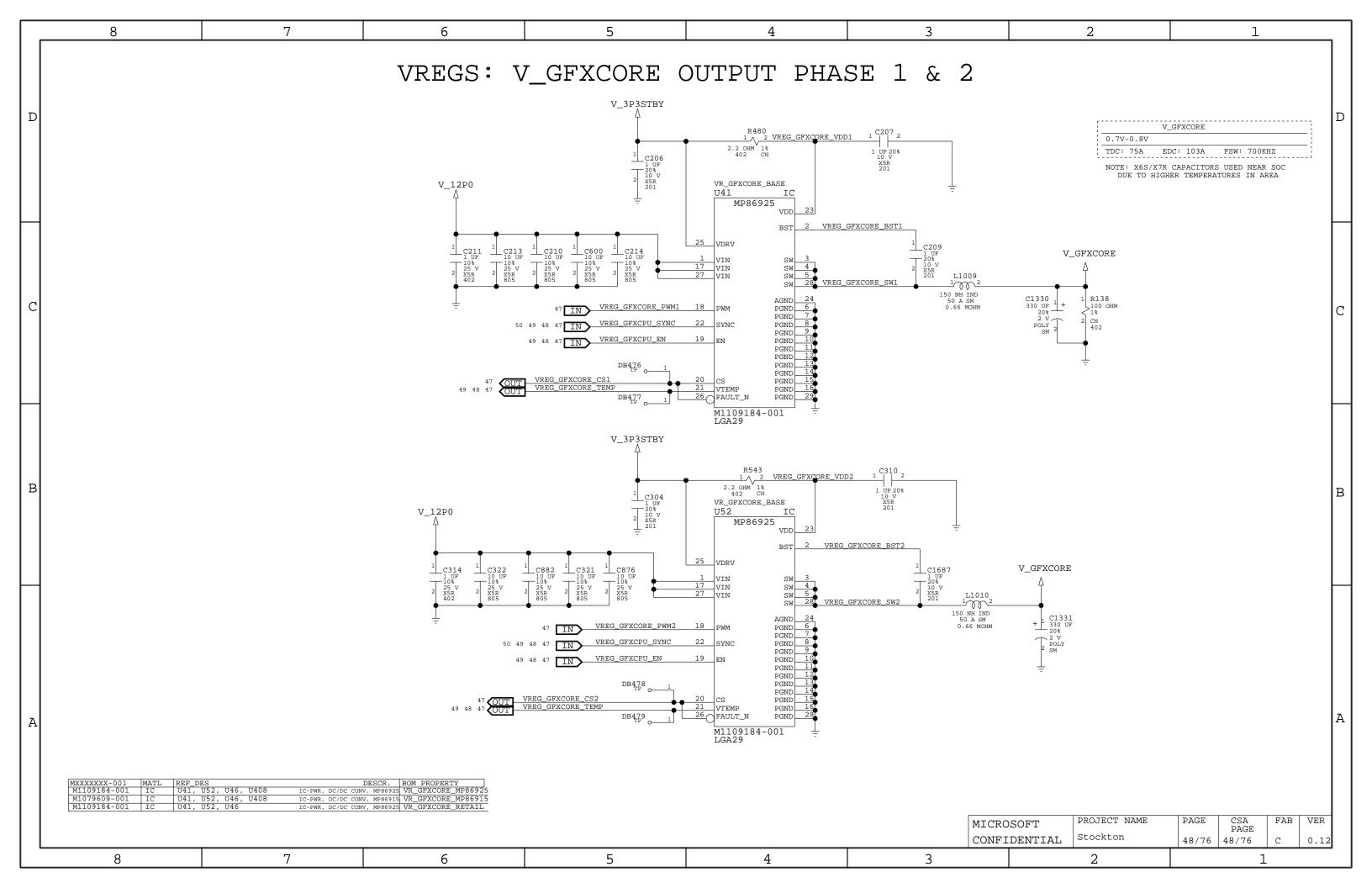


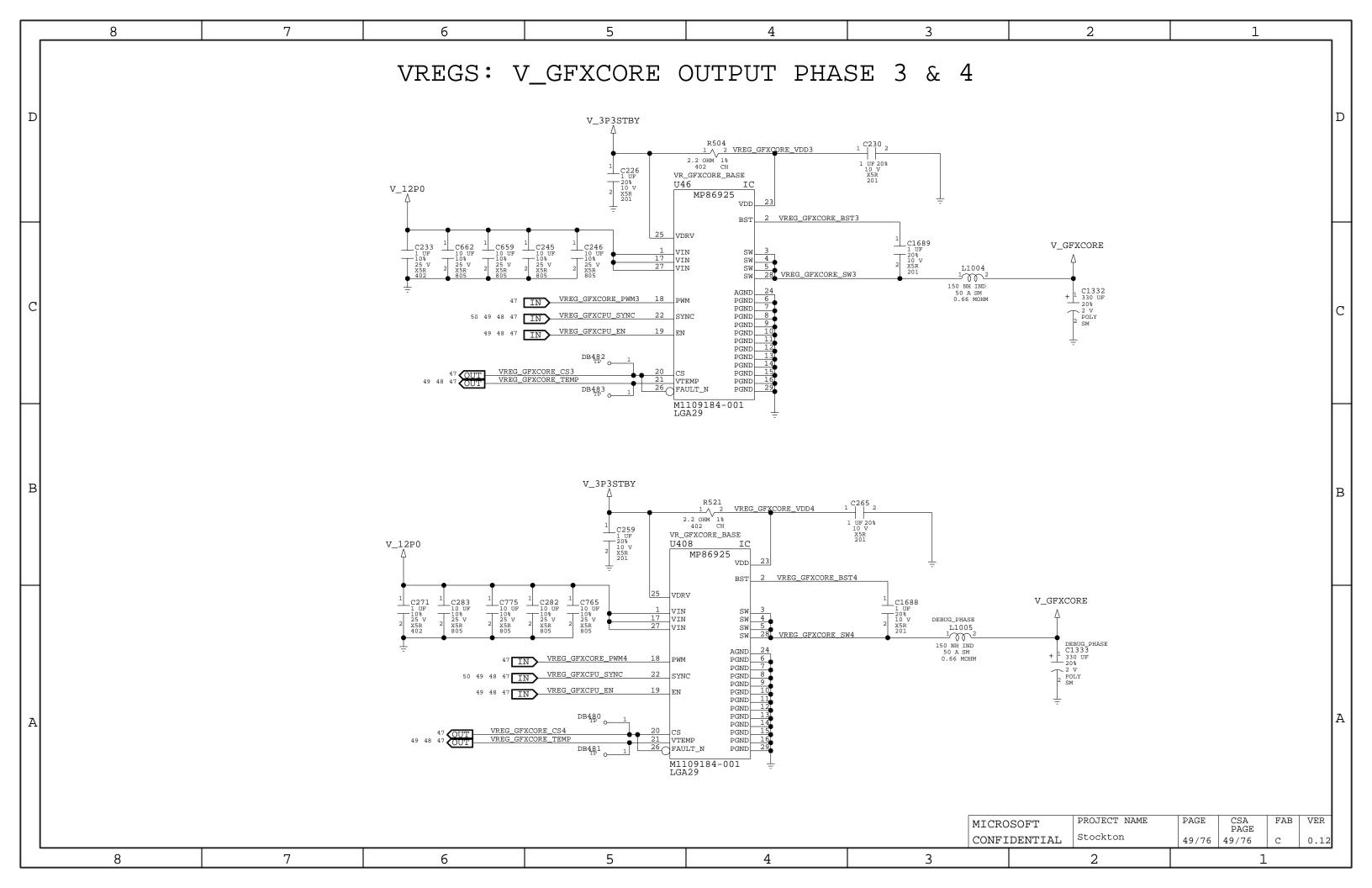


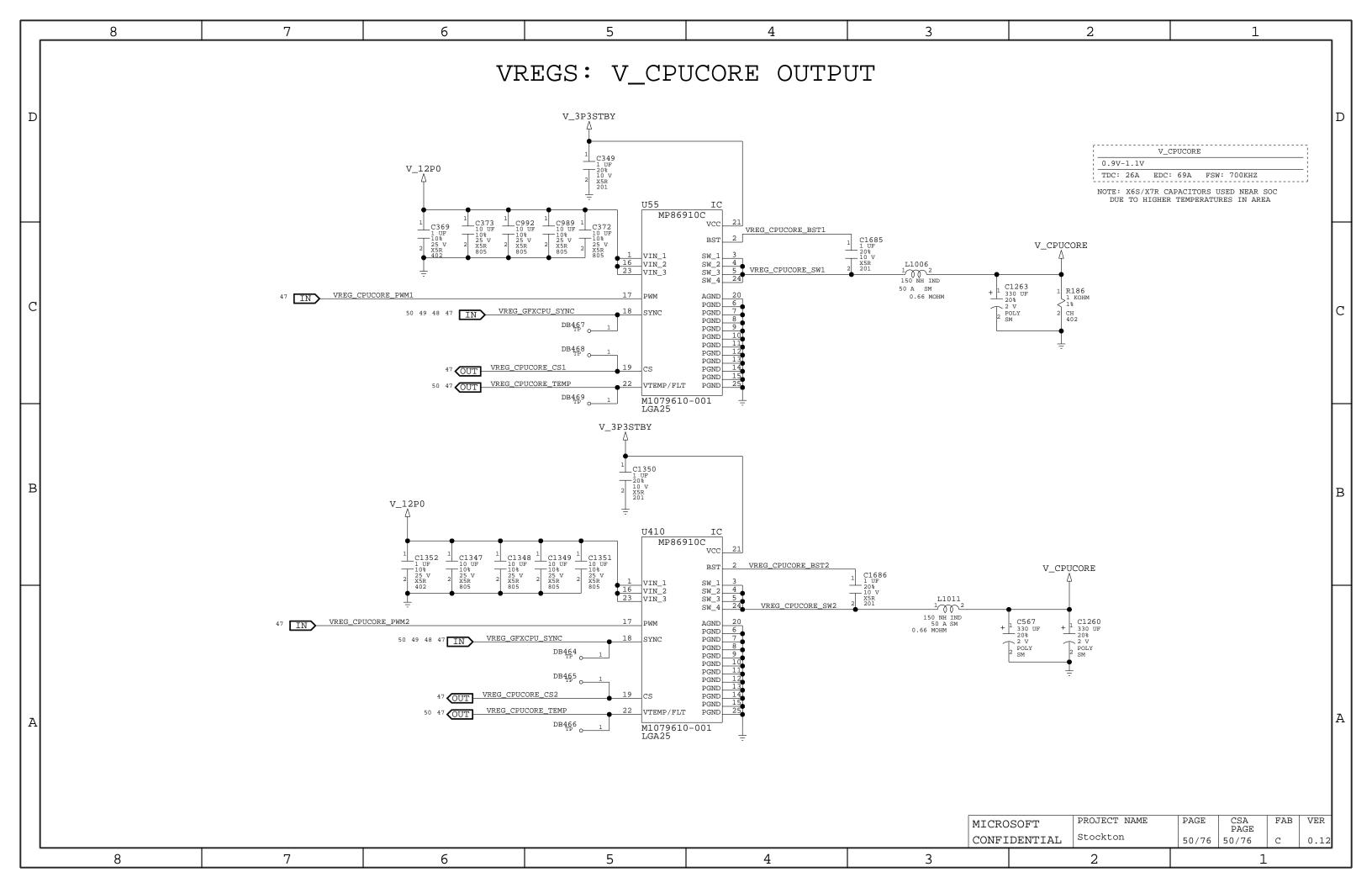


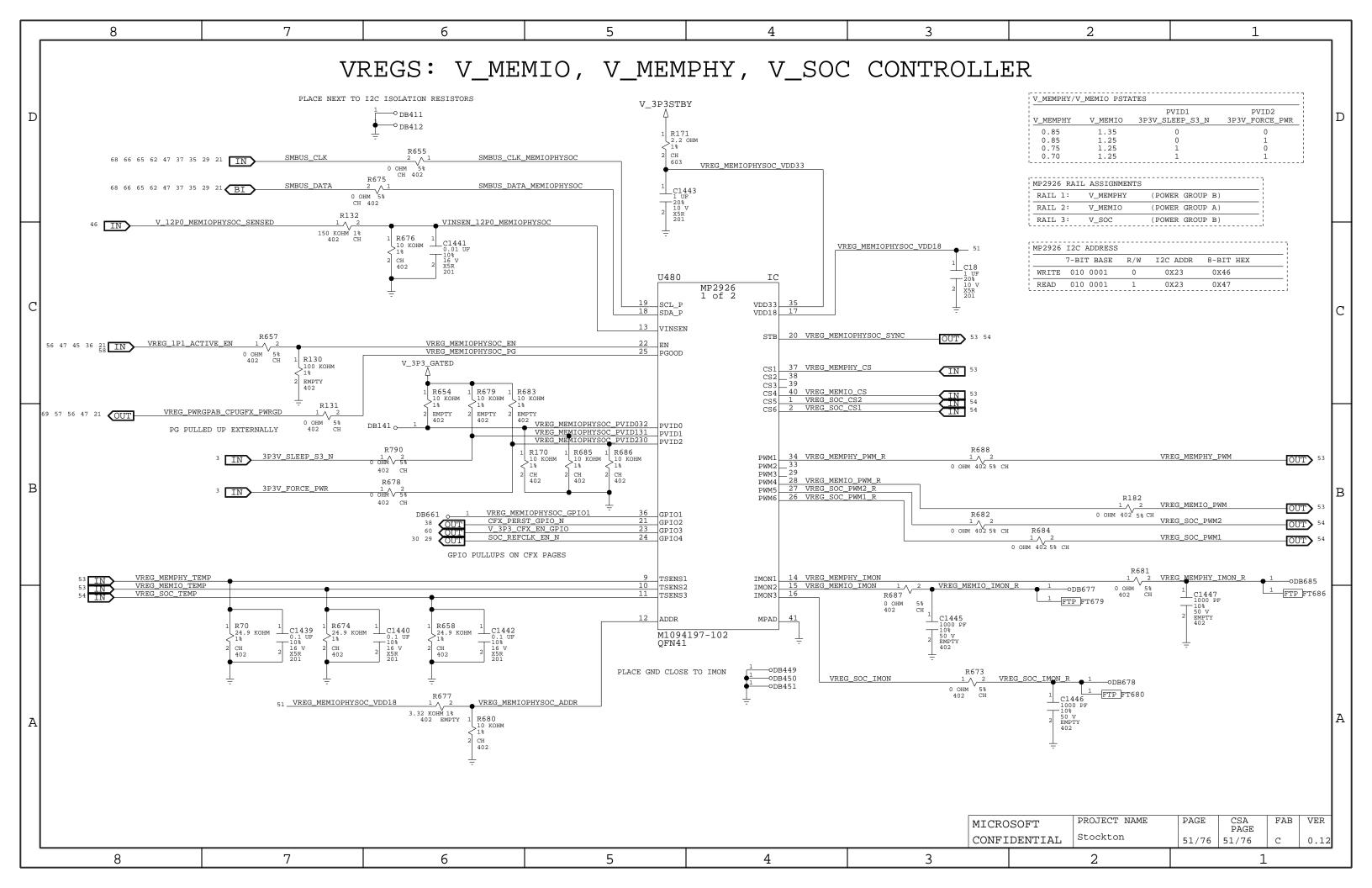


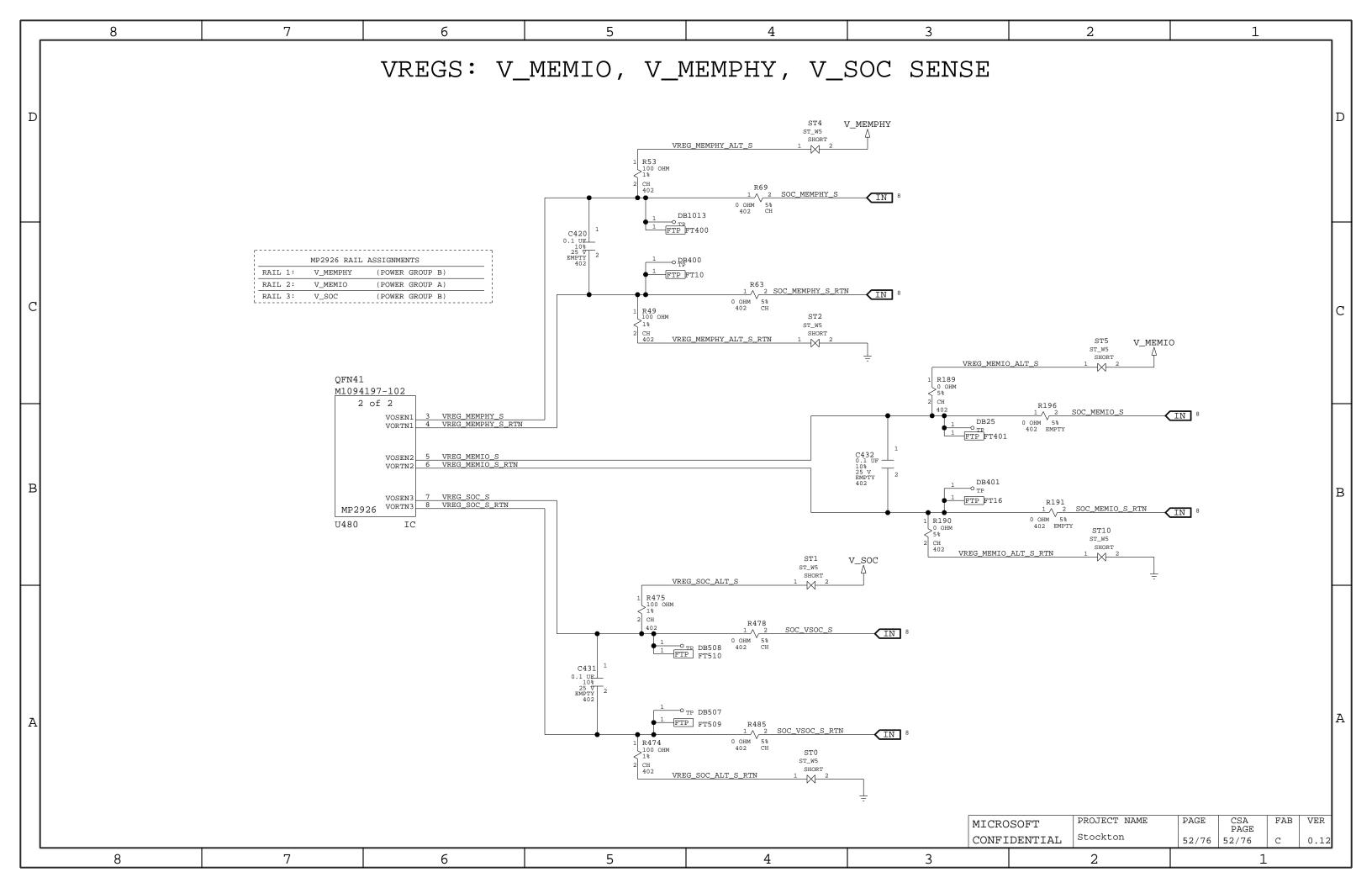


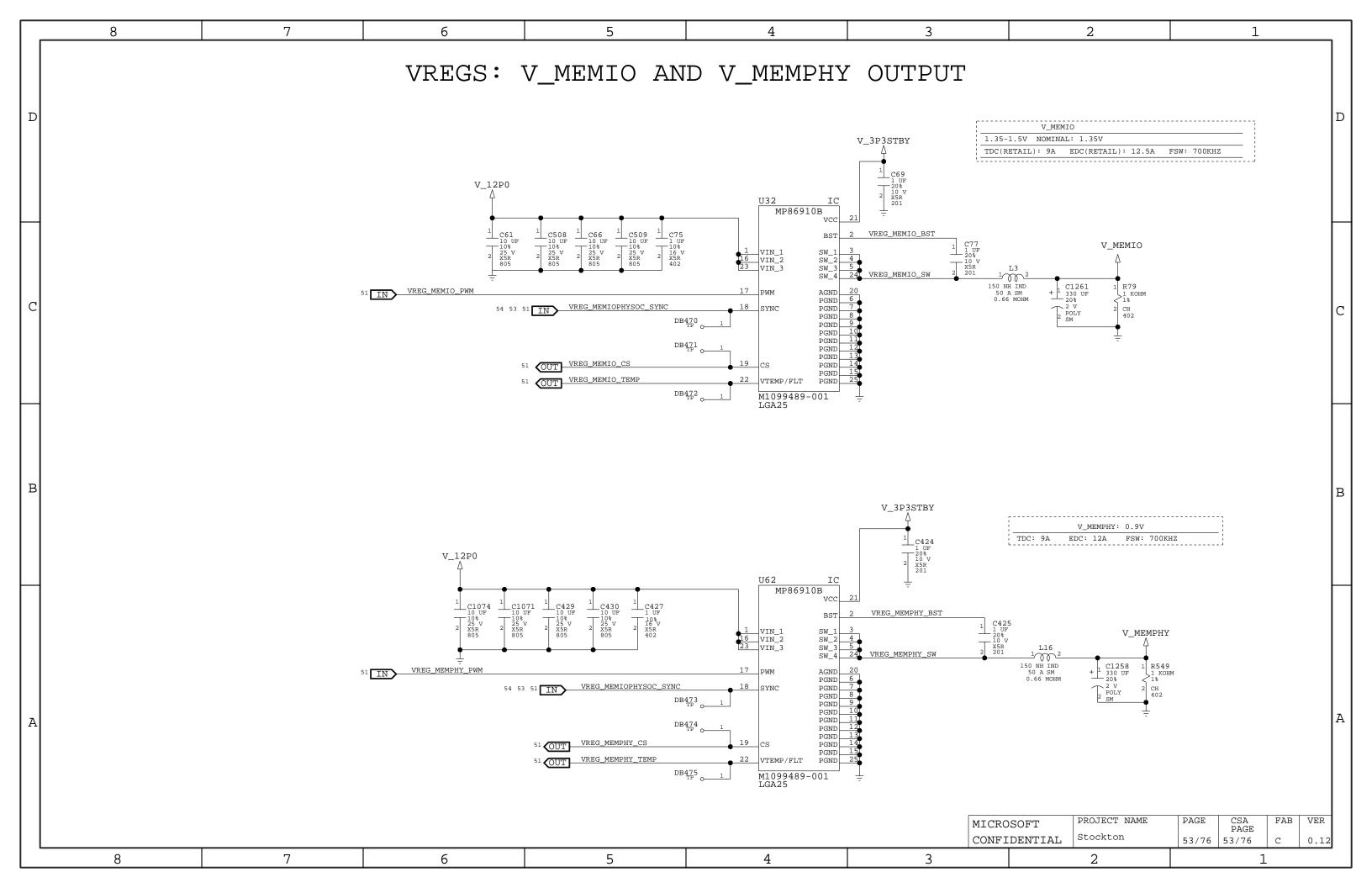


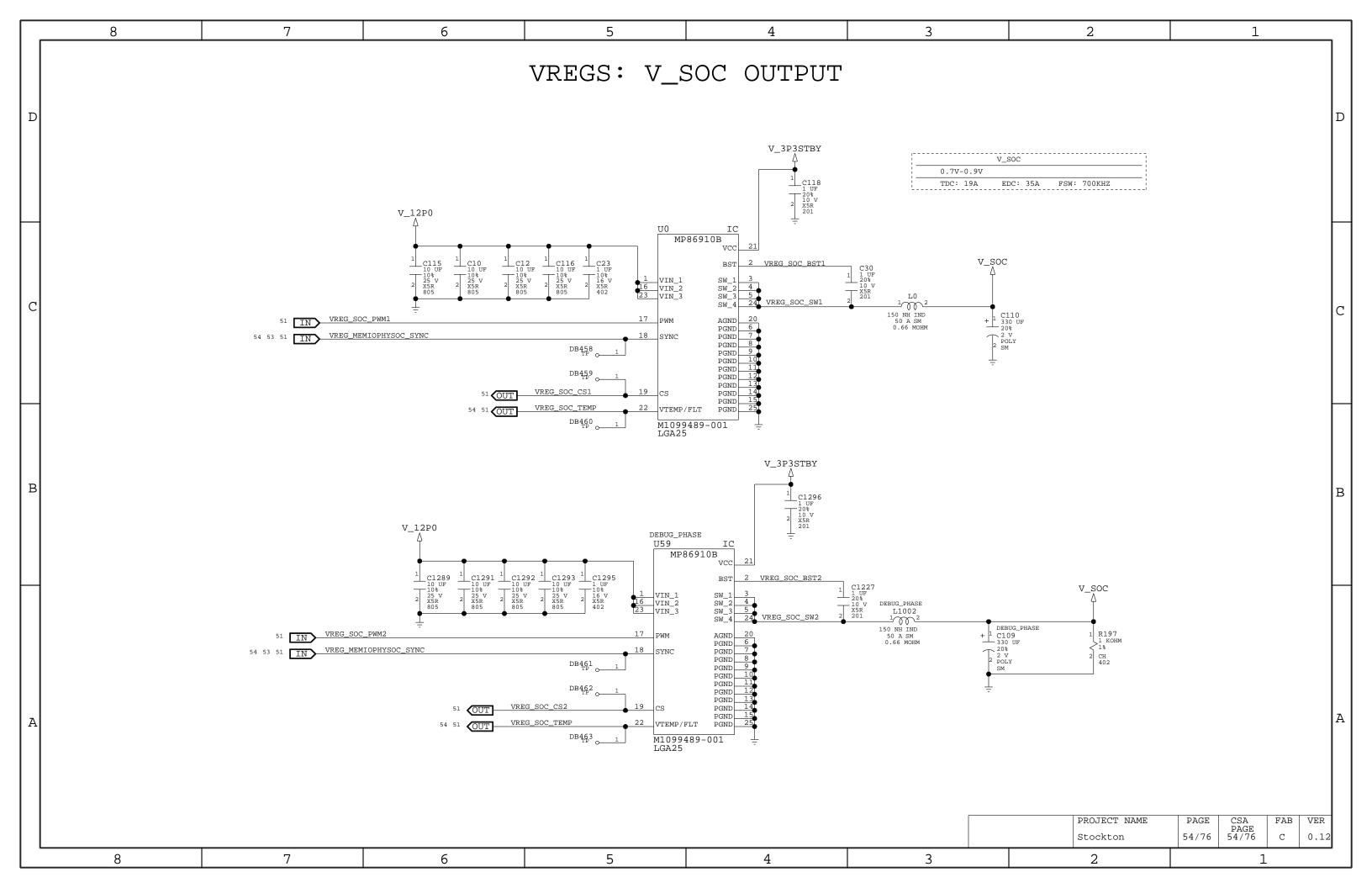


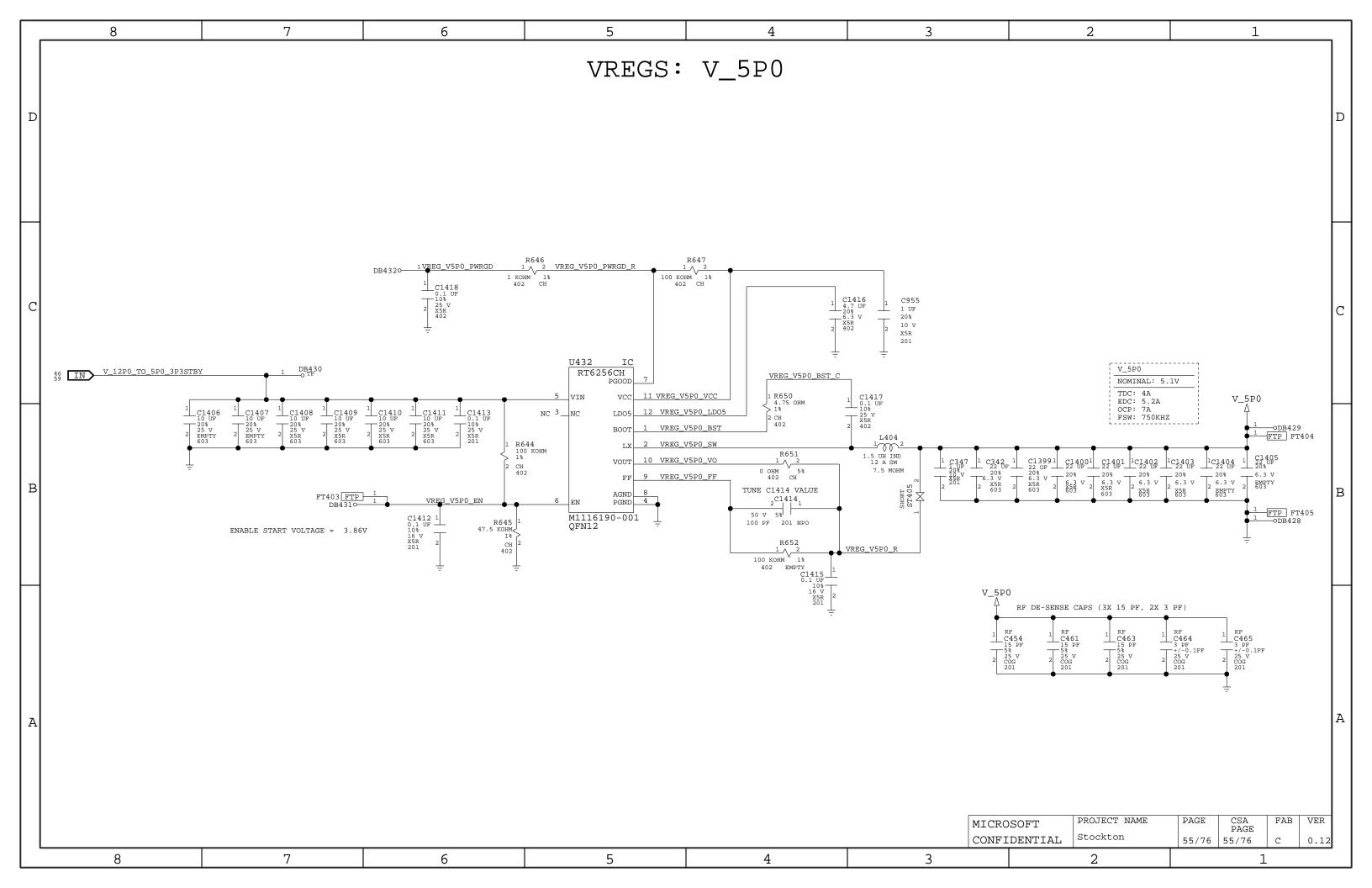


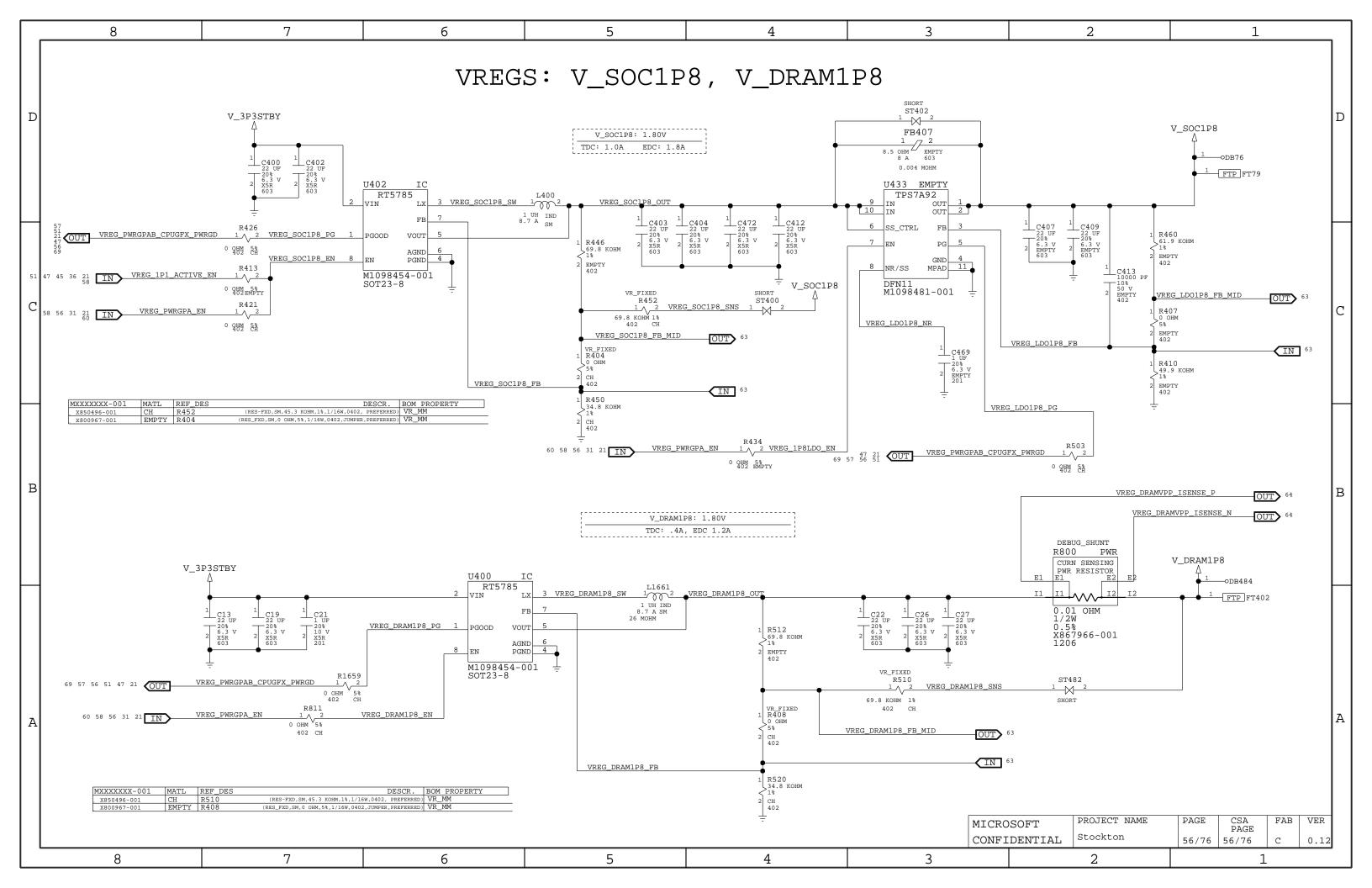


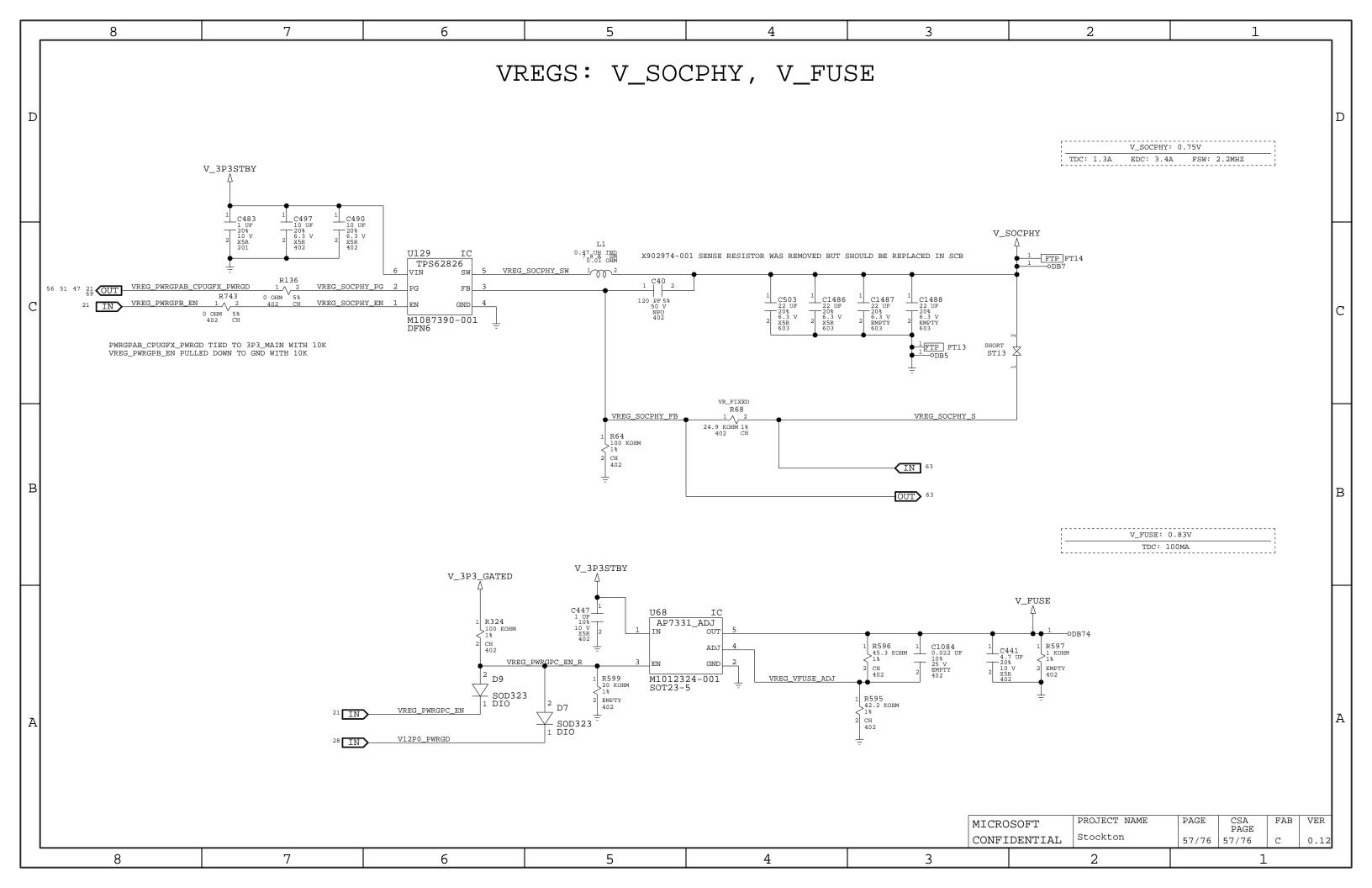


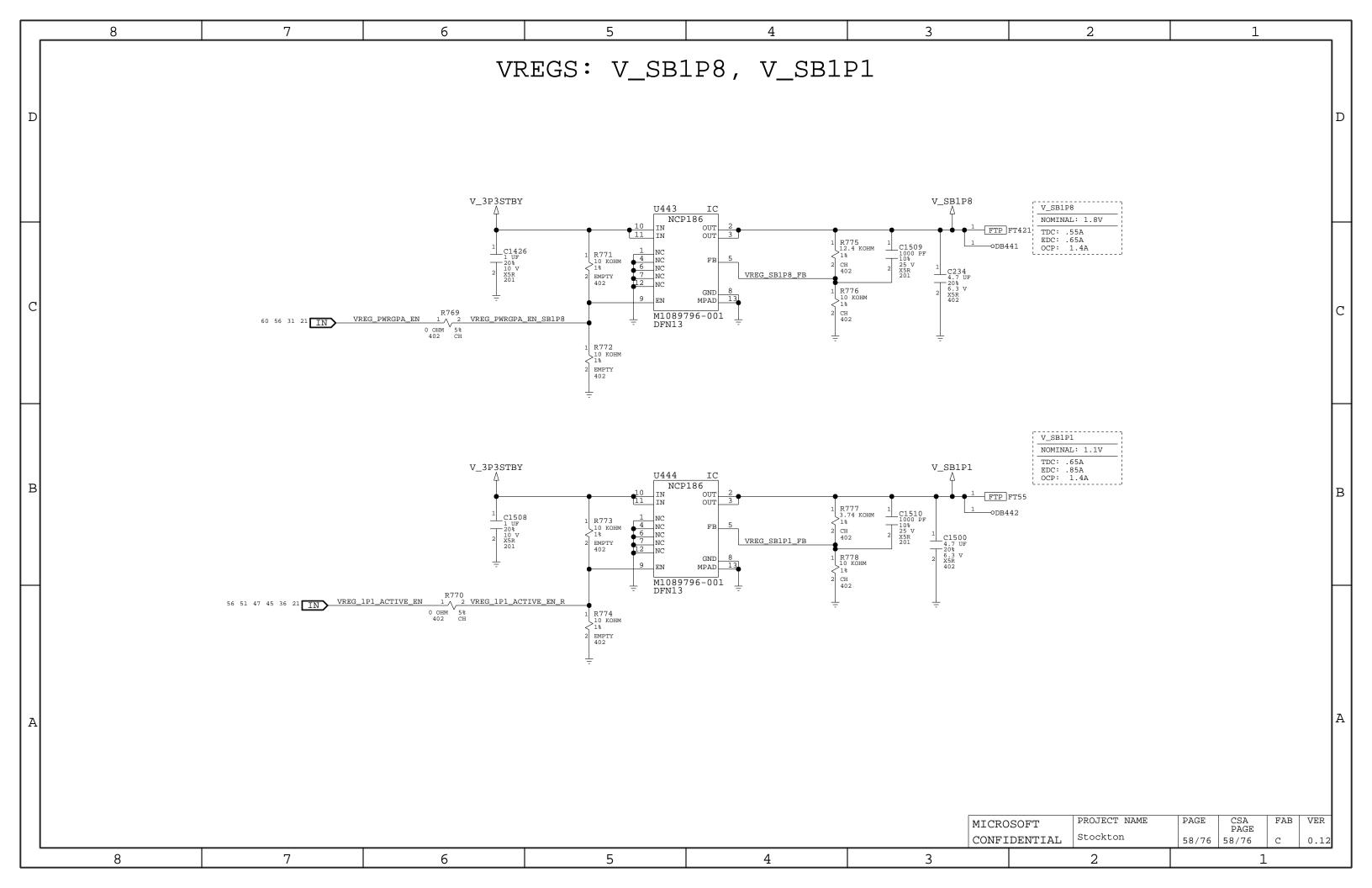


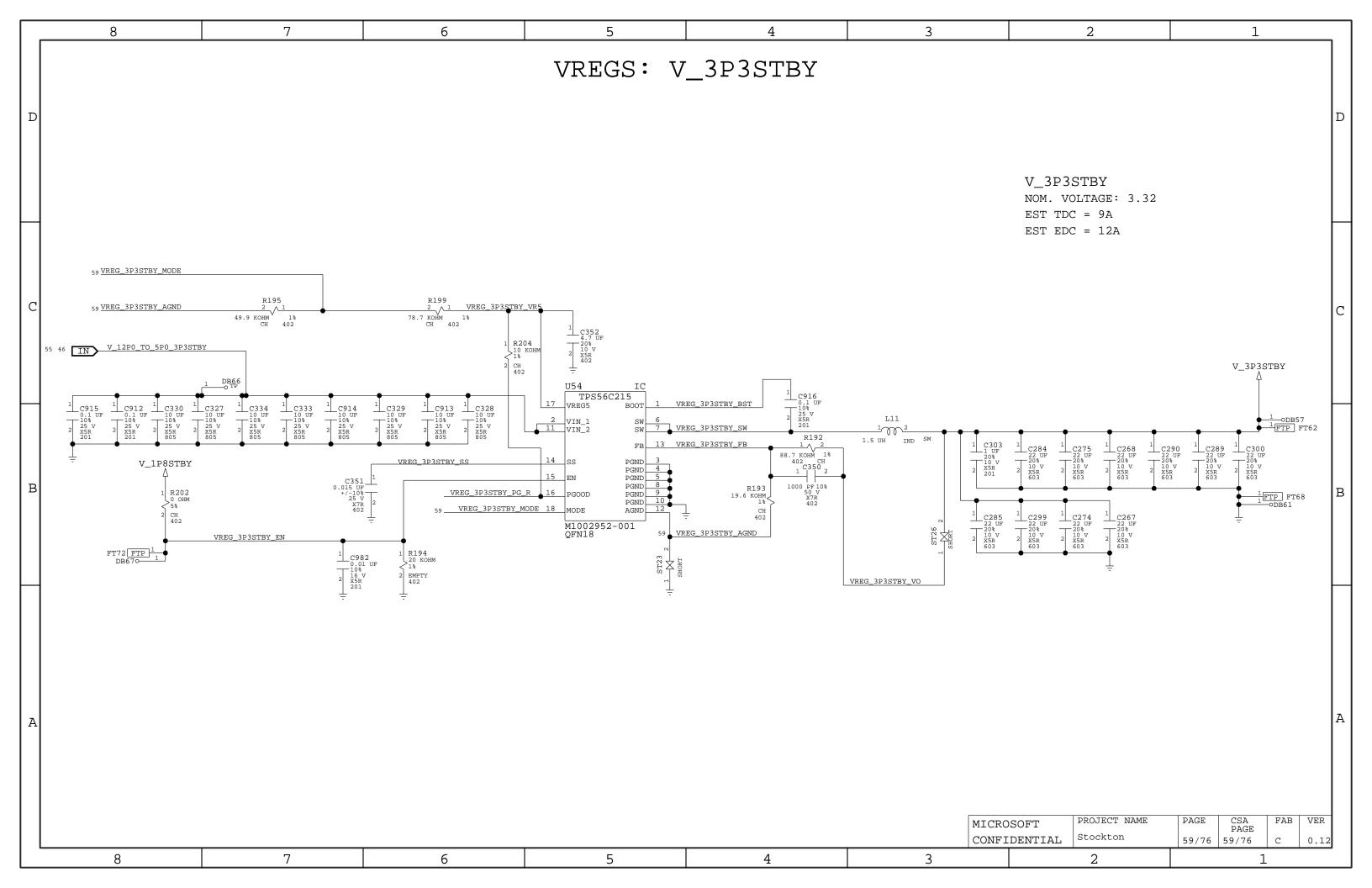


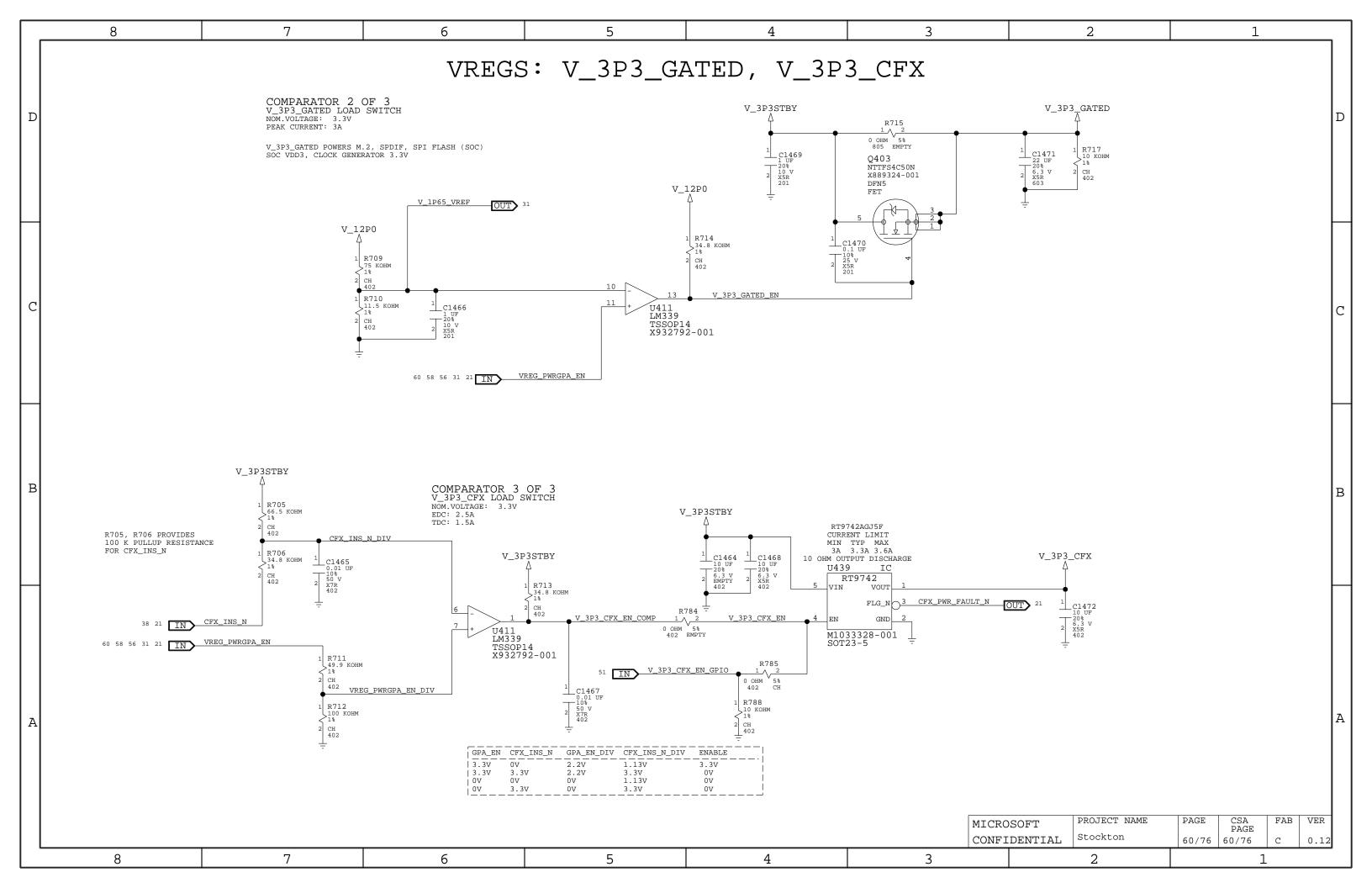


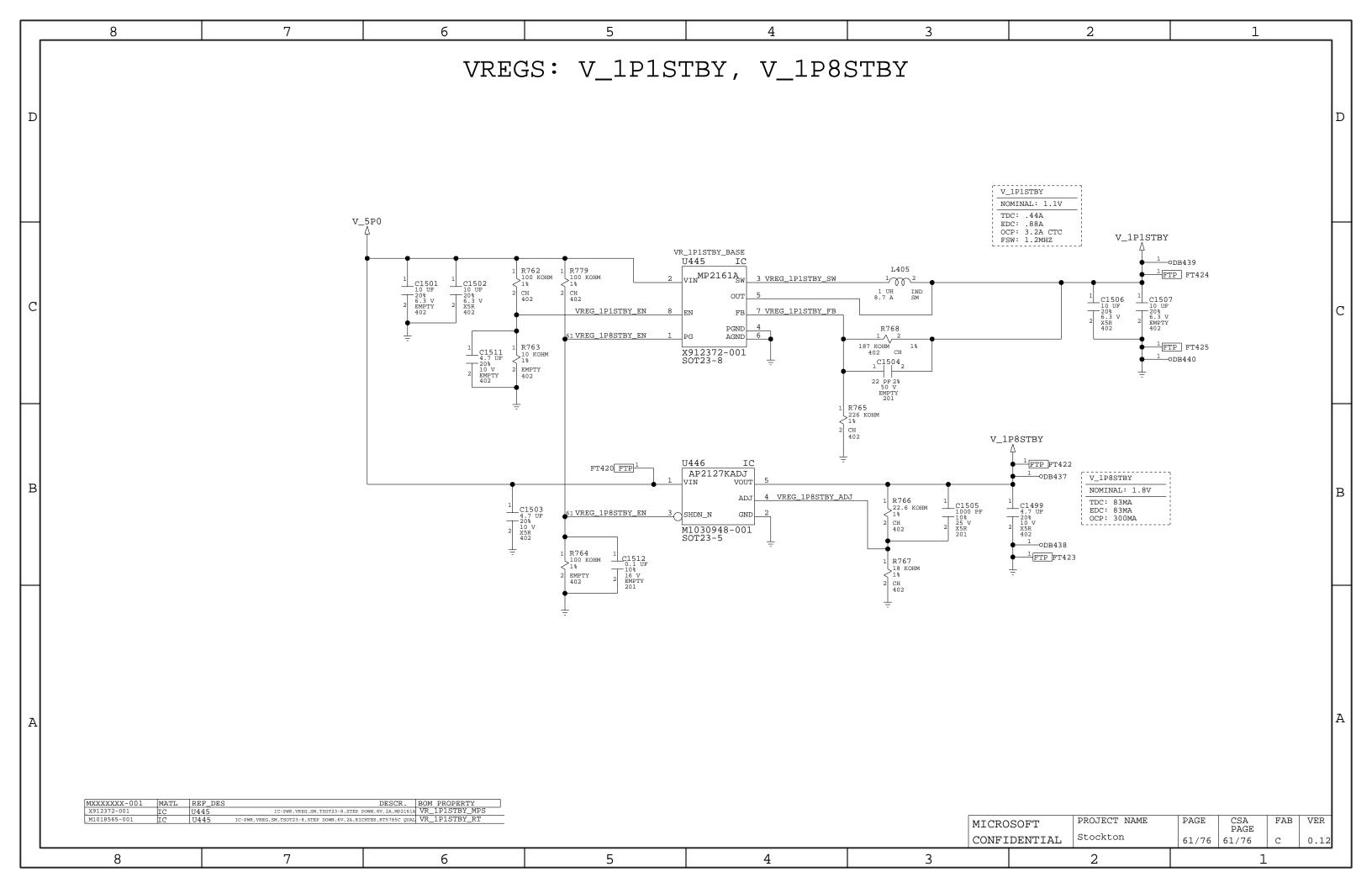


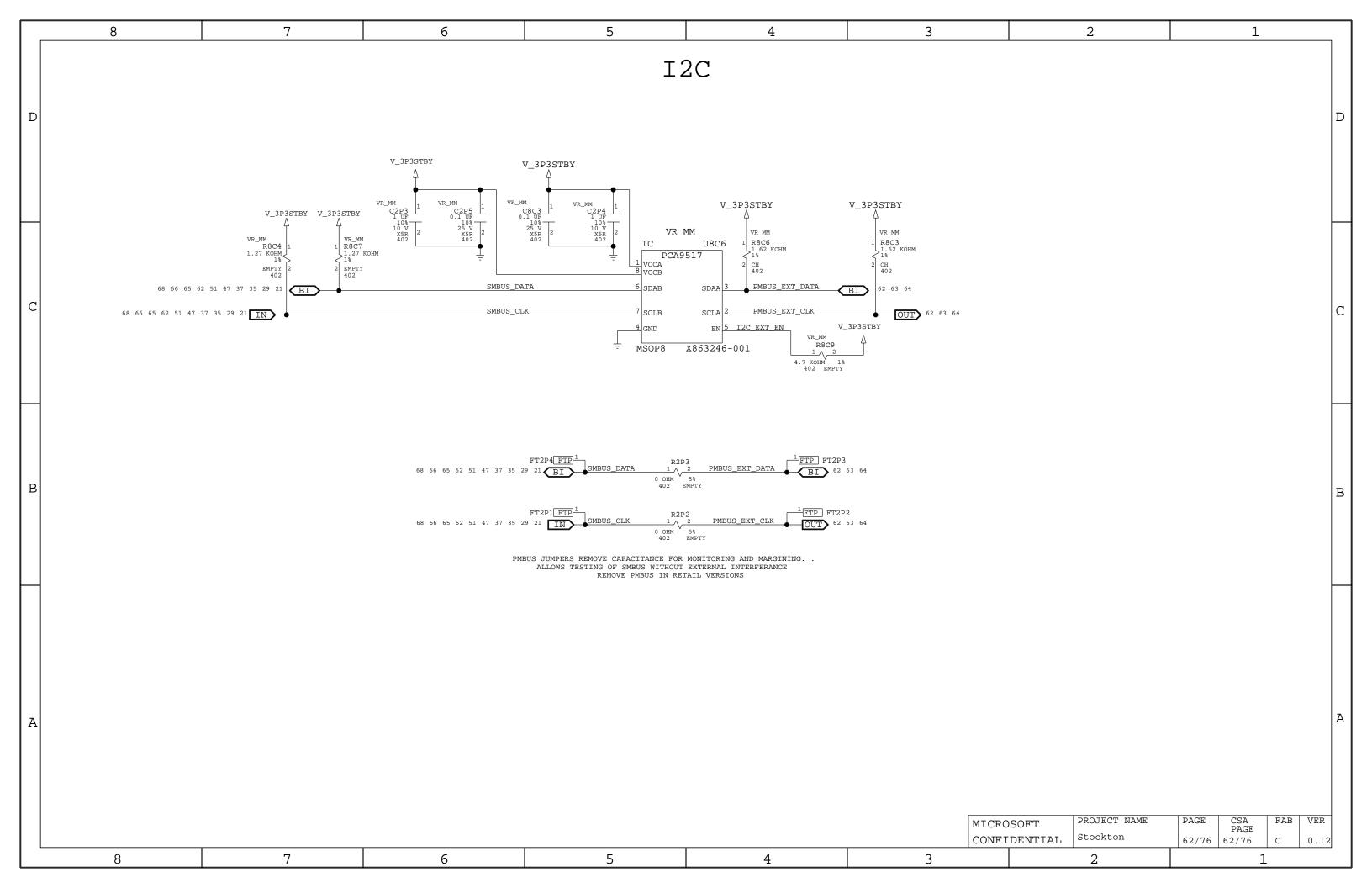


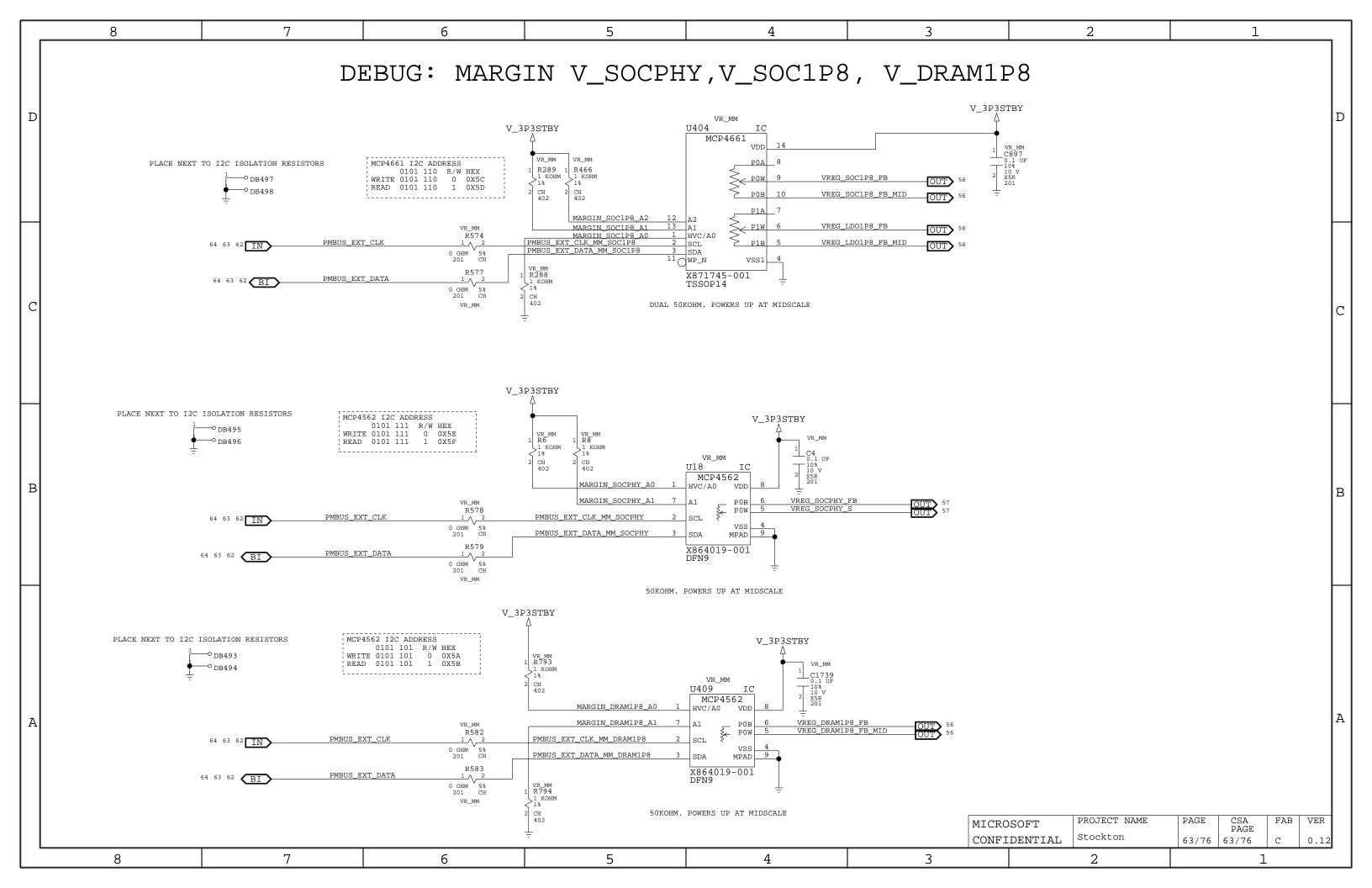


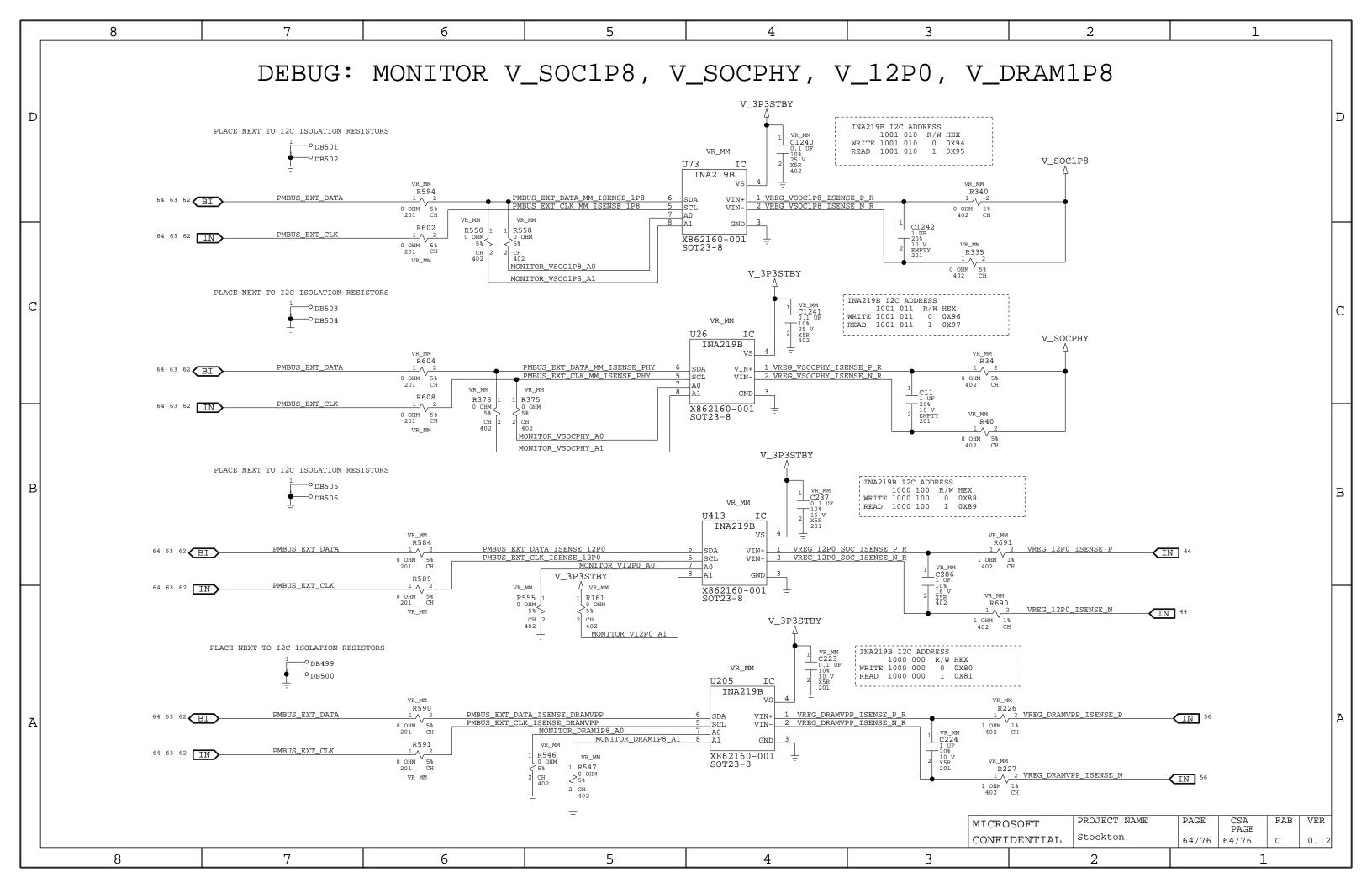


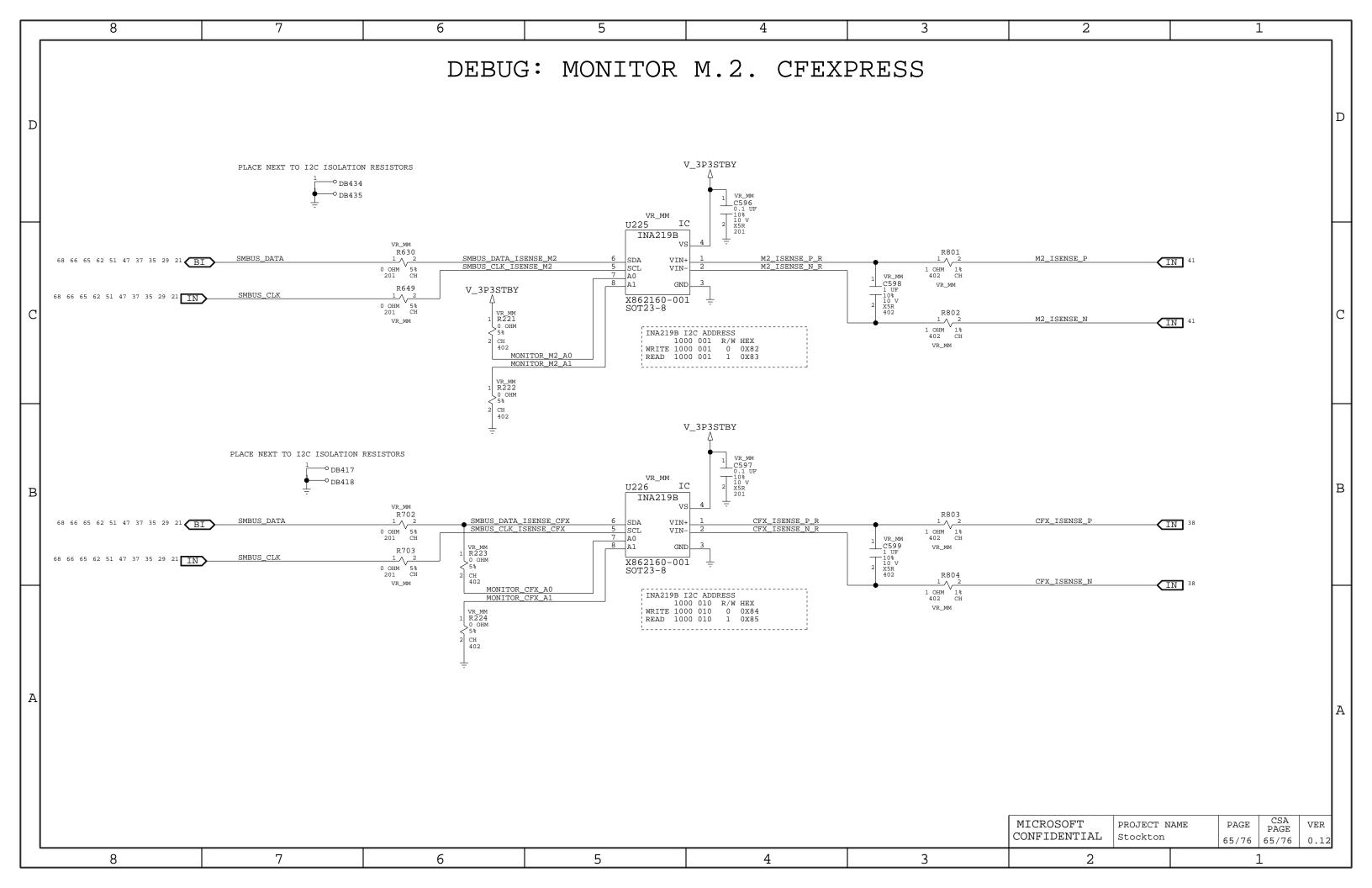


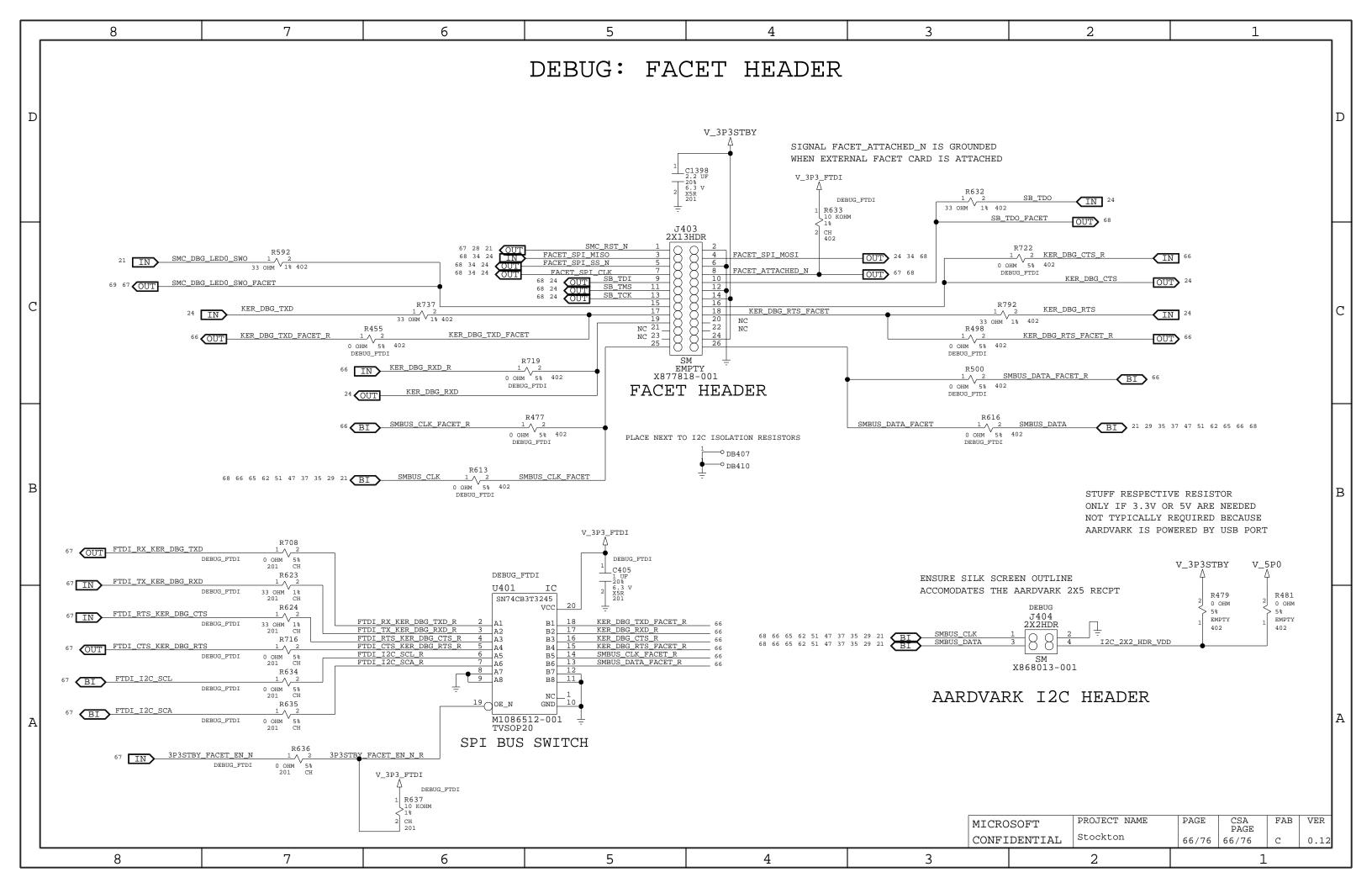


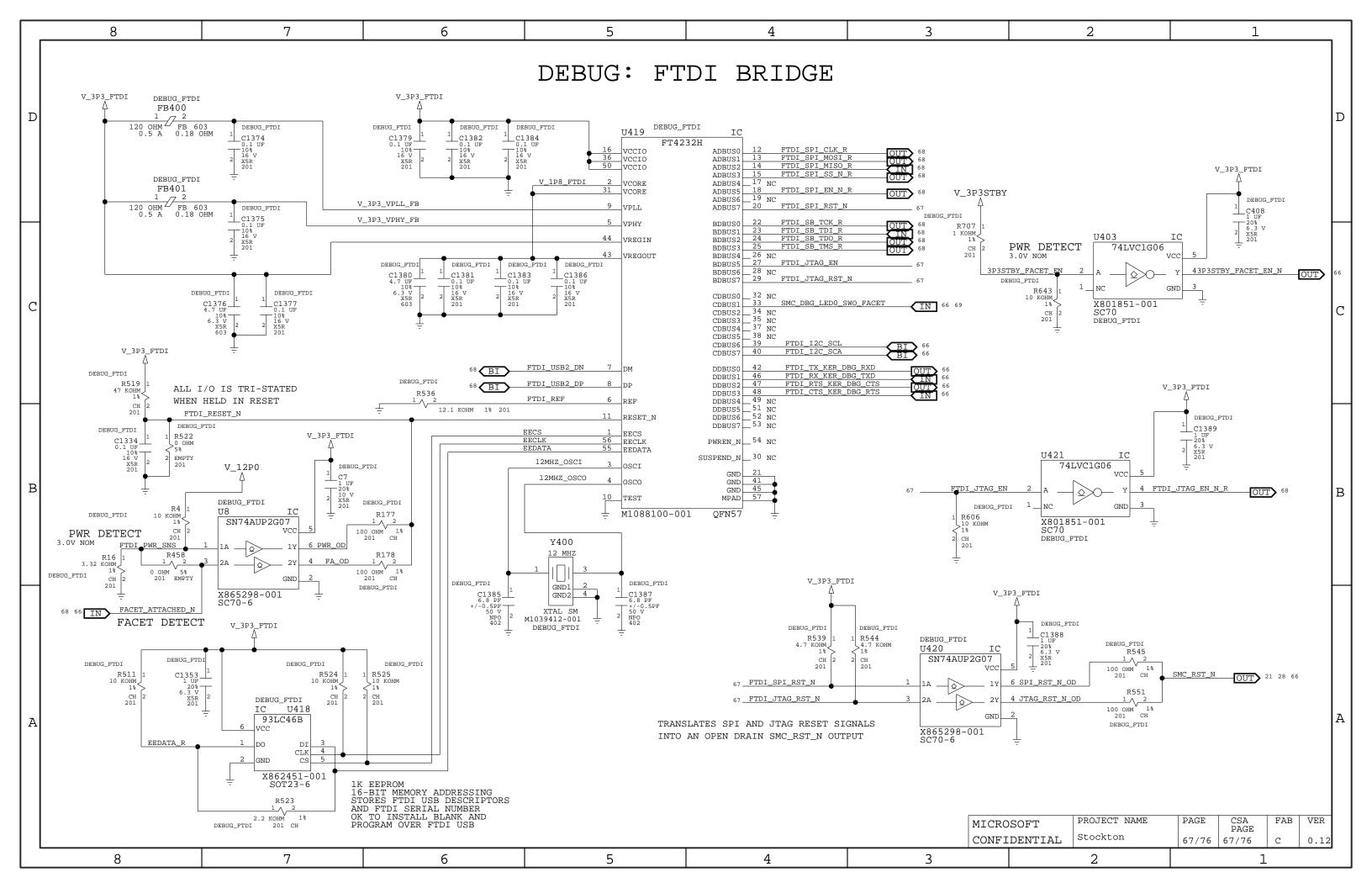


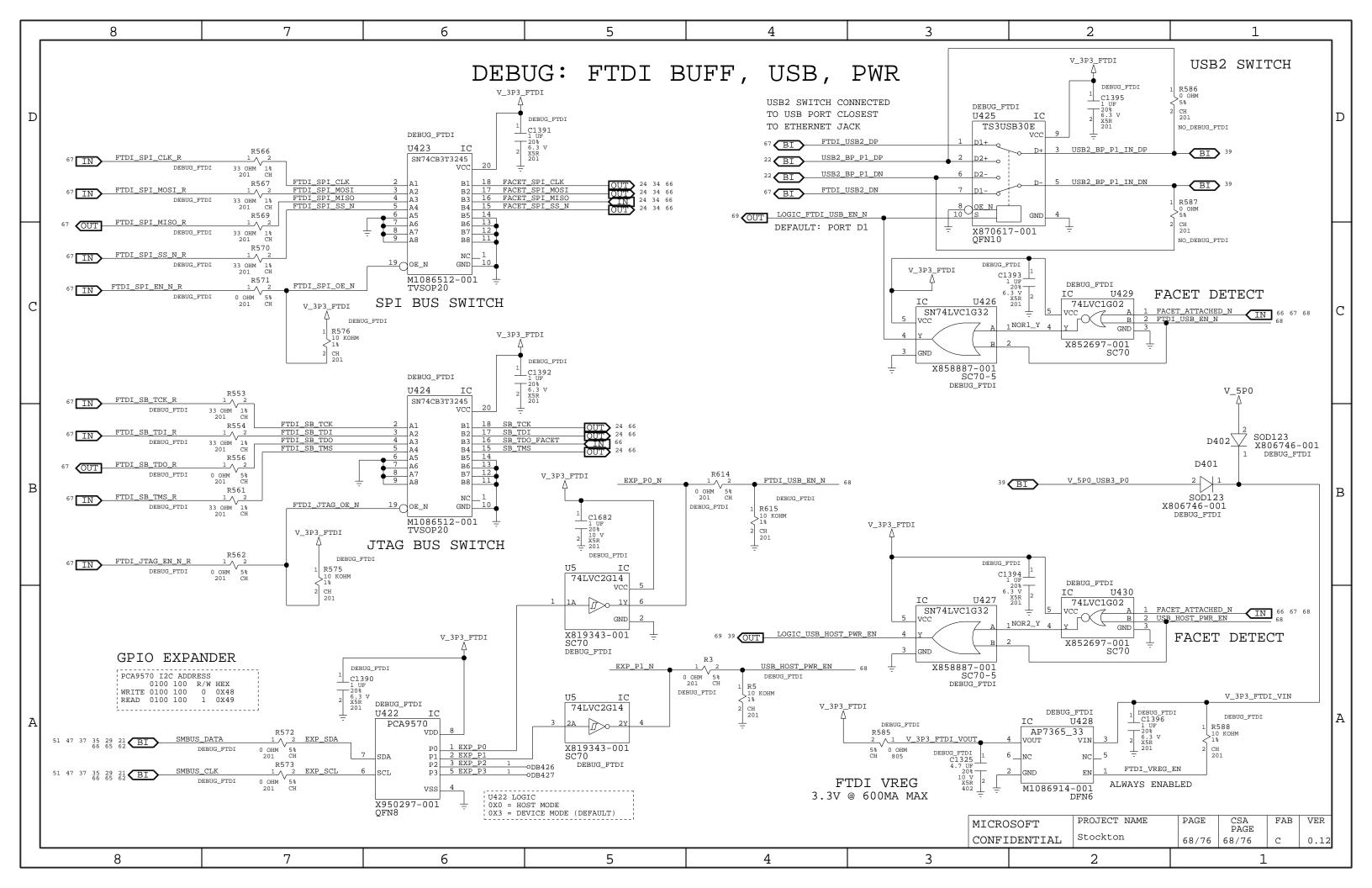


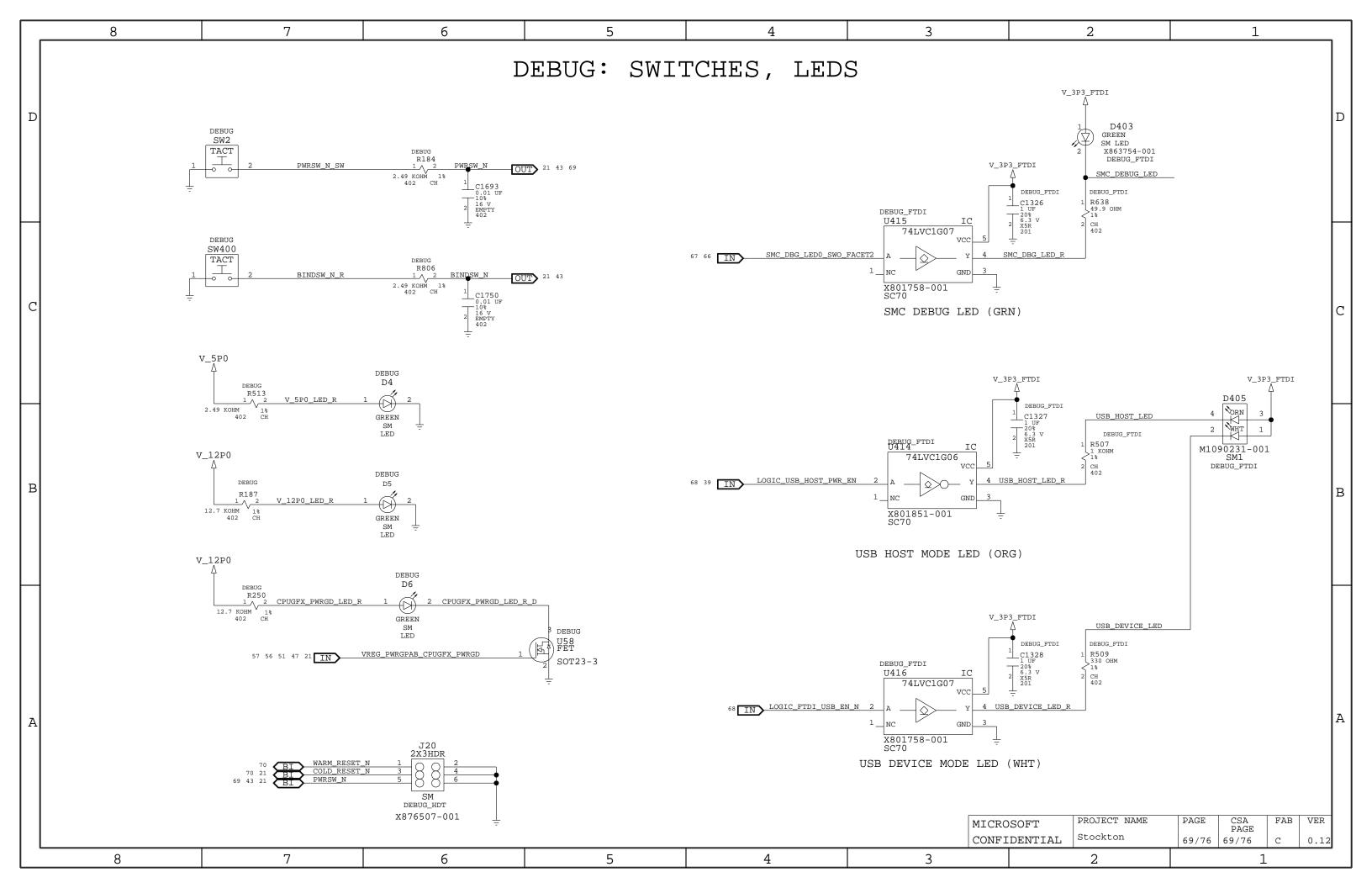


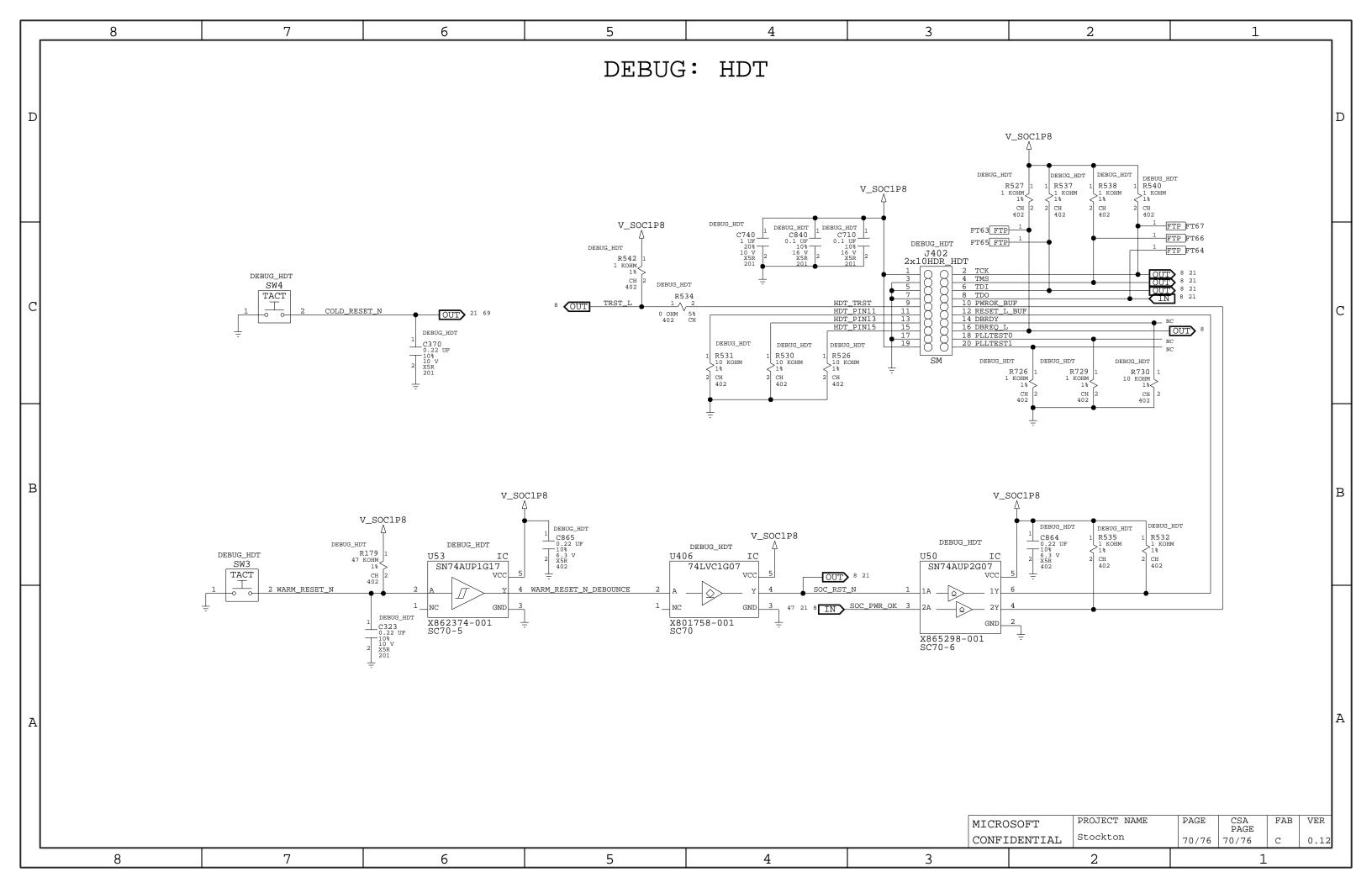


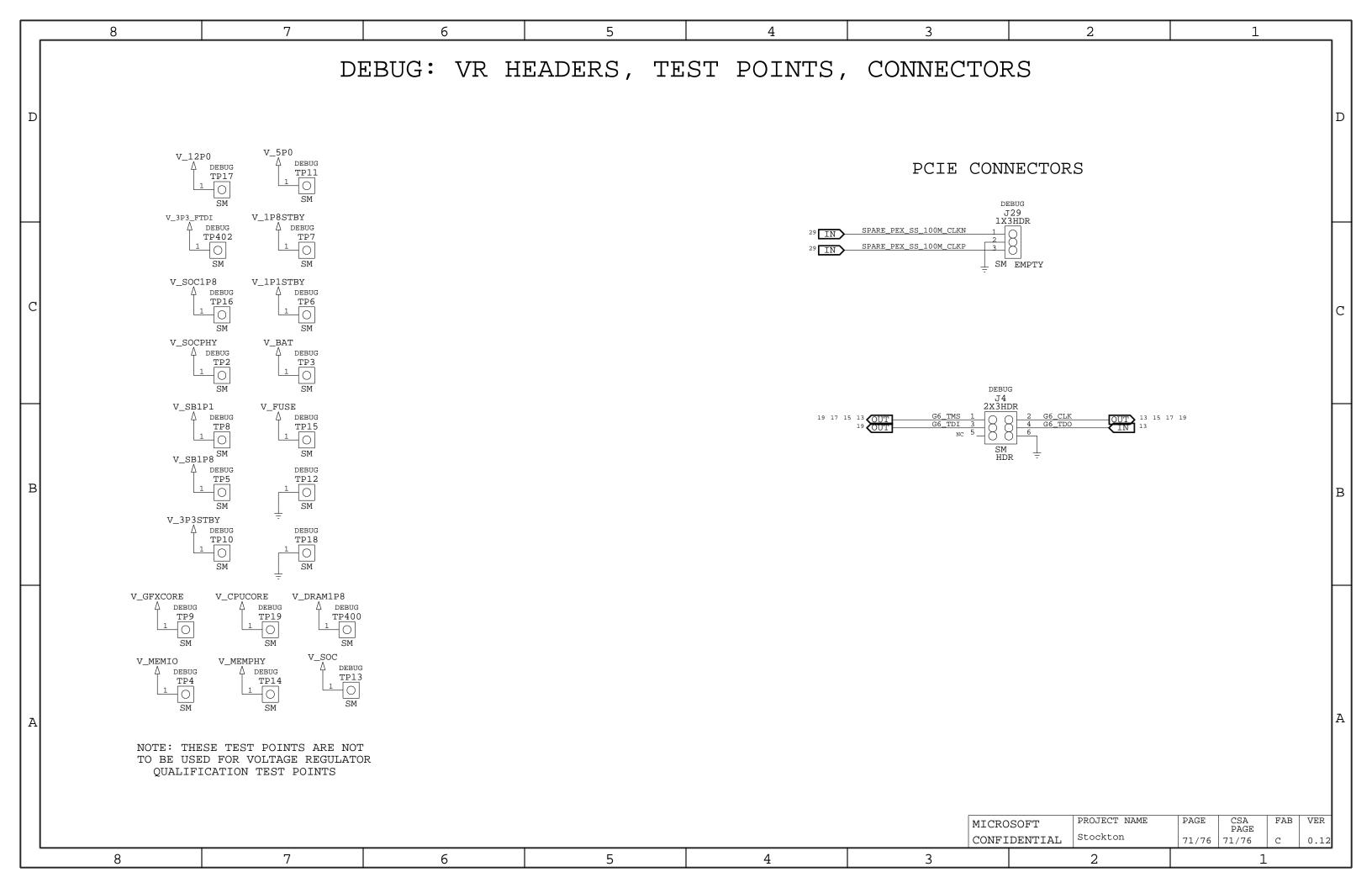


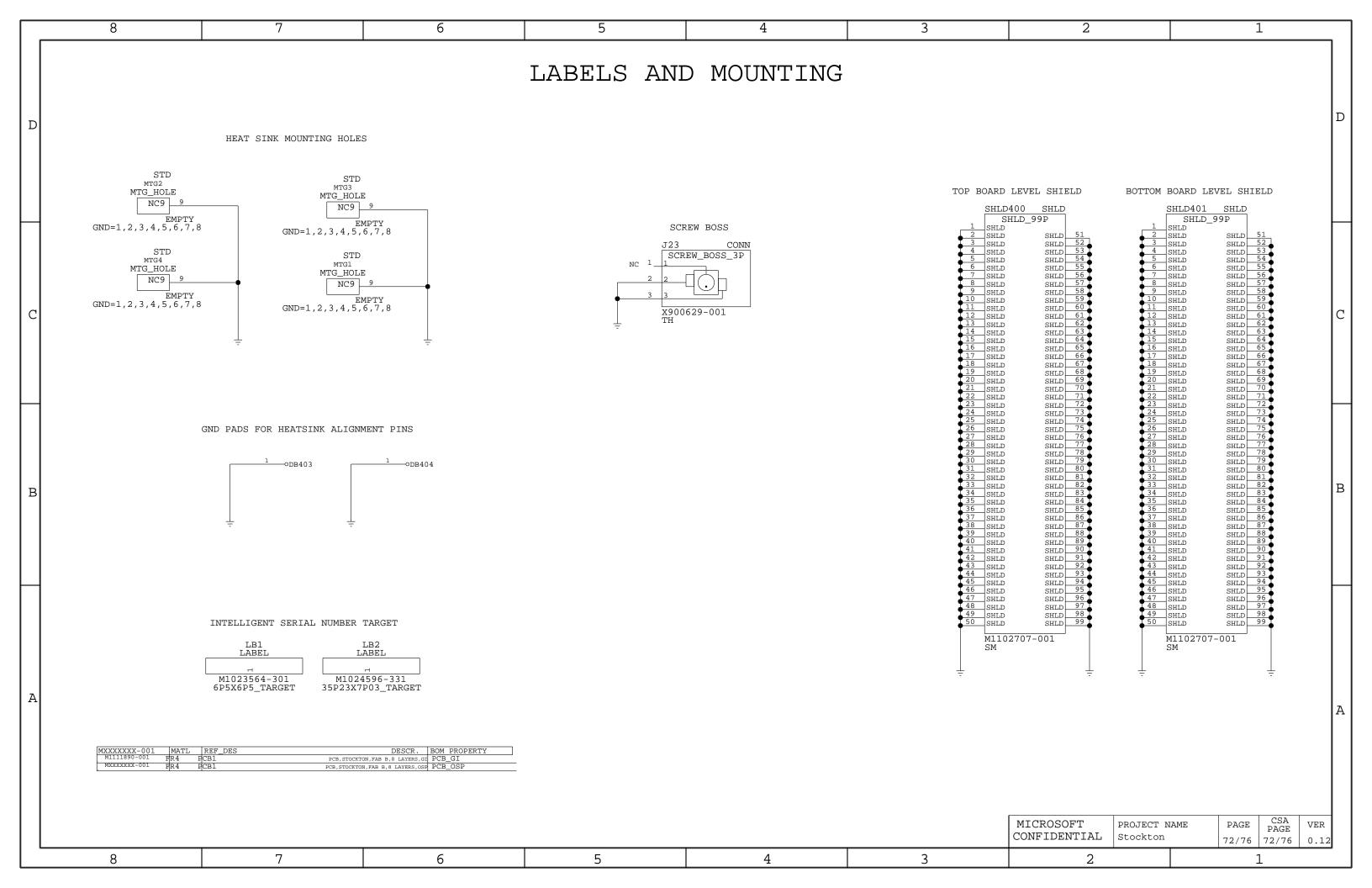












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D	BOM	DEFINITION									
	AUDIO	INCLUDES COMPONENTS FOR THE STANDARD AUDIO SOLUTION									
	AUDIO_PREM	INCLUDES COMPONENTS FOR THE I									
	COMMON	ALL COMPONENTS WITH NO BOM PE	·	JOHOTTON							-
	DEBUG	COMPONENTS REQUIRED FOR BRING									
	DEBUG_HDT	HDT-RELATED DEBUG COMPONENTS									
	DEBUG_SHUNT	COMPONENTS WHICH ARE ON DEBUG BOARDS, BUT ARE REMOVED/SHORTED ON RETAIL									_
	EMMC_BASE	DUMMY PLACE HOLDER FOR EMMC DEVICE & RESISTORS. NEVER USE THIS IN THE RECIPE FILE. SELECT ONE OF THESE INSTEAD: EMMC_HYNIX_16NM, EMMC TOSHIBA_15NM, EMMC SAMSUNG_14NM									-
	EMMC_HYNIX_16NM	HYNIX EMMC DEVICE HYNIX EMMC DEVICE									—
	EMMC_SAMSUNG_14NM	SAMSUNG EMMC DEVICE									_
	EMMC_TOSHIBA_15NM	TOSHIBA EMMC DEVICE									_
C	SANTO_BASE	DUMMY PLACE HOLDER FOR SANTO SB. NEVER USE THIS IN THE RECIPE FILE. USE ONE OF THESE INSTEAD: SANTO_DEV OR SANTO_RETAIL									C
	SANTO_DEV	DEBUG VERSION OF SANTO SB									
	SANTO_RETAIL	RETAIL VERSION OF SANTO SB									
	M2_ONLY	POPULATE TO SUPPORT AN M.2 INTERFACE									
	NO_M2	POPULATE WHEN THERE IS NO M2. INTERFACE									
	PCB_GI	FAB TYPE: GOLD									
	PCB_OSP	FAB TYPE: ORGANIC SOLDERABILITY PRESERVATIVE GREEN SOLDERMASK									
	PCB_OSP_BLACK	FAB TYPE: ORGANIC SOLDERABILITY PRESERVATIVE BLACK SOLDERMASK									
	RTC_RETAIL	RTC CIRCUIT IMPLEMENTATION FOR RETAIL BOARDS									
	RTC_XDK	RTC CIRCUIT IMPLEMENTATION FOR XDK BOARDS									
	SOC_BASE	DUMMY PLACE HOLDER FOR SOC. NEVER USE THIS IN THE RECIPE FILE. SELECT ONE OF THESE INSTEAD: EMMC_HYNIX_16NM, EMMC TOSHIBA_15NM, EMMC SAMSUNG_14NM									$-\mid_{B}$
В	SOC_EMPTY										
	SOC_INCLUDE VR_FIXED	STUFFS SPARKMAN SET ALL VIDE TO BLYED VOLTACES (NON-MADCINED) EVCLUDES V MEMIO MIST DE HSED IN CONTINICATION WITH NOT VID MM									-
	VR_MM	SET ALL VRS TO FIXED VOLTAGES (NON-MARGINED). EXCLUDES V_MEMIO. MUST BE USED IN CONJUNCTION WITH NOT VR_MM ALLOWS MOST VRS TO BE MARGINED FOR M&M BOARDS. EXCLUDES V_MEMIO. MUST BE USED IN CONJUNCTION WITH NOT VR_FIXED									
	RETAIL	COMPONENTS STUFFED FOR A RETAIL CONSOLE. DO NOT USE WITH DEBUG									
	DEBUG_PHASE DRAM_VPP_DEBUG	PHASES USED FOR INITIAL POWER UP SEDARATES SOC 1 8V AND DRAW 1 8V USE IE MARGINING SOC 1 8V OUTSIDE OF DRAW 1 8V LIMITS NEVER USE WITH DRAW VRD RETAIL.									_
	DRAM_VPP_RETAIL	SEPARATES SOC 1.8V AND DRAM 1.8V. USE IF MARGINING SOC 1.8V OUTSIDE OF DRAM 1.8V LIMITS. NEVER USE WITH DRAM_VPP_RETAIL COMBINES SOC 1.8V AND DRAM1.8V USEING A FILTER NETWORK. NEVER USE WITH DRAM_VPP_DEBUG									— L
	DEBUG_FTDI	STUFFS INTERCEPT CIRCUITRY FOR DEBUG									_
	NO_DEBUG_FTDI SPI_FLASH_BASE	BYPASSES INTERCEPT CIRCUITRY FOR NO DEBUG DUMMY PLACE HOLDER FOR SPI FLASH. NEVER USE THIS IN THE RECIPE FILE.									_
	SPI_FLASH_MACRONIX	STUFFS MACRONIX SPI FLASH. NEVER USE THIS IN THE RECIPE FILE.									-
.	SPI_FLASH_WINBOND	STUFFS MACRONIX SPI FLASH STUFFS WINBOND SPI FLASH									_
	DI 1_I DADII_WINDOND	> STOFFS WINDOWD SFI FIMSH									-
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